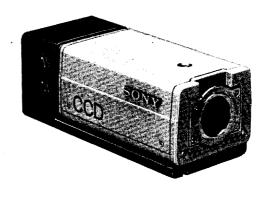
COLOR VIDEO CAMERA
AUTO IRIS LENS

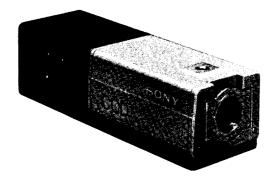
DXC-101/102 VCL-08Y/16Y

Revised-1

DXC-101



DXC-102





WARNING

To prevent fire or shock hazard, do not expose the set to rain or moisture.

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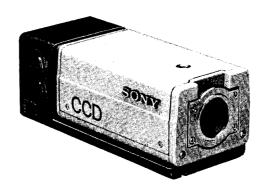
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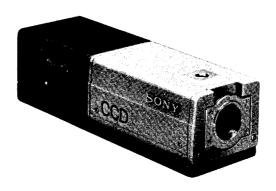
COLOR VIDEO CAMERA HEAD

DXC-101/102

DXC-101



DXC-102





SPECIFICATIONS

Pickup device Interline-transfer CCD, 1-chip

Picture elements

500 × 582 (horizontal/vertical)

Sensing area

8.8 mm × 6.6 mm

(equivalent to 2/3-inch pickup tube)

Lens mount

C mount

Signal system EIA stand

EIA standards, NTSC color system

Scanning system

525 lines, 2:1 interlace, 30 frames/sec.

Scanning frequency

Horizontal: 15.734 kHz

Vertical: 59.94 Hz

Sync system

DXC-101: Internal DXC-102: Internal

External with the VBS or BS signal

Resolution

Horizontal: 320 lines

Vertical: 350 lines

Minimum illumination

30 lux (F1.4 at +12 dB gain setup)

Sensitivity

2,000 lux, F4.0 (3,200°K) AUTO, 0dB, 6dB or 12dB

Gain selection A Video output 1.

1.0 V (p-p), sync negative, 75 ohms,

unbalanced

Video signal-to-noise ratio

More than 48 dB

(Gamma: OFF, Detail: OFF)

Input/output connectors

DXC-101: VIDEO OUT: BNC type

LENS: 4-pin connector

DC IN: 12-pin connector

DXC-102: DC IN/VIDEO OUT: BNC type

LENS: 4-pin

REMOTE: BNC type

GEN LOCK IN: BNC type

Power requirements

DXC-101:

10.5 to 16.0 V DC

DXC-102: 25 to 28 V DC

Power consumption

DXC-101: 4.2 W

DXC-102: 7.6 W

Operating temperature

0°C to 40°C (32°F to 104°F)

Storage temperature

-40°C to +60°C (-40°F to +140°F)

Operating humidity

Less than 70 %

Storage humidity

Less than 90 %

Vibration resistance

Less than 7 G (11 to 200 Hz)

Shock resistance

Less than 70 G

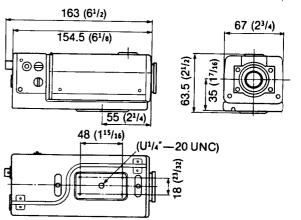
Weight

DXC-101: Approx. 550 g (1 lb 3 oz)
DXC-102: Approx. 800 g (1 lb 12 oz)

Dimensions

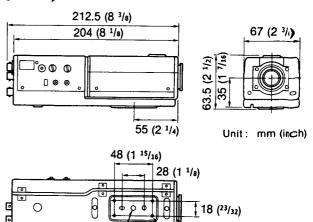
[DXC-101]

Unit: mm (inch)



[DXC-102]

U1/4" - 20 UNC



4-M3

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SECTION 1 GENERAL DESCRIPTION

1-1. DXC-101/101P GENERAL DESCRIPTION

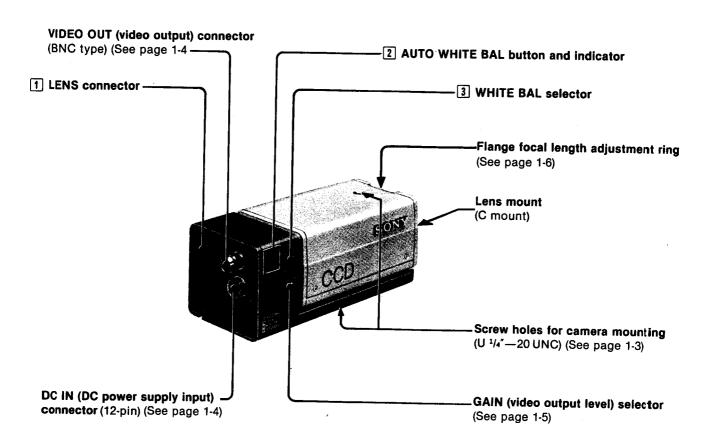
1-1-1. GENERAL FEATURES

The DXC-101/101P color video camera, designed for monitoring and surveillance, features a 1-chip CCD (Charge Coupled Device) which affords small size, light weight, and low power consumption. This CCD improves highlight after-images and color reproduction, eliminates highlight burn-in and picture distortion, and resists vibration and shock.

The camera lens mount is a C mount. Auto iris lenses such as the VCL-08Y and the VCL-16Y (optional) are available.

To use this camera for monitoring, connect a video monitor and the CMA-D1/D1CE camera adaptor (optional) to the camera. The camera can be installed on a wall or ceiling with a mounting bracket.

1-1-2. LOCATION AND FUNCTION OF PARTS



1 LENS connector (4-pin)

This connector is used when the VCL-08Y or VCL-16Y auto iris lens is used, to control the iris of the lens automatically.

2 AUTO WHITE BAL (automatic white balance adjustment) button and indicator (green)

Press this button to adjust the white balance automatically.

When the adjustment is completed, the indicator lights up for a few seconds.

3 WHITE BAL (white balance adjustment) selector

AUTO: Set to AUTO to adjust the white balance automatically.

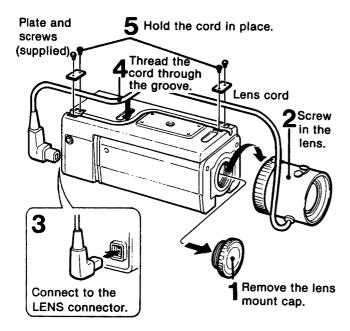
1, 2 or 3: Set to 1, 2 or 3 to adjust the white balance to one of the factory-preset values.

For details, refer to "WHITE BALANCE ADJUST-MENT" on page 1-5.

1-1-3. INSTALLATION

•LENS MOUNTING

Mount the lens according to the following procedure from 1 to 5.



To change the lens mounting position, refer to the instruction manual of the lens.

•CAMERA INSTALLATION

To install the camera on a wall or ceiling, use a screw which matches the screw hole in the camera ($U^1/4''-20$ UNC), and attach the camera to a support or to a mounting bracket with the screw.

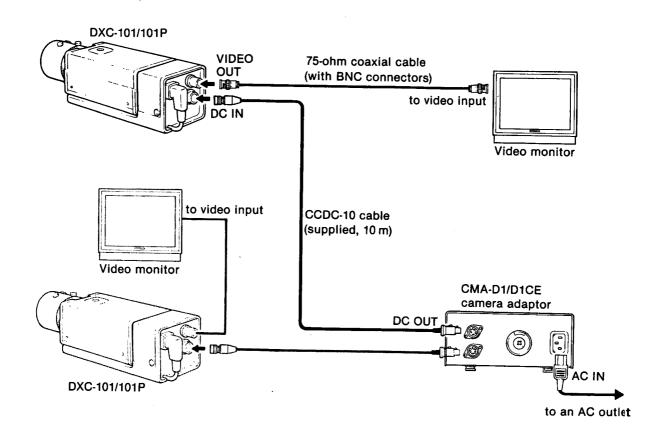
Be sure to use the screw specified below. ISO standard: $\ell = 4.5 \, \text{mm} \pm 0.2 \, \text{mm}$ ASA standard: $\ell = 0.197 \, \text{inches}$

Caution on installation

Do not install the camera in a place as follows:

- ●Extremely hot or cold places (operating temperature: 0°C to 40°C or 32°F to 104°F).
- •Where it is exposed to rain, high humidity or dust.
- •Where it is subjected to very high vibration.
- Place near a TV or radio station which radiates high power radio waves.

1-1-4. CONNECTIONS



1-1-5. OPERATION

1) PREPARATION

- Check that all the units are connected properly.
- Set the POWER switch of the CMA-D1/D1CE to ON to turn on the camera.
- Turn on the video monitor, and adjust its controls properly.
- Set the GAIN selector of the camera to 0 dB.
- Illuminate the object properly.
- When a manual iris control lens is used, adjust the iris depending on the lighting conditions.

2) WHITE BALANCE ADJUSTMENT (for lifelike color reproduction)

There are two ways to adjust the white balance as described below.

To adjust the white balance to the factory-preset values Select the position of the WHITE BAL selector depending on the lighting conditions.

Selector position	Label indication	Lighting condi- tions
1	3200°K (color temperature)	lodine lamp, sunrise, sunset
2	INDOORS	Fluorescent light
3	OUTDOORS	Under a clear sky

For better color setup according to lighting conditions (Automatic white balance adjustment)

Perform the procedure described below.

- 1 Set the WHITE BAL selector to AUTO.
- 2 Shoot a white object (a white cloth or a white wall) with the camera so that the white object fills the screen.
- 3 Press the AUTO WHITE BAL button. When the automatic white balance adjustment is completed, the indicator lights up for a few seconds.

The white balance adjustment function may not operate in the following lighting conditions:

If the lighting is insufficient, the AUTO WHITE BAL indicator will not light up. This signifies that the white balance cannot be adjusted properly.

If the lighting is excessive, the AUTO WHITE BAL indicator will light up, even if the white balance cannot be adjusted properly. In this case, the entire monitor screen turns greenish to indicate that the white balance adjustment cannot be made properly.

In both cases, try to adjust the white balance again as follows.

When an auto iris lens is used:

When the lighting is insufficient, the white balance cannot be adjusted properly. Increase the lighting and press the AUTO WHITE BAL button again.

When a manual iris lens is used:

When the lighting is insufficient or excessive, the white balance cannot be adjusted properly. When the lighting is insufficient, open the iris or increase the lighting; when the lighting is excessive, stop down the lens. Then press the AUTO WHITE BAL button again.

Memory of the automatic white balance adjustment value

In the DXC-101/101P, a built-in memory stores the adjusted white balance value. The memorized value will be retained for about 24 hours after the power is turned off without any further power supply to the camera or until the adjustment is made again.

3) VIDEO OUTPUT LEVEL SELECTION

The video output level can be adjusted with the GAIN selector.

AUTO: Set the selector to this position when the brightness of objects changes as in conditions outdoors. The video output level is automatically adjusted according to the brightness of the objects.

0 dB: The selector is usually set to this position.

6 or 12 dB: The video output level can be raised by 6 dB or by 12 dB depending on the position of the selector. When the lighting is insufficient and the picture observed on the monitor is too dim, set the selector to one of these positions.

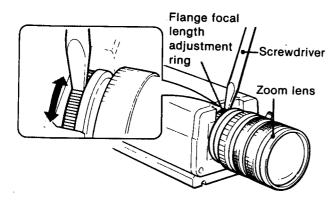
After these adjustments (white balance and video output level) are completed, shoot an object with the camera and observe the picture on the monitor screen. Then, adjust the lens focus. Once these adjustments have been completed, no further adjustments will be necessary provided that both the lighting and the distance to the object do not change. To monitor the picture again after the camera and other in its have been turned off, just turn on the camera adaptor and the monitor.

1-1-6. FLANGE FOCAL LENGTH ADJUSTMENT

When a zoom lens is used with this camera, flange focal length adjustment may be required. The proper flange fòcal length adjustment insures that the object is in focus both at the wide-angle position and at the telephoto position when zooming. Once the flange focal length adjustment has been made, readjustment is not necessary as long as the lens stays mounted on the same camera.

Focus on an object with fine detail to adjust the flange focal length.

- When a manual iris lens is used, set the iris fully open.
 - When an auto iris lens is used, illuminate an object so that the iris is fully open.
- Point the camera at an object about 3 meters (10 feet) from the camera.
- 3 Set the zoom to the telephoto position.
- 4 Turn the focus ring to adjust the focus.
- 5 Set the zoom to the wide-angle position.
- Turn the flange focal length adjustment ring of the camera until the same object is in focus. Do not turn the focus ring.

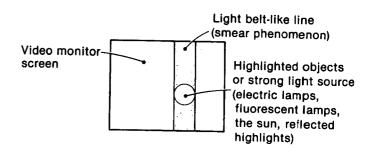


7 Repeat steps 3 to 6 until the object is in focus while the zoom is in both the telephoto position and the wide-angle position.

1-1-7. SPECIFIC EFFETS CAUSED BY CCD

Smear in picture

This may appear when a highlighted object is shot.



Patterned noise in picture

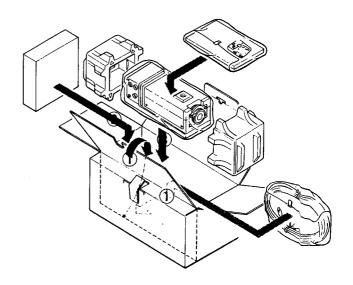
When the camera is used at a high temperature, a fixed patterned noise may appear on the entire screen of the monitor.

Gear-tooth effect in picture

When vertical stripes or straight lines are shot, they may look wavy.

1-1-8. REPACKING FOR SHIPMENT

The repacking procedure is subject to change. Refer to the packing instructions on the original carton, as well as those shown here.



1-2. DXC-102/102P GENERAL DESCRIPTION

1-2-1. OUTLINE

The DXC-102/102P color video camera, designed for monitoring and surveillance, features a 1-chip CCD (Charge Coupled Device) which allows the camera to be small and lightweight and have a low power consumption. This CCD reduces highlight after-images, eliminates highlight burn-in and picture distortion, improves color reproduction, and resists vibration and shock.

The camera lens mount is a C mount.

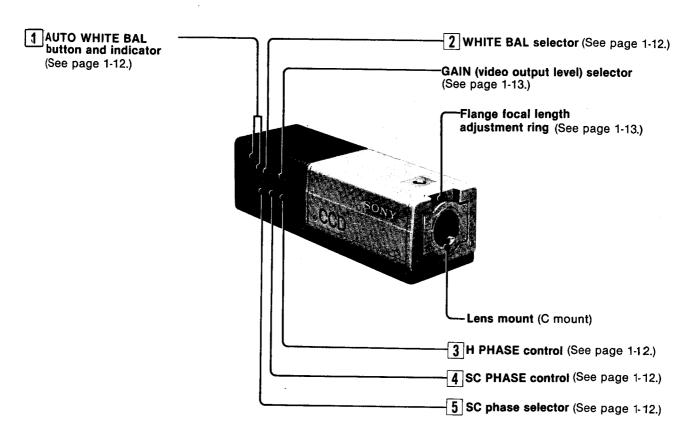
Auto iris lenses such as the VCL-08Y and the VCL-16Y (optional) are available from your authorized Sony dealer.

To use this camera for monitoring, connect a video monitor and a CMA-10/10CE camera adaptor (optional) to the camera.

The camera can be synchronized to a reference signal (VBS or BS) supplied to the camera.

The camera can be installed on a wall or ceiling with a mounting bracket.

1-2-2. LOCATION AND FUNCTION OF CONTROLS



1 AUTO WHITE BAL (automatic white balance) button and indicator (green)

When the WHITE BAL selector is set to AUTO, press this button to adjust the white balance automatically. When the adjustment is completed, the indicator lights up for a few seconds.

2 WHITE BAL (white balance adjustment) selector

AUTO: Set to AUTO to adjust the white balance automatically.

1, 2 or 3: Set to 1, 2 or 3 to adjust the white balance to one of the factory-preset values.

3 H (horizontal) PHASE control

When two or more cameras are used, turn this control with a small screwdriver to adjust the H phase difference between the gen-lock input and video output signals.

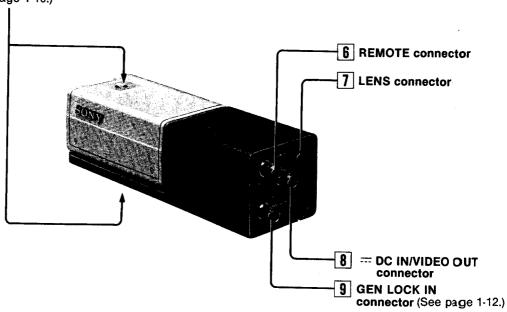
4 SC (subcarrier) PHASE control

When two or more cameras are used, this control is used for fine adjustment of the subcarrier phase after making the rough adjustment with the SC phase selector 5.

5 SC (subcarrier) phase selector

When two or more cameras are used, set this selector so that the SC phase difference between the gen-lock input and video output signals to 0° or 180°

Screw holes for camera mounting (U 1/4" -- 20 UNC) (See page 1-10.)



6 REMOTE (remote control) connector (BNC type)
Connect to the REMOTE connector of a CMA-10/10CE camera AC adaptor (optional), so that the white balance and the pedestal level can be adjusted by the camera AC adaptor. For details on the pedestal level adjustment, refer to the CMA-10/10CE's instruction manual.

Notes

- When the camera's REMOTE connector is connected to the CMA-10/10CE's REMOTE connector, the white balance adjustment cannot be made by the camera.
- •If you wish to cancel the white balance control by the camera AC adaptor and to adjust the white balance by the camera, first turn off the camera AC adaptor, then, disconnect the cable connecting the REMOTE connectors.

If the connecting cable is disconnected with the camera AC adaptor powered, the camera's white balance adjustment function will be inoperative. In this case, first turn off the camera AC adaptor, and after a few seconds, turn on the adaptor once again, so that the adjustment function will be operative.

7 LENS connector (4-pin)

Connect the lens connector plug of the VCL-08Y or VCL-16Y auto iris lens (optional) here. For details about the lens, refer to the lens' instruction manual.

B-DC IN (input) / VIDEO OUT (output) connector (BNC type)

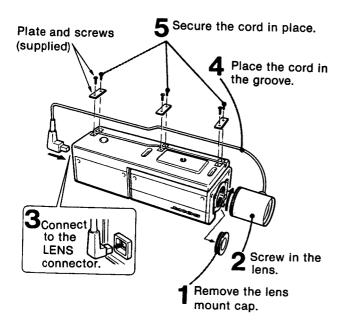
Connect the --- DC OUT/VIDEO IN connector of the CMA-10/10CE camera AC adaptor (optional) here. Through a single coaxial cable, the power is supplied to the camera and the video output signals from the camera are transmitted to the camera AC adaptor.

GEN LOCK IN (input) connector (BNC type)
Connect the gen-lock input signal (VBS or BS) for synchronization. No connection is necessary when only one camera is used.

1-2-3. INSTALLATION

•LENS ATTACHMENT

Mount the lens following Steps 1 to 5 in order.



To change the position of the mounted lens, refer to the lens' instruction manual.

•CAMERA INSTALLATION

To install the camera on a wall or ceiling, attach the camera to a support or to a mounting bracket by using a screw which matches the screw holes in the camera (U 1/4"—20 UNC).

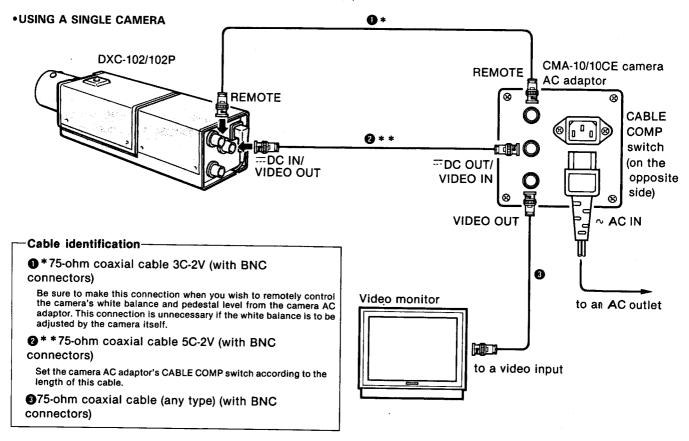
Be sure to use the screw specified below. ISO standard: $\ell = 4.5 \text{ mm} \pm 0.2 \text{ mm}$ ASA standard: $\ell = 0.197 \text{ inches}$

Caution on installation

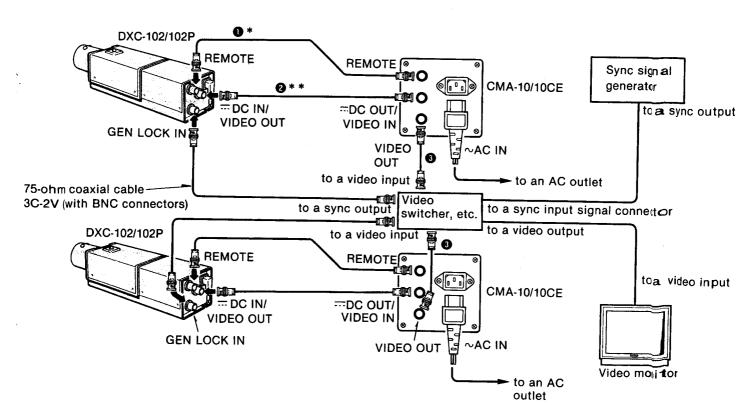
Do not install the camera in:

- An extremely hot or cold location. (Operating temperature: 0°C to 40°C or 32°F to 104°F)
- •A location exposed to rain, high humidity or dust.
- A location subject to strong vibrations. (Resistance to vibration: 7G. Resistance to shock: 70G)
- A location near TV or radio station which radiates strong signals.

1-2-4. CONNECTIONS



•USING TWO OR MORE CAMERAS



Use of the GEN LOCK IN connector

When two or more cameras are to be used in connection with a video switcher, a special-effects generator or a similar equipment, etc., and each camera picture selected by the switcher is to be observed on the same video monitor, supply each camera with the same reference signal to obtain the same picture tone.

Connect a sync signal generator to the GEN LOCK IN connector to supply a reference signal (VBS or BS) to each camera, so that all the cameras are synchronized to this signal.

Adjustment of the picture tone for two or more cameras When two or more cameras are used in connection with a video switcher, a special-effects generator or a similar equipment, supply each camera with a reference signal and adjust each camera to obtain the same picture tone. Adjust the SC (subcarrier) phase and the H (horizontal) phase following the procedure described below.

Subcarrier phase adjustment

Adjust the subcarrier phase roughly with the SC phase selector, then, make the fine adjustment using the SC PHASE control. A vectorscope will allow you to make the adjustment more easily.

Horizontal phase adjustment

Adjust the horizontal phase with the H PHASE control. A waveform monitor or an oscilloscope will allow you to make the adjustment more easily.

1-2-5. OPERATION

1) PREPARATION

- Check that all the units are connected properly.
- Set the POWER switch of the CMA-10/10CE to ON to turn on the camera.
- •Turn on the video monitor, and adjust its controls properly.
- •Set the camera's GAIN selector to 0 dB.
- Illuminate the subject properly.
- If a manual iris control lens is used, adjust the iris depending on the lighting conditions.

2) WHITE BALANCE ADJUSTMENT (for lifelike color reproduction)

There are two ways to adjust the white balance:

To adjust the white balance to the values preset at the factory

Select the position of the WHITE BAL selector depending on the lighting conditions.

Selector position	Label indication	Lighting conditions
1	3200°K (color temperature)	lodine lamp, sunrise, sunset
2	INDOORS	Fluorescent light
3	OUTDOORS	Under a clear sky

Automatic white balance adjustment (For the best possible color tone given under the lighting conditions)

- 1 Set the WHITE BAL selector to AUTO.
- Shoot a white object (a white cloth or a white wall) with the camera so that the white object fills the screen.
- 3 Press the AUTO WHITE BAL button. When the automatic white balance adjustment is completed, the indicator lights up for a few seconds.

The white balance adjustment function may not operate in the following lighting conditions:

If the lighting is insufficient, the AUTO WHITE BAL indicator will not light up. This signifies that the white balance cannot be adjusted properly.

If the lighting is excessive, the AUTO WHITE BAL indicator will light up, even if the white balance cannot be adjusted properly. In this case, the entire monitor screen turns greenish to indicate that the white balance adjustment cannot be made properly.

in both cases, try to adjust the white balance again as follows.

When an auto iris lens is used:

If the lighting is insufficient, increase the lighting and press the AUTO WHITE BAL button again.

When a manual iris lens is used:

If the lighting is insufficient, open the iris or increase the lighting; if the lighting is excessive, stop down the lens. Then press the AUTO WHITE BAL button again.

Memory of the automatic white balance adjustment value

In the DXC-102/102P, a built-in memory stores the adjusted white balance value. The memorized value will be retained for about 24 hours after the power is turned off without any further power supply to the camera or until the adjustment is made again.

3) VIDEO OUTPUT LEVEL SELECTION

The video output level can be adjusted with the GAIN selector.

AUTO: Set the selector to this position when the lighting conditions are subject to change, as in conditions outdoors. The video output level is automatically adjusted according to the lighting conditions.

0 dB: Generally, set the selector to this position.

6 or 12 dB: The video output level is raised by 6 dB or by 12 dB depending on the position of the selector. When the lighting is insufficient and the picture observed on the monitor is too dim, set the selector to one of these positions.

After the white balance and video output level adjustments have been completed, shoot an object with the camera and observe the picture on the monitor screen. Then focus the lens.

Once these adjustments have been completed, no further adjustments will be necessary unless the lighting conditions and the distance to the object change. To monitor the picture again after the camera and other units have been turned off, just turn on the equipments.

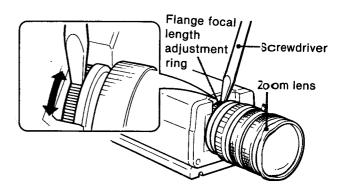
1-2-6. FRANGE FOCAL LENGTH ADJUSTMENT

When a zoom lens is used with this camera, flange focal length adjustment ensures that the object is in focus both at the wide-angle position and at the telephoto position when zooming. Once the flange focal length adjustment has been made, readjustment is unnecessary as long as the lens stays mounted on the same camera.

Focus on an object with fine detail to adjust the flange focal length.

Procedure

- When a manual iris lens is used, set the iris fully open.
 - When an auto iris lens is used, illuminate an object so that the iris is fully open.
- Point the camera at an object about 3 meters (10 feet) from the camera.
- 3 Set the zoom to the telephoto position.
- 4 Turn the focus ring to adjust the focus.
- 5 Set the zoom to the wide-angle position.
- 6 Turn the flange focal length adjustment ring of the camera until the same object is in focus. Do not turn the focus ring.

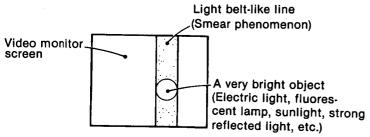


7 Repeat Steps 3 to 6 until the object is in focus while the zoom is in both the telephoto position and the wide-angle position.

1-2-7. SPECIAL CHARACTERISTICS OF A CCD

Smear phenomenon

A smear may appear when a very bright object is shot.



Patterned noise

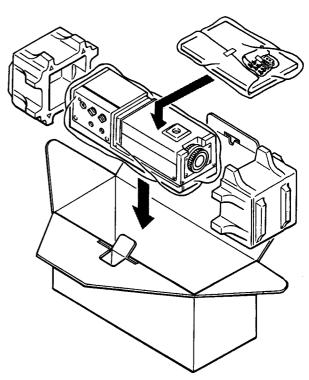
This may appear uniformly over the entire monitor screen when the camera is operated at a high temperature.

Wavy picture

This may appear when fine stripes, strait lines, etc. are shot. The image monitored on the screen may appear wavy.

1-2-8. REPACKING FOR SHIPMENT

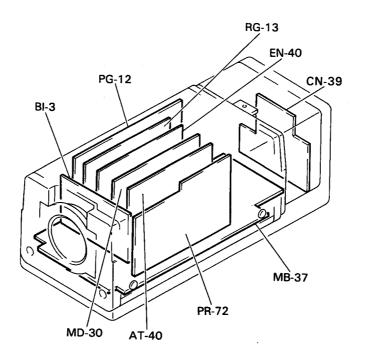
The repacking procedure is subject to change. Refer to the packing instructions on the original carton, as well as those shown here.



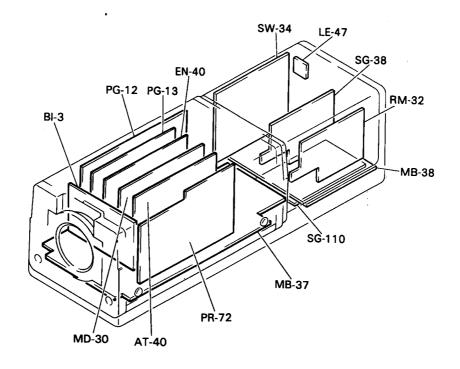
SECTION 2 SERVICE INFORMATION

2-1. BOARD LAYOUT

DXC-101/101P

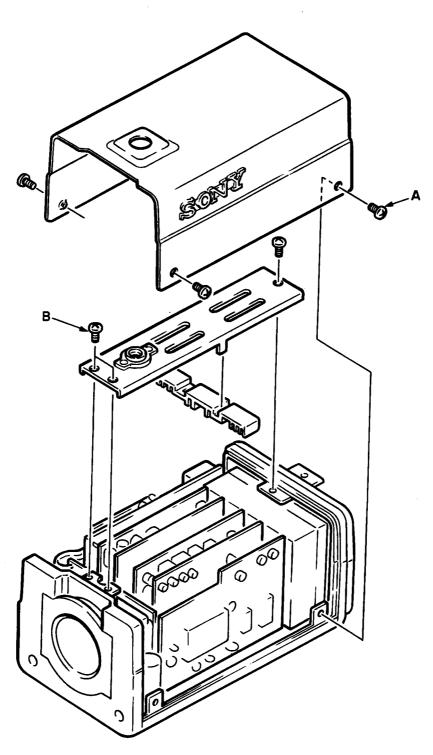


DXC-102/102P



2-2. REMOVAL OF CABINET

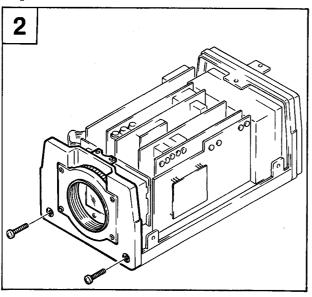
Remove the four screws A (PRECISION +P2 \times 3) and remove the camera cover. Remove the three screws B (PRECISION +P2 \times 3) which hold the SPAN ASSY and remove the SPAN ASSY and board holder.



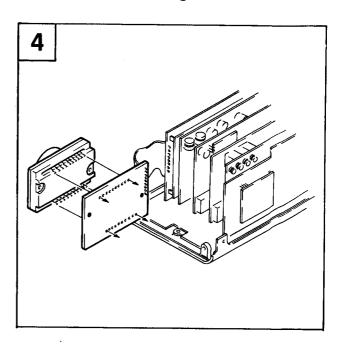
2-3. REPLACEMENT OF MAIN PARTS

2-3-1. REPLACEMENT OF CCD ASSY

- Remove the cabinet referring to 2-2. REMOVAL OF CABINET.
- Remove the two screws which hold the front panel.

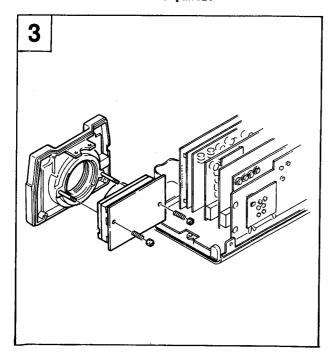


4. Remove pins 1 - 20 of IC on the BI-3 board by using a desoldering tool.



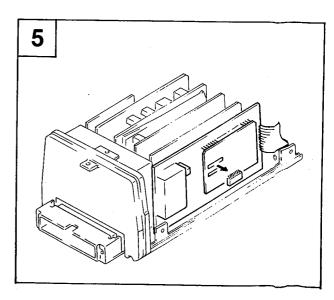
3. Remove the hexagonal screw shown in the figure below.

When the board is pulled in the direction shown by the arrow, the CCD ASSY can be removed from the front panel.



5. When the CCD ASSY is replaced, be sure to replace the ROM IC with a new one attached to a CCD ASSY for repair. Take out the ROM IC (MB7052) of the IC on the PG-12 board. Place "soldawick" on the pins of the ROM IC and apply a soldering iron on it sufficiently so that it will absorb solder.

To prevent the pattern from peeling off, do not pull it with tweezers or pliers.



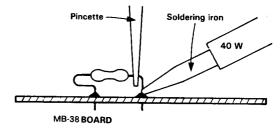
6. Install a new CCD ASSY in opposite procedures of the disassembly. When the ROM IC is installed, use a soldering iron with temperature controller in order to prevent damage to the CCD.

Place a new ROM IC on the home position and solder legs of the ROM IC one by one.

- Apply a soldering iron on a leg for 7 10 seconds to heat up the leg and board.
- After soldering, keep applying the solder iron for 4 - 5 seconds.

2-3-2. CAUTION OF FUSE REPLACEMENT
Applying too much heat may burn out fuses used in the camera module and the GENLOCK unit.
In case the fuse is replaced. Cut the lead of the fuse so that rather long lead wire remained with the fuse. Then hold the lead by a metal pincette, and solder the fuse quickly as shown below.

Please avoid any mechanical stress to the fusewhen you bent the leads.



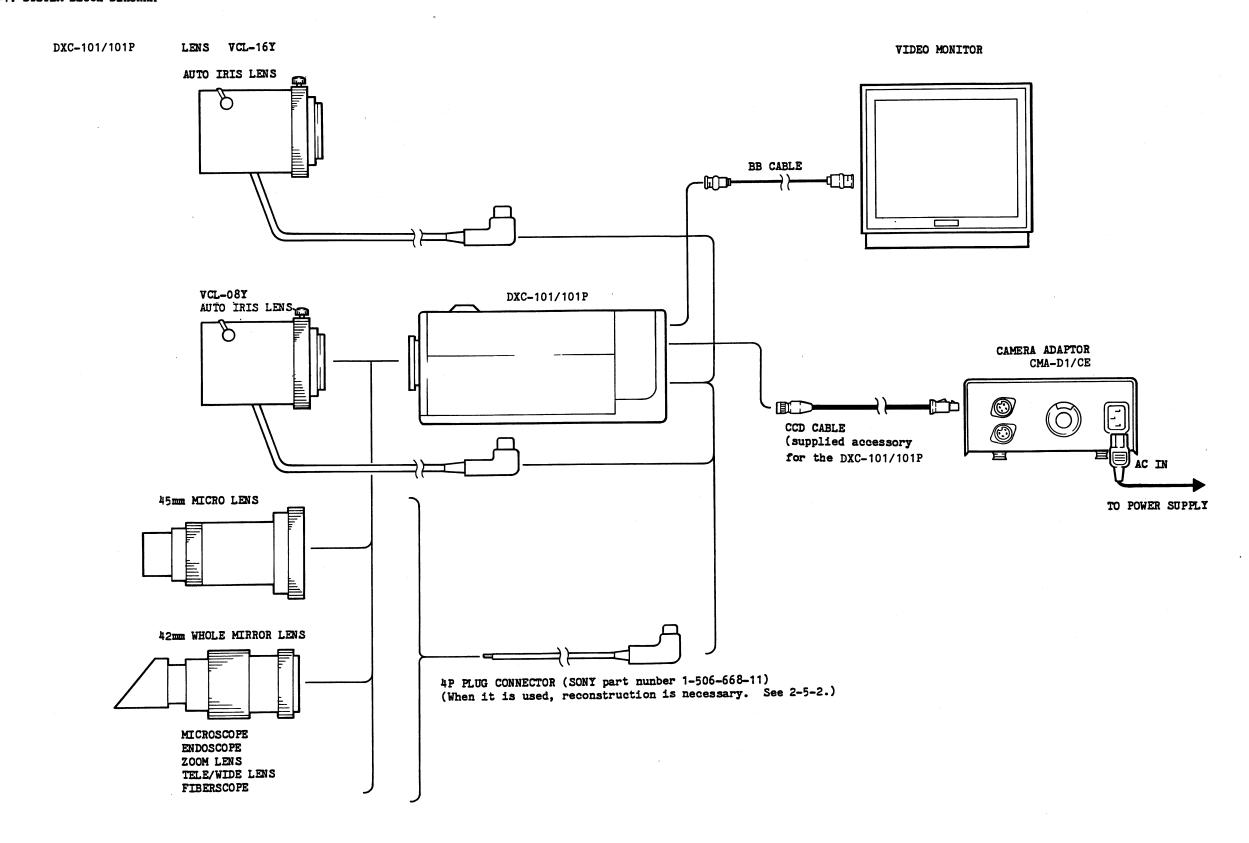
2-4. COMPATIBLE CONNECTORS AND CABLES

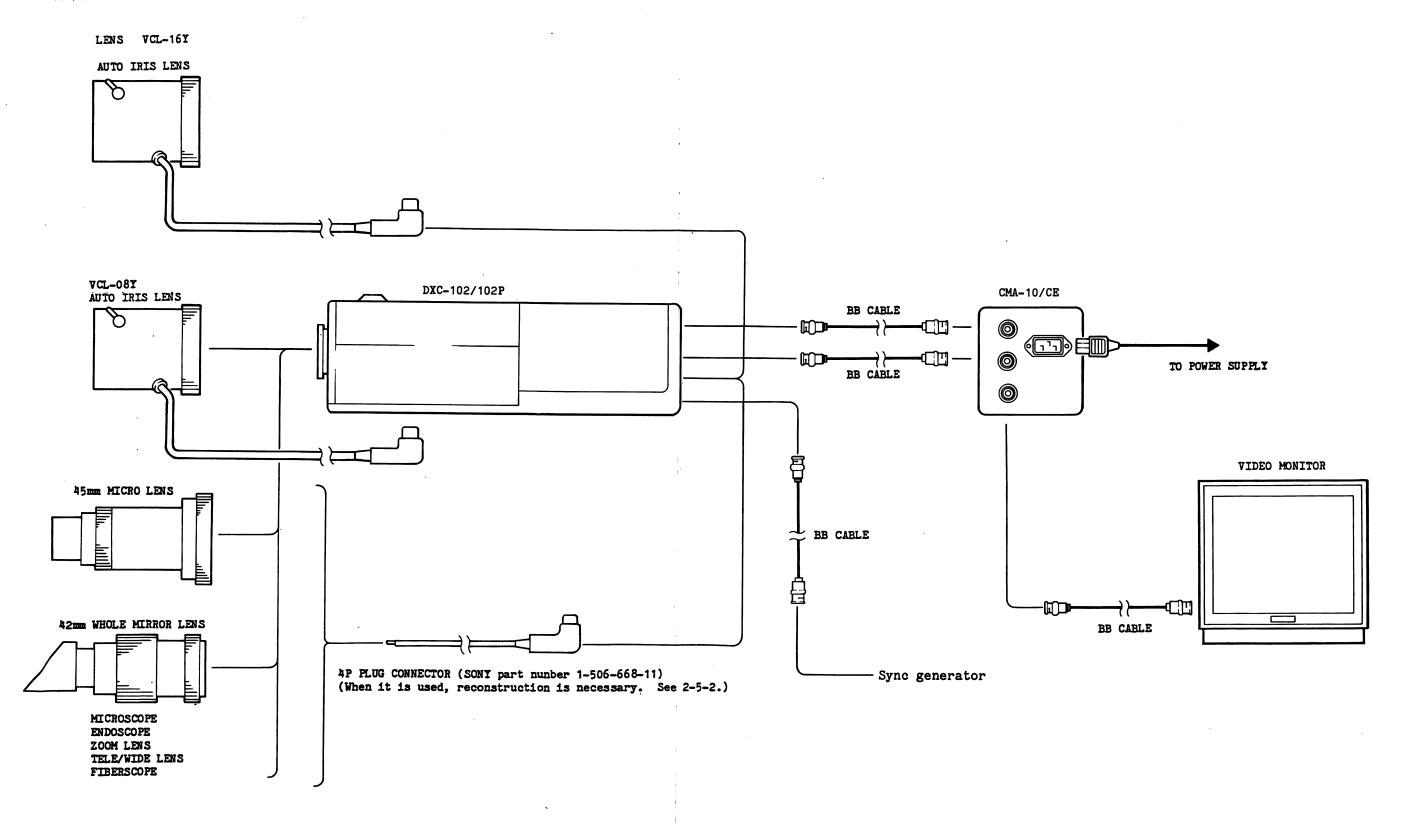
Attach the following connectors or equivalents to the ends of the cables to be connected on the connector panel during at installation or maintenance service.

DXC-102/102P function names	Connector names and part numbers of the connectors on the ends of the connection cables
VIDEO OUT, BNC REMOTE IN, BNC GENLOCK IN, BNC	BNC 1-508-898-00 B B CABLE (optional)
LENS 4P, FEMALE	LENS CONNECTOR 1-506-668-11 (When a lens, except for VCL-08Y or VCL-16Y is installed, modifica- tion is necessary. See 2-5-2.) CABLE with CONNECTOR 1-558-489-11

DXC-101/101P function names	Connector names and part number connectors on the ends of the connectors	es of the connection cables
DC IN 4P, MALE	DIN(4P) PLUG ROUND CONNECTOR, FEMALE (12P) CCDC-10 (supplied accessory for DXC-10	1-557-668-12
LENS 4P, FEMALE	LENS CONNECTOR (When a lens, except for VCL-0 is installed, modification is see 2-5-2.) CABLE with CONNECTOR	1-506-668-11 8Y or VCL-16Y necessary. 1-558-489-11
VIDEO OUT, BNC	BNC B B CABLE (optional)	1-508-898-00

2-5. CONNECTION
2-5-1. SYSTEM BLOCK DIAGRAM

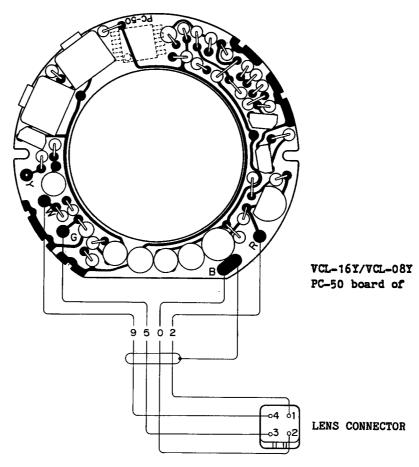




2-5-2. MODIFICATION OF LENS CONNECTOR, EXCEPT FOR VCL-16Y OR VCL-08Y

When another lens is used, connect the lens connector to the lens cable referring to the cable wiring diagram shown below.

VCL-16Y/VCL-08Y LENS (CABLE WIRING DIAGRAM)



CONNECTOR INPUT/OUTPUT SIGNAL

PIN No.	WIRING COLOR CODE	SIGNAL NAME	CONNECTED TERMINAL
1	2	+12V IN	+12V IN Terminal on a board in anoter lens.
2	0	GND	GND IN Terminal on a board in anoter lens.
3	5	REMOTE IN/ OUT	REMOTE IN/OUT Terminal on a board in anoter lens.
4	9	VS IN	VS IN Terminal on a board in anoter lens.

2-6. INFORMATION ON MAINTENANCE SERVICE

2-6-1. NOTES ON REPAIR PARTS

- Frinted Components in bold-face type on the spare parts list are normally stocked for replacement purposes. The remaining parts are not normally stocked for routine service work. Orders for parts not shown in boldface type will be processed, but allow for additional delivery time.
- 2) Components identified by shading marked with on the exploded view and spare parts list are critical to safe operation. Replace these components with Sony parts whose part numbers appear in the manual or service bulletins and service manual supplements published by Sony.
- 3) Replacement parts that are supplied from the Sony Parts Center can sometimes have a different shape and external appearance than what are actually used in equipment. This is due to "accomondating the improved parts and/or engineering changes" or "standardization of genuine parts".

2-6-2. HANDLING OF ROM IC ATTACHED TO A CCD ASSY

When the following components are replaced, be sure to replace a ROM of hybrid IC on the PG-12 board.

- When the CCD ASSY is replaced.
 Replace the ROM with a new one attached to a CCD ASSY for repair.
 (See 2-3. REPLACEMENT OF MAIN PARTS)
- When the PG-12 board is replaced.
 Move the ROM of hybrid IC to a new PG-12 board.

2-6-3. PRECAUTIONS

Avoid operating and storing the camera in the following locations.

- Extremely hot or cold places (The operating temperature is from 0°C to +40°C.)
- Places subject to humidity or excessive dust
- Places subject to strong vibration
- Places near an antenna which transmits a strong electromagnetic wave.

Avoid covering the camera with a cloth or similar items while an operation to prevent raising the temperature in the camera because it is being badly ventilated.

Note on transporting

Do not discard the carton. It affords maximum protection whenever the camera is transported by track, ship, or plane. Repack it as it was originally packed.

Note on cleaning

Clean the cabinet or panel with a dry soft cloth or soft cloth lightly moistened with mild detergent solution.

Do not use solvents such as alcohol, benzine, thinner, or insecticide as the finish may be damaged.

2-6-4. Caution when replacing the CCD image sensor

To prevent the static electricity shock
 The CCD image sensor is easily destroyed by
 the static electricity.

When handling this device, prevent the static electricity shock as follows.

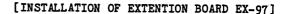
- a) Work with bare hands or wearing non-electrified gloves, and wearing non-electried clothes so as to prevent the static electricity.
- b) Install an earth board or an earth wire on a floor, a table and a door in a workshop so as to discharge the static electricity.
- c) Earth tools such as a screw drives, long nose pliers, a tweezer and a soldering iron.
- d) Earth a worker by wearing an earth band.
- e) The CCD image sensor is recommended to be discharged by spraying inoized air.
- 2. Window Glass

When dusts or soils stick to the surface of the glass, black spots appear in the picture. Keep the window glass clean.

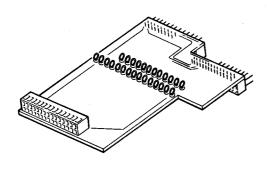
- a) Wipe off dusts and soils with soft cloth or cleaning paper which contains a little organic solution such as alcohol, and spray inoized air.
- b) Just before use, peel off a protection tape which has been stuck to the glass at the factory after performing "1 To porevent the static electricity shock". Don't use the stripped tape again.

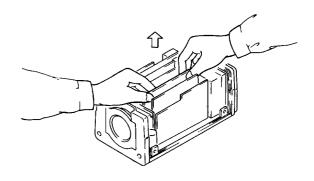
2-7. SERVICE JIG

Extension board: EX-97 (J-6028-450-A) It is used for the alignment of the MD-30 and EN-40 boards. If two extension boards are prepared, the MD-30 and EN-40 boards can be aligned correctly at the same time.



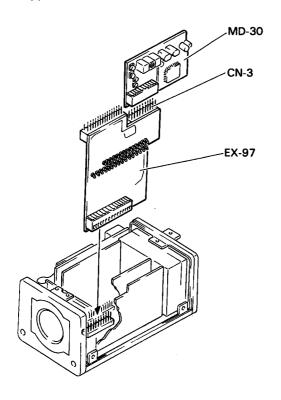
- Remove the cabinet referring to 2-2. REMOVAL OF CABINET.
- 2. Hold the ends of the board and pull up MD-30, EN-40 boards as shown in the figure.



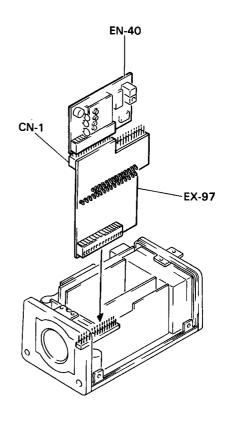


3. Insert the EX-97 board.

Insert CN1 on the MD-30 board to CN3 on the EX-97 board.



Insert CN1 on the EN-40 board to CN1 on the EX-97 board.



SECTION 3 THEORY OF OPERATION

3-1. Operation principle of the CCD

A CCD (Charge Coupled Device) consists of MOS (Metal-Oxide-Silicon) capacitors arranged in a regular array. It basically performs three functions connected with handling electrical charges.

1. Photoelectric conversion (photo sensor) incident light generates electrical charges on the MOS capacitors, with the quantity of charge being proportional to the brightness.

2. Accumulation of electrical charges

When a voltage is applied to the electrodes of the CCD, an electrical potential well is formed in the silicon layer. The electrical charge is accumulated in this well.

3. Transmission of electrical charge

When a high voltage is applied to the electrodes, a deeper well is formed; when a low voltage is applied, a shallower well is formed. In the CCD, this property is used to transmit electrical charge. When a high voltage is applied to the electrodes, a deep electric potential well is formed, and electrical charge flows in from neighboring wells. When this is repeated over and over among the regularly arranged electrodes, the electrical charge is transferred from one MOS capacitor to another.

This is the priciple of CCD electrical charge trasmission.

3-2. Mechanism of CCD electrical charge transmission

The DXC-101/102 camera uses a 4-phase drive method CCD in practice. For simplicity, a 2-phase drive method CCD is explained below.

Figure 1 shows an example of the changes which can occur in potential wells is successive time intervals.

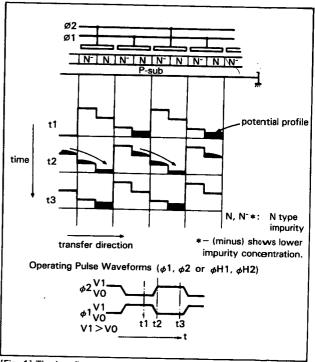
At t1, the electrode voltages are $\emptyset1>\emptyset2$, so the potential wells are deeper toward the electrode at the higher voltage $\emptyset1$.

Electrical charge accumulates in these deep wells. At t2, the clock voltages ø1 and ø2 are reversed; now the wells toward the electrode at voltage ø2 are deeper while those toward the electrode at voltage ø1 are shallower. Since the wells toward the electrode at ø2 are deeper than those toward the electrode at ø1, the signal charge flows toward the deeper wells toward the electrode at voltage ø2. At t3, the electrode voltages have not changed since t2, so the signal charge flows into the wells toward the electrode at ø2, and one transmission of electrical charge is completed. This action is repeated over and over to execute the horizontal and vertical transmissions.

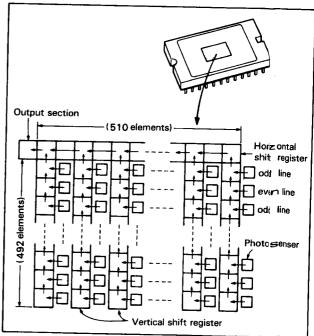
3-3. The interline-transfer organization of the CCD image sensors

The DXC-101/102 CCD video camera module adopts an interlinetransfer organization in which precisely aligned phontosensors and vertical Transmission section are arrayed interlinearly and a horizontal shift resister links up with the vertical Transmission section. Light variations are sensed by the phontosensors, which generate electronic

charges proportional to the light intensity. The generated charges are fed into the vertical shift registers all at once. The charges are then transferred from the vertical Transmission section to the horizontal shift registers successively and finally reach the output amplifier to be read out successively.



[Fig. 1] The interline-transfer organization of the CCD image sensors



(Fig. 2) Two Phase CCD Charge Transfer

3-4. BI-3 board

Light which comes through the camera lens strikes the CCD chip surface of IC1 on the BI-3 board. The surface of the CCD chip contains a number of photo sensors. The photo sensors are arranged in a 510 (horizontal) X 492 (vertical) array, so that threr are a total of 250,920. Incident light is converted to an electrical signal with the amplitude (electric charge analog amount) at the photosensor section in proportion to the brightness of the light. The converted electric charge is read out by the transfer section from the photosensor, and is transferred in sequence and fed to the output section.

The transfer section is subdivided into horiontal and vertical transfer sections.

Figure 2. in the figure below, there are 510 vertical transfer sections, while there is only one horizontal transfer section, across the top. Each converted electric charge is transferred to the transmission element (vertical transmission element) immediately to the left of it.

The electric charge on each vertical transfer section are transferred in sequence, from the bottom to the top of the screen, at a frequency determined by the vertical transfer clock $f_{\rm H}$. At the top there is the horizontal transfer section.

The horiozontal transfer section sends electrical signals to the output section at a rate of 455 $f_{\rm H}$.

The capacitor in the output section converts the electrical charge to a voltage signal; it is then output from the IC1, passed through the buffer Q1 and sent to MB-37 board.

3-5. MB-37 board

The signal from the Bl-3 board output by the CCD chip is separated into two signal paths. The signal of one path is sampled by the sample and hold pulse (SHP), the singal of the other path is sampled by two different sample and hold pulses (SHD and SHP), and these signals are converted into video signals. The output signal of a CCD chip used as an image photo sensor includes inherent noise, and these sample and hold circuits remove most of this noise.

The SAMPLE and HOLD circuits and DC-DC converter are on this board.

If an element of the CCD chip is defective, its output is not sampled, but is replaced by the last sampled signal.

Each signal then goes to the differential amplifier, and the output signal goes to the PR-72 board.

The externally supplied DC from the CN-39 board is converted into four different DC voltages by the DC-DC converter: $+20\,V$, $+8.5\,V$, $+5\,V$, and $-5\,V$. These voltages are supplied to each board.

3-6. PR-72 board

The video signal processing circuits are on this board.

The processing circuits convert the output signal of the CCD chip into several control signals and into gammacorrected G and R/B signals.

The signal from the MB-37 board output by the CCD chip is gain controlled by the gain control signals (AGC CONT, G1, and G2), then this gain-controlled signal is separated into two signal paths. The signal of one path is not processed on this board, but goes directly to the AT-40 board as the IRIS DET signal, which is the controlled lens iris data.

THe signal of the other path is automatically gain controlled in the AGC circuit, then it is separated into two signal paths. Here, the signal of one path goes directly to the AT-40 board as the AGC DET signal, which is the controlled auto gain data. The signal of the other path, which is to be used as the video signal, is separated into G and R/B signals.

These G and R/B signals are mixed, then the mixed signal is applied to the color mixing correction, white balance control, and clamping circuits. This signal is separated into two paths. The signal of one path goes directly to the AT-40 board as the G DET signal, which is the controlled G signal data. The signal of the other path is applied to the blanking mixer, pedestal adder, gamma correction circuit, and white clip circuit; then it goes to the MD-30 board as the G γ signal.

The white balance for each R or B signal is respectively performed by the R or B attenuator control signal from the MB-37 board. Each signal is clamped, off-set controlled, then switched line-by-line by the multiplexer so that the R and B signals are alternately output as a sequential signal. This signal is separated into two signal paths. The signal of one path goes directly to the AT-40 board as the R/B DET signal, which is the controlled R/B signal data. The signal of the other path is applied to the blanking mixer, pedestal adder, gamma correction circuit, and white clip circuit; then it goes to the MD-30 board as the R/B γ signal.

3-7. MD-30 board

The KNEE control circuits for the G and R/B signals are on this board. The 1H delay line circuits, which delay the signals by 1H or 2H, and the matrix circuits for the $\gamma_{H'}$ YLYH R-Y, and B-Y signals are also on this board.

The G γ signal from the PR-72 board is applied to the knee clipper and the clamping circuits, then it is separated into two signal paths. The signal of one path is directly cutput as the original G signal, and the signal of the other pathe is delayed by the 1H delay line. This delayed signal is clamped, gain controlled, then separated into two signal paths. Here, the signal of one path is directly output so the 1H delayed G signal, and the signal of the other path is again delyed by the same 1H delay line. This 2H delayed signal is clamped, gain controlled, then output as the 2H delayed G signal. As described here, the G1 signal is delayed to produce the following three signals, which have different timings: OH delayed (G0), 1H delayed (G1) and 2H delayed (G2) signals.

The R/B signal from the PR-72 board is also processed in the same way to produce OH delayed (R0/B0), 1H delayed (R1/B1), and 2H delayed (R2/B2) signals.

Then, the G0 and R0/B0 signals, the G1 and R1/B1 signals, and the G2 and R2/B2 signals are applied to the subtracters to output the G0-R0/B0, G1-R1/B1, and G2-R2/B2 signals.

The G0 and G1 signals, and the R0/B0 and R1/B1 signals are applied to the $Y_{\rm H}$ matrix circuits and mixed to be two signals. These two signals are mixed to be the $Y_{\rm H}$ signal.

The undesired sampling noise in the Y_H signal is filtered by the low-pass filter, then the filtered signal goes to the EN-40 board.

Both the G1-R1/B1 signal and the mixed signal of the G0-R0/B0 and G2-R2/B2 signals are applied to the multiplexer, and the R and B signals are switched line-by-line with the ID signal to output the G-R and G-B signals. Each of these signals is separated into two signal paths. Each signal of one separated path is applied to the chroma matrix circuits ot output the R-Y and B-Y signals. These signals are gain controlled, then go to the EN-40 board. Each signal of the other separated path is applied to the Y_L matrix circuit with the G1 signal to be one signal. This signal is mixed with a signal resulting from a mixture of the G0, G1, and G2 signals and the apperture correction in the vertical direction. The signal processed here is compared with the Y_H signal, then goes to the EN-40 board as the Y_L-Y_H signal.

3-8. EN-40 board

The encoders are on this board.

The R-Y and B-Y signals from the MD-30 board are clamped modulated by the balanced modulators, then mixed to become the chrominance signal. After passing through the burst signal adder, this signal is applied to the chroma balanced mixer.

The Y_H signal from the MD-30 board is clamped, then delayed by 150 ns. After this, apperture correction is performed. This signal is then mixed with the clamped Y_L - Y_H signal from the MD-30 board. Next, the signal is applied to the gain controller, blanking cleaner, setup circuit, and white clip circuit; then it is separated into two signal paths. The signal of one path is mixed with the chrominance signal in the chroma balanced mixer, previously described. For this signal, the undesired Y signal components are filtered by the band-press filter. After this, blanking mixing is performed with the HD signal, and this signal is mixed with the signal of the other path.

This mixed signal is separated into two signal paths. The signal of one path is clamped, then goes to the MB-37 board as the video output signal (VBS). A sync signal is added to the signal of the other path, then this signal also goes to MB-37 board as the VS (B/W) signal.

3-9. CN-39 board

The power-on reset circuit, auto white balance trigger signal generator, and auto white balance indicator signal generator are on this board.

The power-on reset circuit operates when power is supplied. This circuit prevents mal-operations of the auto white balance trigger signal generator and the auto white balance indicator signal generator caused by insufficient voltage supplied to the ICs or by noise when the power is switched on.

When manual white balance is performed, this power-on reset circuit is controlled by the WB1 and WB2 signals. Therefore, in this case too, this circuit prevents maloperations of the auto white balance trigger signal generator and the auto white balance indicator signal generator.

The auto white balance drive signal, which is HIGH when the auto white balance button on the side of the camera unit is pressed, is applied to the auto white balance trigger signal generator. The output signal of this auto white balance trigger signal generator operates as a trigger signal to the auto white balance circuit. When the auto white balance adjustment is completed and the white balance becomes the specified value, the indicator control signal, which is used to indicate OK for the white balance completion, is fed from the AT-40 board. This signal is applied to the auto white balance indicator signal generator. The output signal of the auto white balance indicator signal generator controls and switches the auto white balance LED indicator on the side of the camera unit. The drive signals (GAIN1 and GAIN2) from the gain switch on the side of the camera unit go directly to the PR-72 board. The VBS and VS (B/W) signals go directly to the VIDEO OUT connector and to the LENS connector on the back of the camera unit respectively.

3-10. PG-12 board

The sync signal generator (IC1) and the pulse generator (IC2) which is necessary to drive the CCD chip are on this board.

In the IC1 circuit, the VCO control signal from the RG-13 board is used as a clock signal to generate the following signals:

BLKG: Horizontal and vertical blanking signals

SYNC: Horizontal and vertical sync signals (composite

sync)

CK: 910 fn clock pulse

HD and VD: Horizontal and vertical drive pulses

BF: Horizontal and vertical burst flag

O/E: fv/2 pulse for detection of Odd/Even fields

These CK, O/E, and HD pulses generated by IC1 and the VCO control signal from the RG-13 board are applied to IC2 to generate the following signals:

H1 and H2: Horizontal shift register drive pulses

These two signals having different phases are used to drive the horizontal shift register of the CCD chip to transfer the electric charges stored in the horizontal shift register.

V1 to V4:

Vertical shift register drive pulses

These four signals having different phases are used to drive the vertical shift registers of the CCD chip to transfer the electric charges stored in the vertical shift registers.

PG: Precharge gate control pulse

The precharge gate is the gate of the output section connected to the horizontal shift register of the CCD chip. This gate is controlled by this pulse to convert a transferred electric charge into a voltage.

SHP and SHD: These pulses are the sample and hold pulses to gate the output signal of the CCD chip.

H BLKG: This pulse is used to hold the horizontal flyback period of the output signal of the CCD chip.

VAA: This pulse is used to hold the vertical flyback period of the output signal of the CCD chip.

SH1 and SH2: These are the sample and hold pulses for the 1H delay line (MD-30 board).

SP1 and SP2: These are the sample and hold pulses for chrominance separation (PR-72 board).

CLP1: This pulse is used to clamp the level of the optical black part o the output signal of the CCD chip.

CLP2 and CLP3: These are the 1H period clamp pulses.

ID: This is the identification signal for the R/B lines.

B line: H R line: L

3-11. AT-40 board

The AGC control signal generator, auto white balance controller, and auto white balance indicator driver signal generator are on this board.

The G DET signal derived from the G signal and the R/B DET signal derived from the R/B signal, which are fed from the PR-72 board, are clamped and their amplitude is doubled. For each signal, the signal in a time period, which is the same as for 1/9 of one field picture (1/3 in horizontal and 1/3 in vertical directions), is blanked by the BLKG signal, then the pedestal is added. These signals are compared with each other and output as the R-G COMP and B-G COMP signals, which are applied to the auto white balance controller circuit.

When the auto white balance trigger signal is applied to the auto white balance controller circuit, the R-G COMP and B-G COMP signals control the voltages used to control the corresponding chrominance signal attenuators, and these signals are output to the PR-72 board as the R and B attenuator control signals.

The AGC DET signal from the PR-72 board, used to detect the auto gain, is clamped and its amplitude is amplified by 3.3 times. Then, this signal is applied to the blanking cleaner and the pedestal adder.

After this, the signal is applied to the weighting amplifier so that the highlighting at the top part of a picture is not detected, then it is applied to the mean value detector. This detected signal is amplified by the DC amplifier, then goes to the PR-72 board as the AGC control signal.

When the level of the auto white balance trigger signal becomes HIGH, auto white balance adjustment is performed. When this adjustment is completed and OK is indicated, the level of the auto white balance indicator driver signal switches from H to L, then goes to the MB-37 board.

3-12. RG-13 board

The 4fsc signal generator, VCO control signal generator, and +12 V voltage regulator are on this board. To select an external or internal 4fsc signal or to select an internal or external VCO control signal is controlled by the EXT/INT signal.

The DXC-101/102 camera unit does not have a gen-lock unit; therefore, the level of the EXT/INT signal is kept LOW to select internally generated signals only. Of the internally generated signals, the frequencies of the 28 MHz VCO control signal for the NTSC system and of the 28 MHz 4fsc signal for the PAL system are adjusted on the RV2/RG-13 board.

The 4fsc output signal goes to the EN-40 board, and the VCO control output signal goes to the PG-12 board.

The MB-37 board supplies $+20\,\mathrm{V}$ to this $+12\,\mathrm{V}$ voltage regulator. For this regulator, $+5\,\mathrm{V}$ is used as a reference voltage to regulate the $+12\,\mathrm{V}$ output. This output voltage is supplied to the MD-30 and PG-12 boards.

3-13. MB-38 board (DXC-102/P only)

The GENLOCK DRIVER circuit and EXT 4fsc oscillator circuit are on the MB-38 board.

VBS, CK, SYNC, and SC signals from the camera module are sent to the GENLOCK DRIVER curcuit. Then, the SC COMP signal, which is the output signal of the MB-38 board, goes to the SG-110 board. This SC COMP signal is converted to a VCO control signal on the SG-110 board, then returned to the MB-38 board. This VCO control signal drives the EXT 4fsc oscillator, and the EXT 4fsc signal goes to the camera module.

3-14. SG-38 board (DXC-102/P only)

The GENOCK DRIVER circuit is on the SG-38 board. When a composite video signal is sent to the GENLOCK IN connector (BNC), the external sync mode is selected and the level of the GEN EXT/INT signal from pin 9 of IC1 becomes HIGH. The composite video signal sent to the GENLOCK IN connector (BNC) is sync-separated in the sync separator circuit of IC2 to output EXT CHROMA and EXT SYNC signals. The EXT SYNC signal is directly input to IC1 to send to the GENLOCK DRIVER inside the IC. The undesired Y-signal components of the EXT CHROMA signal are removed by the low-pass filter, composed of L4 and C5, then the signal is sent to IC1 to be converted to an EXT SC signal by the band-pass filter inside the IC.

This EXT SC signal is sent to the GENLOCK DRIVER inside the IC.

The INT SC signal from the camera module is phase-shifted and its duty cycle is set to 50% in IC4 to output two signals having opposite phases. IC3 selects one of these signals and the selected signal is sent to IC1. The PHASE SHIFTER in IC4 is controlled by the SC PHASE controller on the GENLOCK unit side and the phase selection of the signals in IC3 is controlled by the SC O°/180° selector.

The following signals, output from IC1, go to the SYNC GENERATOR inside the camera module when the NTSC/PAL selector mode signal and CK signal from the camera module are sent to IC1 with the signals described before.

HR: H-reset signal VR: V-reset signal

L ALT R: L ALT reset signal (PAL model only)

H COM: H-phase comparator signal SC COM: SC phase comparator signal

GEN EXT/INT: Detection signal for EXT/INT syrc mode

H: External sync L: Internal sync

When a composite video signal is not sent to the GENLOCK IN connector (BNC), the internal sync mode is selected. In this case, the level of the GEN EXT/NT signal output from pin 9 of IC1 is LOW.

3-15. RM-32 board (DXC-102/P only)

A 4-bit microprocessor is on the RM-32 board. The VD signal from the camera module and the AUTO W/B IND signal from the SW-34 board are sent to the microprocessor, and the microprocessor outputs and inputs the signal as serial data to and from the REMOTE connector.

The AUTO W/B TRIG signal and PEDESTAL control signal from the microprocessor go to the SW-34 and MB-38 boards. This microprocessor also outputs the CCU IND and W/B control signals. The CCU IND signal is separated into two signal paths.

The signal of one path goes to the SW-34 board. The signal of other path and the W/B control signal are sent to the NOR gate with the control signal from the W/B switch on the GENLOCK unit side, then the output signal of this gate goes to the MB-38 board as the W/B control signal.

3-16. SW-34 board (DXC-102/P only)

The AUTO W/B IND and AUTO W/B TRIG signal generator circuits are on the SW-34 board.

The AUTO W/B IND drive signal from the RM-32 board and the AUTO W/B IND drive signal from the camera module are sent to the AUTO W/B IND signal generator circuit to output the AUTO W/B IND signal which controls the AUTO W/B indicator LED on the GENLOCK unit side.

The AUTO W/B TRIG drive signal from the RM-32 board and the TRIG signal controlled by the AUTO W/B button on the GENLOCK unit side are sent to the AUTO W/B TRIG signal generator circuit. The AUTO W/B TRIG signal, which is the output of this circuit, goes to the camera module via the MB-38 board.

The W/B control signal controlled with the W/B switch on the GENLOCK unit side controls the AUTO W/B IND and AUTO W/B TRIG signal generator circuits. It also goes to the RM-32 board.

The GAIN control signal controlled with the GAIN switch goes to the camera module via the MB-38 board. The signals controlled with the H PHASE controller, SC PHASE controller, and SC 0 $^{\circ}$ /180 $^{\circ}$ switch go to the SG-38 board.

3-17. SG-110 board (DXC-102/P only)

The DC adder circuit and VCO control signal generator circuit are on the SG-110 board.

The VBS signal from the MB-38 board is added to the DC of the DC IN/VIDEO OUT connector, then it is output from the DC IN/VIDEO OUT connector.

The DC from the DC IN/VIDEO connector is sent to the voltage regulator, then supplied to the MB-38 board as the REG $\,+\,22\,$ V.

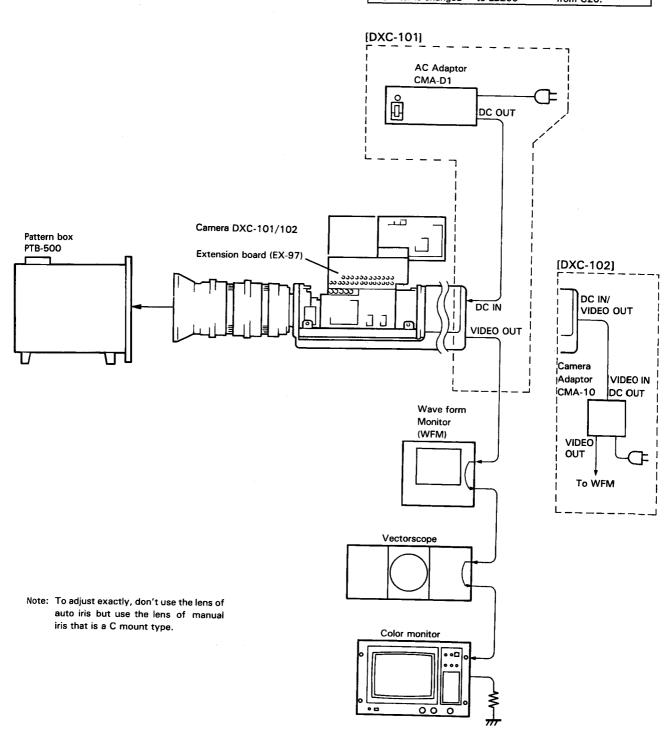
The SC COMP signal from the MB-38 board is sent to the VCO control signal generator circuit. The undesired chroma signal components are removed by the low-pass filter of IC1, then it goes to the MB-38 board as the VCO control signal.

SECTION 4 ALIGNMENT

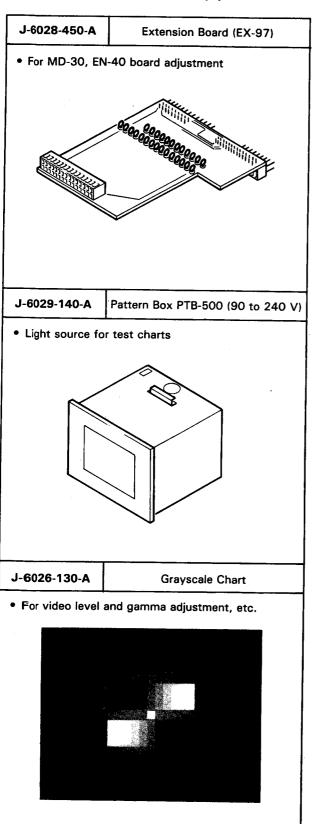
4-1. PREPARATION

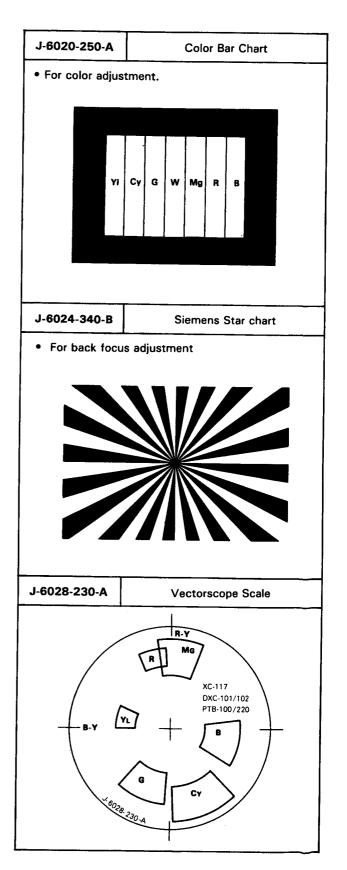
4-1-1. Connection for Adjustment

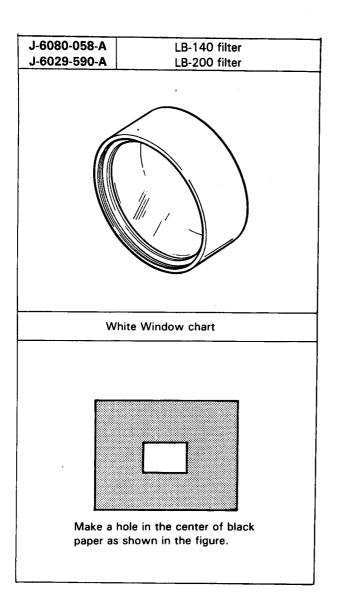
Revised-1 Change Information in SECTION 4
Pattern box is changed to PTB-500 from PTB-100.
Parts number of above
is changed to J-6029-140-A from J-6020-490-A.
The filter is changed to LB140 from C14.
The filter is changed to LB200 from C20.



4-1-2. Adjustment Fixtures and Equipment







Commercial measuring equipment and fixture

- Dual Trace Oscilloscope
- Vectorscope
- Wareform Monitor (WFM)
- Frequency Counter
- Digital Voltmeter
- Color Monitor
- Lens (C mount and manual iris type)

4-1-3 Switch Setting Position before Adjustment

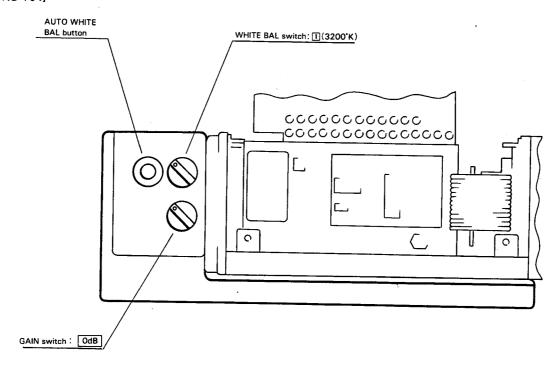
Set the switches as follows:

GAIN switch:

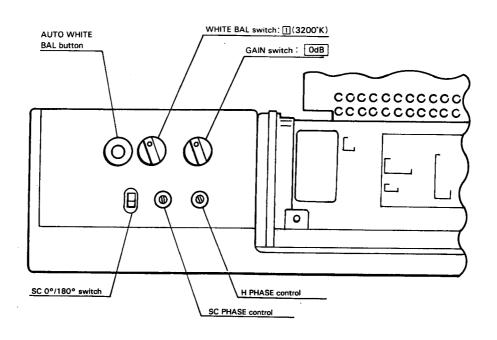
"0dB"

WHITE BAL switch: "1" (3200°K)

[DXC-101]



[DXC-102]



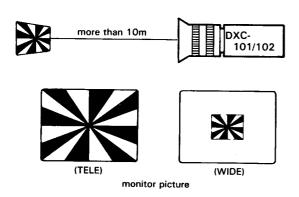
4-1-4. Mechanical Back Focus Adjustment

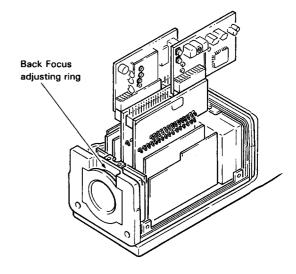
Subject: Siemens Star chart

Lens iris: Open

Adjust:

- Set the zoom control at TELE so as to obtain the maximum multiplication factor. Optically focus the image so as to obtain the maximum resolution.
- Set the zoom control at WIDE so as to obtain the minimum multiplication factor. Do not optically focus the image at this time.
 - Check whether the image is focused on the monitor while turning the zoom control from TELE to WIDE. If the image is not focused, properly set at back focus as follows.
- 3. When the zooming mechanism is set at WIDE, turn the back focus adjusting ring.
- 4. Repeat step 1 through 3 several times.





4-2. POWER SUPPLY SYSTEM

4-2-1. +12V Adjustment

Equipment: Digital voltmeter
Test point: TP1 (GND: GND terminal/Extension

board)/PG-12 board

Spec.: $+12V \pm 0.1V$

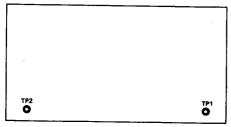
4-3. SYNC SYSTEM

4-3-1. Sub-carrier Frequency Adjustment

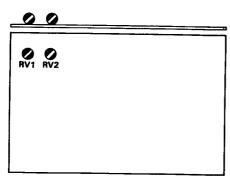
Equipment: Frequency counter
Test point: TP2 (GND: GND terminal/Extension

board)/PG-12 board

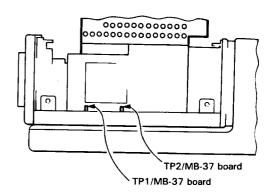
Spec.: $3,579,545 \pm 5 Hz$

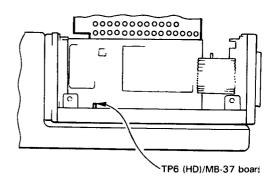


PG-12 Board (Component Side)



RG-13 Board (Component Side)





4-4. PROCESS SYSTEM

4-4-1. OdB Video Level Adjustment

Subject: Grayscale chart Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

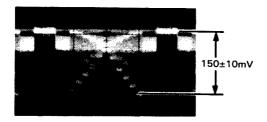
TP4 (GND: TP10/PR-72)/PR-72 board

Trigger: TP6 (HD)/MB-37 board Adj. point: **②**RV1/PR-72 board

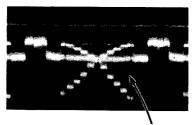
©RV6/PR-72 board

Adjust:

1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.

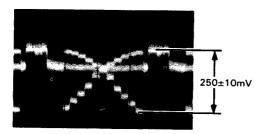


 Adjust the RV6/PR-72 board so that the flicker of the video waveform at TP4/PR-72 board is minimum overall.



Flicker of the video waveform should be minimum overall.

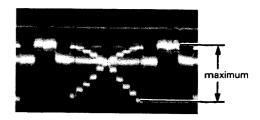
3. Adjust the **②** RV1/PR-72 board so that the video level at TP4/PR-72 board is 250 ± 10 mV.



Note:

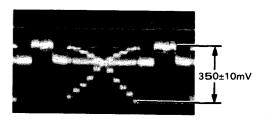
If it is unable to accomplish this adjustment, be sure to carry out step 4 through 6 as follows.

 Preset the ORV1/PR-72 board so that the video level at TP4/PR-72 board is maximum.



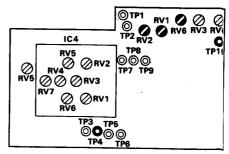
Adjust the

RV2/PR-72 board so that the video level at TP4/PR-72 board is 350 ± 10 mV.



Adjust the ♥RV1/PR-72 board so that the video level at TP4/PR-72 board is 250 ± 10 mV.





PR-72 Board (Component Side)

4-4-2. AGC Adjustment

Subject:

Grayscall chart

Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

TP4 (GND: TP10/PR-72)/PR-72 board

Trigger:

TP6 (HD)/MB-37 board

Adj. point:

⊘ RV1/AT-40 board

RV4/AT-40 board

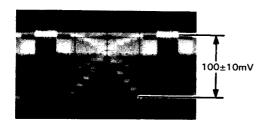
② RV1/PR-72 board **⊘** RV2/PR-72 board

Preparation: Switch setting

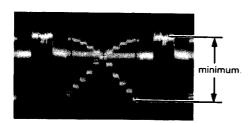
GAIN switch: "AUTO" position

Adjust:

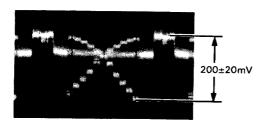
1. Adjust the lens iris so that the video level at TP1/MB-37 board is 100 ± 10 mV.



2. Turn the ORV1/AT-40 board counterclockwise of so that the video level at TP4/PR-72 board is minimum.

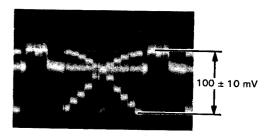


3. Adjust the ORV4/AT-40 board so that the video level at TP4/PR-72 board is 200 ± 20 mV.

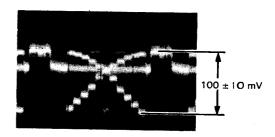


4. Set the GAIN switch at "12 dB".

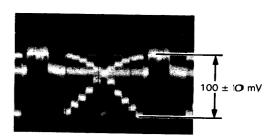
5. Adjust the lens iris so that the video level at TP4/PR-72 board is 100 ± 10 mV.



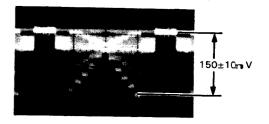
- 6. Set the GAIN switch at "AUTO".
- 7. Adjust the ORV2/PR-72 board so that the video level at TP4/PR-72 board is 100 ± 10 mV.

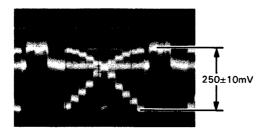


- 8. Set the GAIN switch at "12 dB".
- 9. Adjust the ORV1/PR-72 board so that the video level at TP4/PR-72 board is 100 \pm 10 mV.



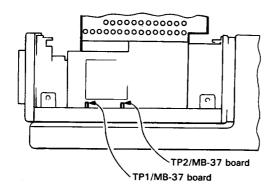
- 10. Set the GAIN switch at "AUTO".
- 11. Adjust the lens iris so that the video evel at TP1/MB-37 board is 150 ± 10 mV.

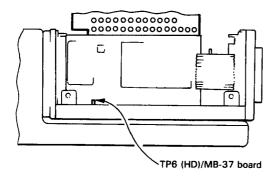


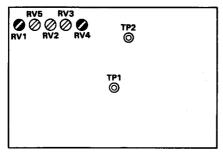


NOTE:

When carring out this adjustment, be sure to Set the GAIN switch to "0" and carry out 4-5-1. OdB Video Level Adjustment.







AT-40 Board (Component Side)

4-4-3. GAMMA Adjustment

Subject: Grayscale chart Equipment: Oscilloscope

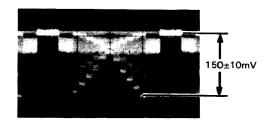
Equipment: Oscilloscope
Test point: TP1 (GND: TP2/MB-37)/MB-37 board

CN1-A4 pin (GND: GND terminal/Extension

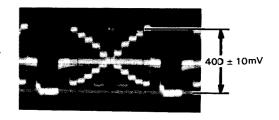
board)/MD-30 board

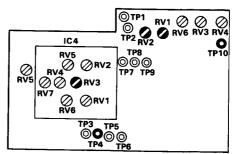
Trigger: TP6 (HD)/MB-37 board Adj. point: IC4- • RV3/PR-72 board

Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



 Adjust the IC4- ◆RV3/PR-72 board so that the level "A" at CN1-A4 pin/MD-30 board is 400 ± 10 mV.





PR-72 Board (Component Side)

4-4-4. Pre-pedestal Adjustment

Closed "C"

Equipment: Oscilloscope

Test point:

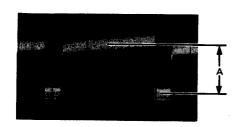
CN1-A4 pin (GND: GND terminal/Extension board)/MD-30 board

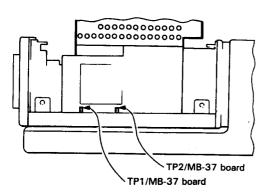
Trigger:

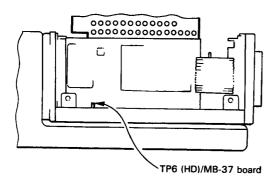
TP6 (HD)/MB-37 board IC4- ORV1/PR-72 board

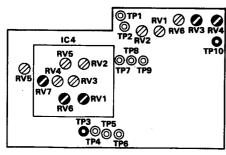
Adj. point: Spec:

 $A=50 \pm 4 \text{ mV}$









PR-72 Board (Component Side)

4-4-5. R/B Gain Adjustment

Subject:

Grayscale chart

Equipment: Oscilloscope

Test point:

TP1 (GND: TP2/MB-37)/MB-37 board TP3 (GND: TP10/PR-72)/PR-72 board

Trigger:

TP6 (HD)/MB-37 board

Adj. point:

Adjust:

IC4- ORV6/PR-72 board

IC4- ORV7/PR-72 board

Preparation: 1. Set the ORV3, ORV4/PR-72 board to

mechanicalcenter.

[Front View]

[Top View]



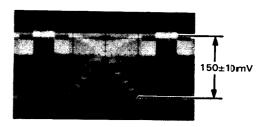


2. Switch setting

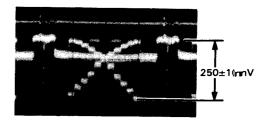
WHITE BAL Switch: "3" position

3. Cover the LB140 filter in front of the lens.

1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



2. Adjust the IC4- ORV6, ORV7/PR-72 board so that the video level at TP3/PR-72 board is 250 \pm 10 mV, and repeat this adjustment several times by turns.



NOTE:

After this adjustment, be sure to remove C14 filter attached the lens and return the WHITE BAL switch to "1".

4-4-6. 3200°K R/B Gain Ajustment

Subject: Grayscale chart Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

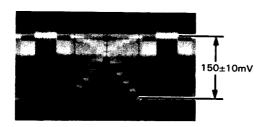
TP3 (GND: TP10/PR-72)/PR-72 board

Trigger: Adj. point: TP6 (HD)/MB-37 board PV3/PR-72 board

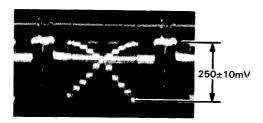
⊘ RV4/PR-72 board

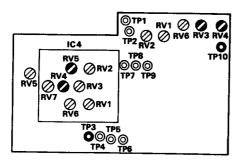
Adjust:

1. Adjust the lens iris so that the video level at TP1/PR-72 board is 150 ± 10 mV.



 Adjust the ORV3, ORV4/PR-72 board so that the video level at TP3/PR-72 board is 250 ± 10 mV, and repeat this adjustment several times by turns.





PR-72 Board (Component Side)

4-4-7. R/B Offset Adjustment

Lens: Closed "C" Equipment: Oscilloscope

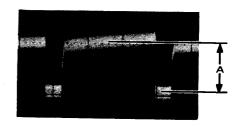
Test point: CN1-B4 pin (GND: GND terminal/Extension

board)/MD-30 board

Trigger: TP6 (HD)/MB-37 board Adj. point: IC4- ②RV4/PR-72 board

IC4- ORV5/PR-72 board

Spec: $A=50 \pm 4 \text{ mV}$



4-4-8. Auto White Balance Adjustment

White window chart

Equipment: Waveform Monitor and Oscilloscope

Adj. point:

② RV2/AT-40 board

RV3/AT-40 board

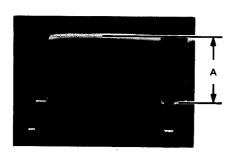
Preparation: 1. RESPONSE switch of WFM

→ "LUM" position

Adjust:

2. Cover the LB200 filter in front of the lens. 1. Test point: VIDEO OUT

Adj. point: lens iris Spec.: $A = 50 \pm 5$ IRE.



2. Set the WHITE BAL switch at "AUTO".

3. Equipment: Oscilloscope

Test point: CH1 CN1-A4 pin/MD 30 board

CH2 CN1-B4 pin/MD-30 board (Set the vertical deflections of

CH1 CH2 at the same DC voltage range.)

Mode:

ADD mode (CH2 is "INVERT".)

Trigger:

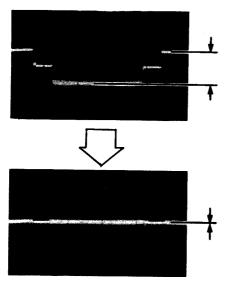
TP6 (HD)/MB-37 board

② RV3/AT-40 board

Adjust:

Adjust so that the wareform is flat, when the AUTO WHITE

BAL button is pushed.



4. Repeat step3. several times.

4-4-9. LOW LIGHT Adjustment

Subject:

White Window chart **Equipment: Waveform Monitor**

Test point:

VIDEO OUT

AUTO W/B Indication LED

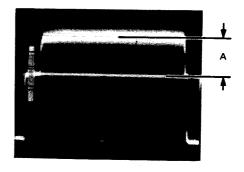
Adj. point: **②** RV5/AT-40 board

Preparation: Set the WHITE BAL switch at "AUTO".

Adjust:

1. Adj. point: lens iris

Spec.: $A = 30 \pm 5$ IRE.

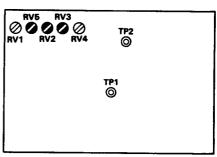


2. Adjust the ORV5/AT-40 board so that the AUTO W/B Indication LED does not illuminate in spite of pushing the AUTO W/B button.

Note:

After this adjustment, be sure to set the

WHITE BAL switch at "1".



AT-40 Board (Component Side)

4-4-10. Video Clip Adjustment

Subject: Grayscale chart Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

IC4-26 pin (GND: TP10/PR-72)/PR-72 board

TP7 (GND: TP10/PR-72)/PR-72 board

Trigger: Adj. point: TP6 (HD)/MB-37 board ORV5/PR-72 board IC4- ORV2/PR-72 board

Adjust:

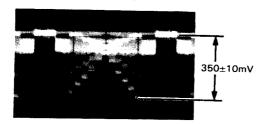
1. Adjust the lens iris so that the video level at TP1/MB-37 board is 450 ± 10 mV.



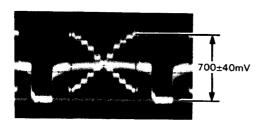
 Adjust the ORV5/PR-72 board so that the video level at IC4-26 pin/PR-72 board clips at 400 ± 10 mV.

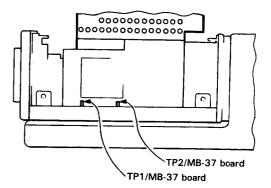


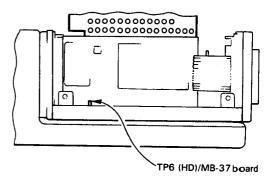
3. Adjust the lens iris so that the video level at TP1/MB-37 board is 350 \pm 10 mV.

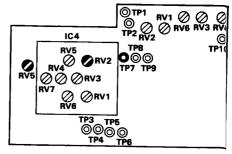


 Adjust the IC4- ORV2/PR-72 board so that the video level at TP7/PR-72 board is 700 ± 40 mV.









PR-72 Board (Component Side)

4-4-11. G KNEE Adjustment

Subject: Grayscale chart Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

TP1 (GND: GND terminal/Extension

board)/MD-30 board TP6 (HD)/MB-37 board

Trigger: Adj. point:

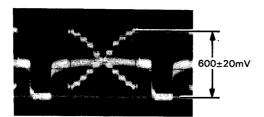
Adjust:

⊘ RV1/MD-30 board

1. Adjust the lens iris so that the video level at TP1/MB-37 board is $350 \pm 10 \text{ mV}$.

350±10mV

2. Adjust the ORV1/MD-30 board so that the video level at TP1/MD-30 board is $600 \pm 20 \text{ mV}.$



4-4-12. R/B KNEE Adjustment

Subject: Grayscale chart Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

TP4 (GND: GND terminal/Extension

board)/MD-30 board TP6 (HD)/MB-37 board

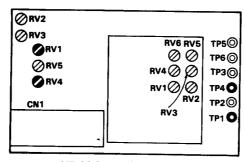
Trigger: **⊘** RV4/MD-30 board Adj. point:

1. Adjust the lens iris so that the video level Adjust: at TP1/MB-37 board is 350 ± 10 mV.



2. Adjust the ORV4/MD-30 board so that the video level at TP4/MD-30 board is $600 \pm 20 \text{ mV}.$





MD-30 Board (Component Side)

4-5. VIDEO OUT SYSTEM

4-5-1. RB0/RB1/RB2 Adjustment

Subject: Grayscale chart Equipment: Oscilloscope

Test point: TP1/MB-37 board

TP4/MD-30 board TP5/MD-30 board TP6/MD-30 board

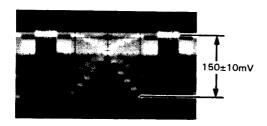
(GND: TP2/MB-37 or GND terminal/Exten-

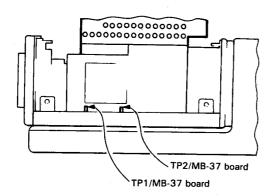
sion board)

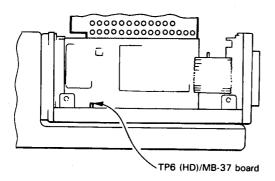
Trigger: TP6 (HD)/MB-37 board Adj. point: IC2- © RV2/MD-30 board

IC2- ORV4/MD-30 board

Adjust: 1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.







2. Test point: CH1 TP5/MD-30 Board

CH2 TP4/MD-30 Board

CH2: "INVERT"

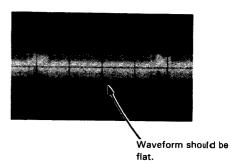
Mode: ADD mode

DC range: 50 mV/Div (Set the vertical

deflections of CH 1 and CH 2 at the same DC voltage

range.)

3. Adjust the IC2- ORV2/MD-30 board so that the waveform is flat.

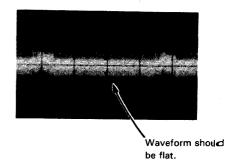


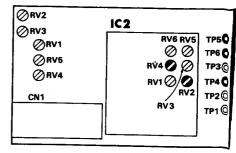
4. Test point: CH1 TP6/MD-30 board CH2 TP4/MD-30 board

CH2: "INVERT"

Mode: ADD mode

5. Adjust the IC2- • RV4/MD-30 board so that the waveform is flat.





MD-30 Board (Component Side)

4-5-2. G0/G1/G2 Adjustment

Subject:

Grayscale chart

Equipment: Oscilloscope

Test point: TP1/MB-37 board

TP1/MD-30 board TP2/MD-30 board TP3/MD-30 board

(GND: TP10/PR-72 or GND terminal/Exten-

sion board)

Trigger: Adj. point:

TP6 (HD)/MB-37 board IC2- ORV1/MD-30 board

IC2- ORV3/MD-30 board

Adjust:

1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



2. Test point: CH1 TP2/MD-30 board CH2 TP1/MD-30 board

CH2: "INVERT"

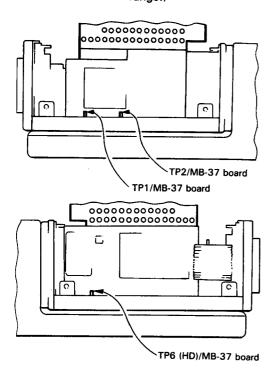
Mode:

ADD mode

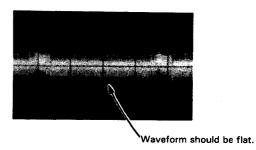
DC range: 50 mV/Div (Set the vertical

deflections of CH1 and CH2 at the same DC voltage

range.)



3. Adjust the IC2- ORV1/MD-30 board so that the waveform is flat.



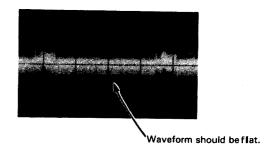
4. Test point: CH1 TP3/MD-30 board CH2 TP1/MD-30 board

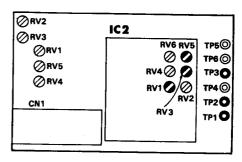
CH2: "INVERT"

Mode:

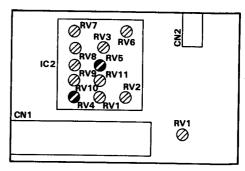
ADD mode

5. Adjust the IC2- ORV3/MD-30 board so that the waveform is flat.





MD-30 Board (Component Side)



EN-40 Board (Component Side)

4-5-3. MPX DC Adjustment

Lens iris: Closed "C"

Equipment: Vectorscope "MAX GAIN" Adj. point: IC2- © RV5/MD-30 board

Adjust: Adjust th

Adjust the IC2- @ RV5/MD-30 board so that

the bright spot at vectorscope screen

becomes one dot.

4-5-4. Carrier Balance Adjustment

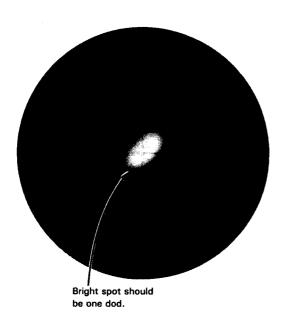
Lens iris: Closed "C"

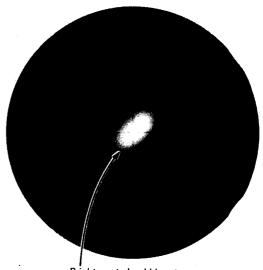
Equipment: Vectorscope "MAX GAIN" Adj. point: IC2- • RV4/EN-40 board

IC2- ORV5/EN-40 board

Adjust: Adjust the IC2- ORV4, ORV5/EN-40 board

by turns several times till the bright spot is at the center of the vectorscope screen.





Bright spot should be at the center of the vectorscope screen.

4-5-5. Pedestal Level Adjustment

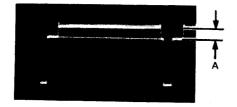
Lens iris: Closed "C"

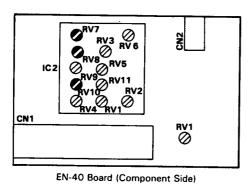
Equipment: Waveform monitor Adj. point: IC2- • RV8/EN-40 board

Preparation: RESPONSE switch of Waveform monitor

→ "LUM" position

Spec.: $A=7.5 \pm 1$ IRE





4-5-6. Y Level Adjustment

Subject: Grayscale chart

Equipment: Oscilloscope and WFM

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

IC2-24pin (GND: GND terminal/Extension

board)/EN-40 board

VIDEO OUT

Trigger: TP6 (HD)/MB-37 board

Adj. point: IC2- ORV7/EN-40 board

IC2- ORV10/EN-40 board

Preparation: RESPONSE switch of WFM

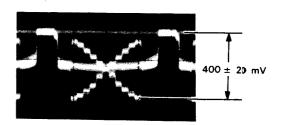
→ "LUM" position

Adjust:

1. Adjust the lens iris so that the video level at TP1/MB-37 board is 150 ± 10 mV.



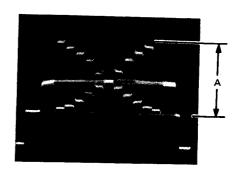
Adjust the IC2- ◆RV7/EN-40 board so that the video level at IC2-24pin//EN-40 board is 400 ± 20 mV.



3. Test point: VIDEO OUT

Adj. point: IC2- ORV10/EN-40 board

Spec.: $A = 100 \pm 5$ IRE



4-5-7. White Clip Adjustment

Subject:

Grayscale chart

Lens iris:

Adjust:

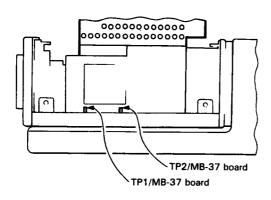
F2.0

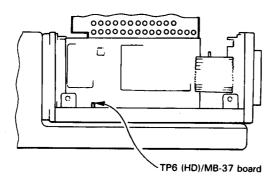
Equipment: Waveform monitor (WFM) Adj. point: IC2- ORV9/EN-40 board

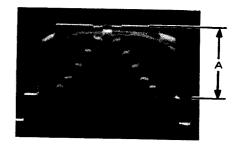
Adjust the IC2- ORV9/EN-40 board so that

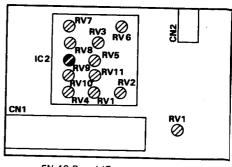
the video waveform clips at Specification.

Spec.: $A=120 \pm 10$ IRE









EN-40 Board (Component Side)

4-5-8. Color Vector Adjustment

Subject:

Color Bar chart

Equipment: WFM and Vectorscope

Adj. point: VIDEO OUT

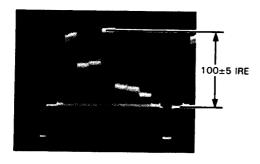
Preparation: RESPONSE switch of WFM

→ "LUM" position

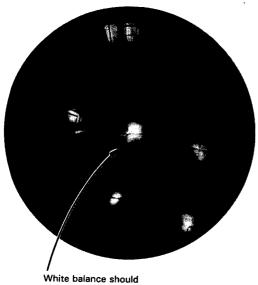
Adjust:

1. Adjust the lens iris so that the VIDEO

OUT level is 100 ± 5 IRE.



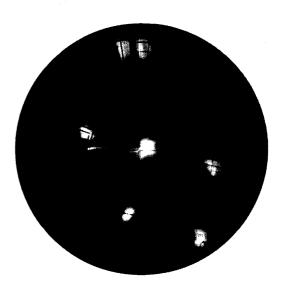
2. When the white balance is not adjusted, set the WHITE BAL switch at "AUTO" position, and push the AUTO WHITE BAL button.

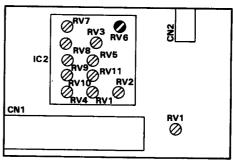


be adjusted.

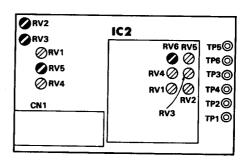
3. Adjust the following ORVs by turns several times till the respective spots conform to the Spec.

⊘ RV2/MD-30 board **⊘** RV3/MD-30 board @ RV5/MD-30 board IC2- ORV6/EN-40 board IC2- ORV6/MD-30 board





EN-40 Board (Component Side)



MD-30 Board (Component Side)

4-5-9. Chroma Suppress Adjustment

Subject:

Color Bar chart

Equipment: WFM and Vectorscope

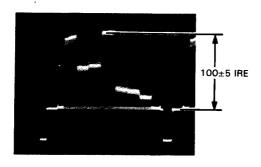
Test point: VIDEO OUT

Preparation: RESPONSE switch of WFM → "LUM" position

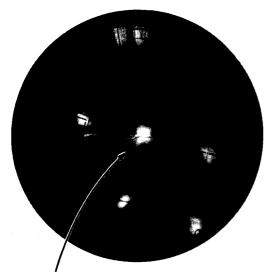
Adjust:

1. Adjust the lens iris so that the VIDEO

OUT level is 100 ± 5 IRE.

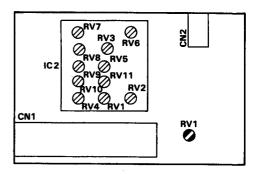


- 2. Set the GAIN switch at "6dB".
- 3. Adjust the RV1/EN-40 board so that the white signal spot is at the center of the vectorscope screen.



White signal spot should be at the center of the vectorscope screen.

Note: After this adjustment, be sure to set the GAIN switch at "0dB".



EN-40 Board (Component Side)

4-5-10. Mixed Color Correction Adjustment

Subject: Grayscale chart

Equipment: WFM

Test point: VIDEO OUT

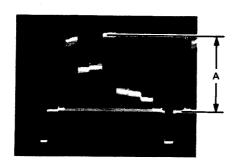
Adj. point: • RV6/PR-72 board

Preparation: RESPONSE switch of WFM

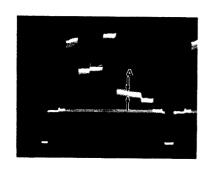
→ "LUM" position

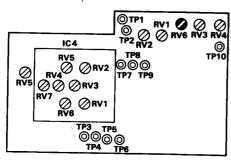
Adjust:

1. Adj. point: lens iris Spec.: $A = 700 \pm 10 \text{ mV}$



- 2. GAIN switch of WFM → MAX GAIN
- 3. Adjust the O RV6/PR-72 board so that level "A" at WFM is less than 36mV.





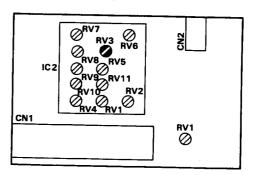
PR-72 Board (Component Side)

4-5-11. Bust Level Adjustment

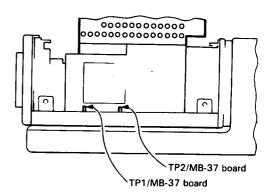
Equipment: Waveform monitor (WFM)
Adj. point: IC2- ©RV3/EN-40 board
Preparation: RESPONSE switch of WFM

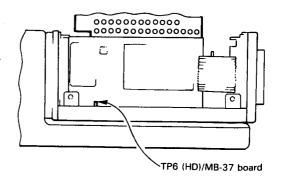
 \rightarrow "FLAT" position Spec.: A=300 ± 15 mV





EN-40 Board (Component Side)





4-5-12. Aperture Adjustment

NOTE:

During this adjustment, make sure that the

lens is just focused as the aperture level will

vary with lens focus.

Subject:

Grayscale chart Equipment: Oscilloscope

Test point: TP1 (GND: TP2/MB-37)/MB-37 board

CN1-A4 pin (GND: GND terminal/Extension

board)/EN-40 board

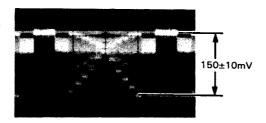
Trigger: Adj. point:

TP6 (HD)/MB-37 board IC2- ORV1/EN-40 board

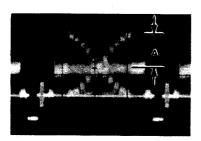
IC2- ORV2/EN-40 board

Adjust:

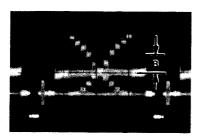
1. Adjust the lens iris so that video level at TP1/MB-37 board is 150 ± 10 mV.



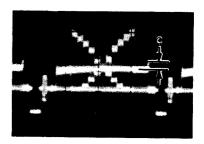
2. Preset the IC2- ORV1/EN-40 board so that the level "A" at CN1-A14 pin/EN-40 board is maximum.

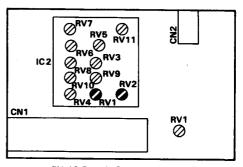


3. Adjust the IC2- ORV2/EN-40 board so that the level "B" at CN1-A4 pin/EN-40 board is 200 ± 20 mV.

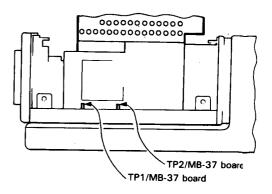


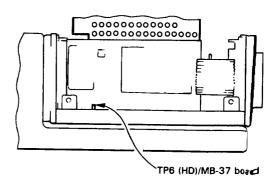
4. Adjust the IC2- @ RV1/EN-40 board so that the level "C" at CN1-A4 pin/EN-40 board is 100 ± 20 mV.





EN-40 Board (Component Side)



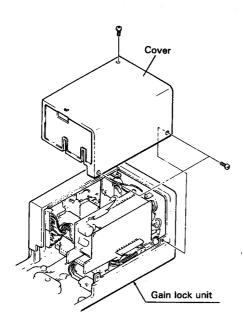


4-5-13. Video DC Level Adjustment (DXC-102 only)

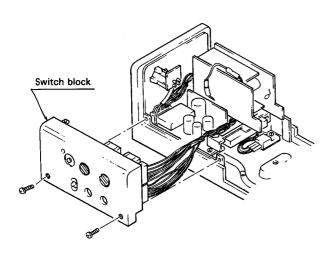
Preparations:

Disassemble the gain lock unit as follows:

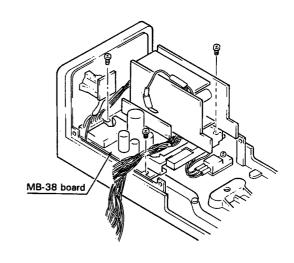
- Remove the three camera unit fixing screws (one at the top and two at the bottom), then remove the camera unit from the gain lock unit.
- 2. Remove the three cover fixing screws from the gain lock unit, then remove the cover.



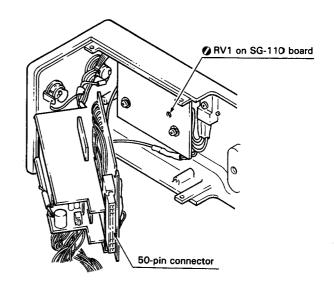
3. Remove the two switch block fixing screws, then remove the switch block. (Do not remove the connectors from the unit.)



4. Remove the three MB-38 board fixing screws, then remove the board. (Do not remove the connectors from the unit.)



5. Place the gain lock unit vertically as shown below:



Notes

- Before adjustment, connect the 50-pin connector of the MB-38 board to its counterpart on the camera unit.
- To assemble the gain lock unit, follow the disassembly procedure in reverse order.

Lens: Close "C"

Equipment: Oscilloscope

Test points: Pin 7 of IC2 (chassis ground) on SG-110

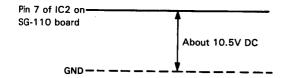
board

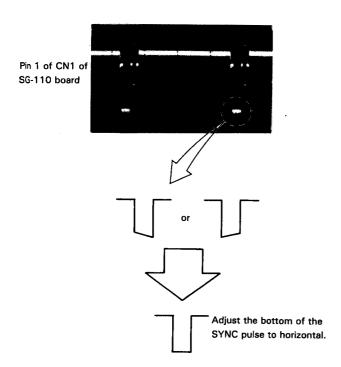
Pin 1 of CN1 (chassis ground) of SG-110

board

Adj. Point: ORV1 on SG-110 PC board

Adjust: Adjust •RV1 on the SG-110 board so that pin 7 of IC2 on the SG-110 PC board is about 10.5V DC and the SYNC pulse bottom of the waveform at pin 1 of CN1 is horizontal.

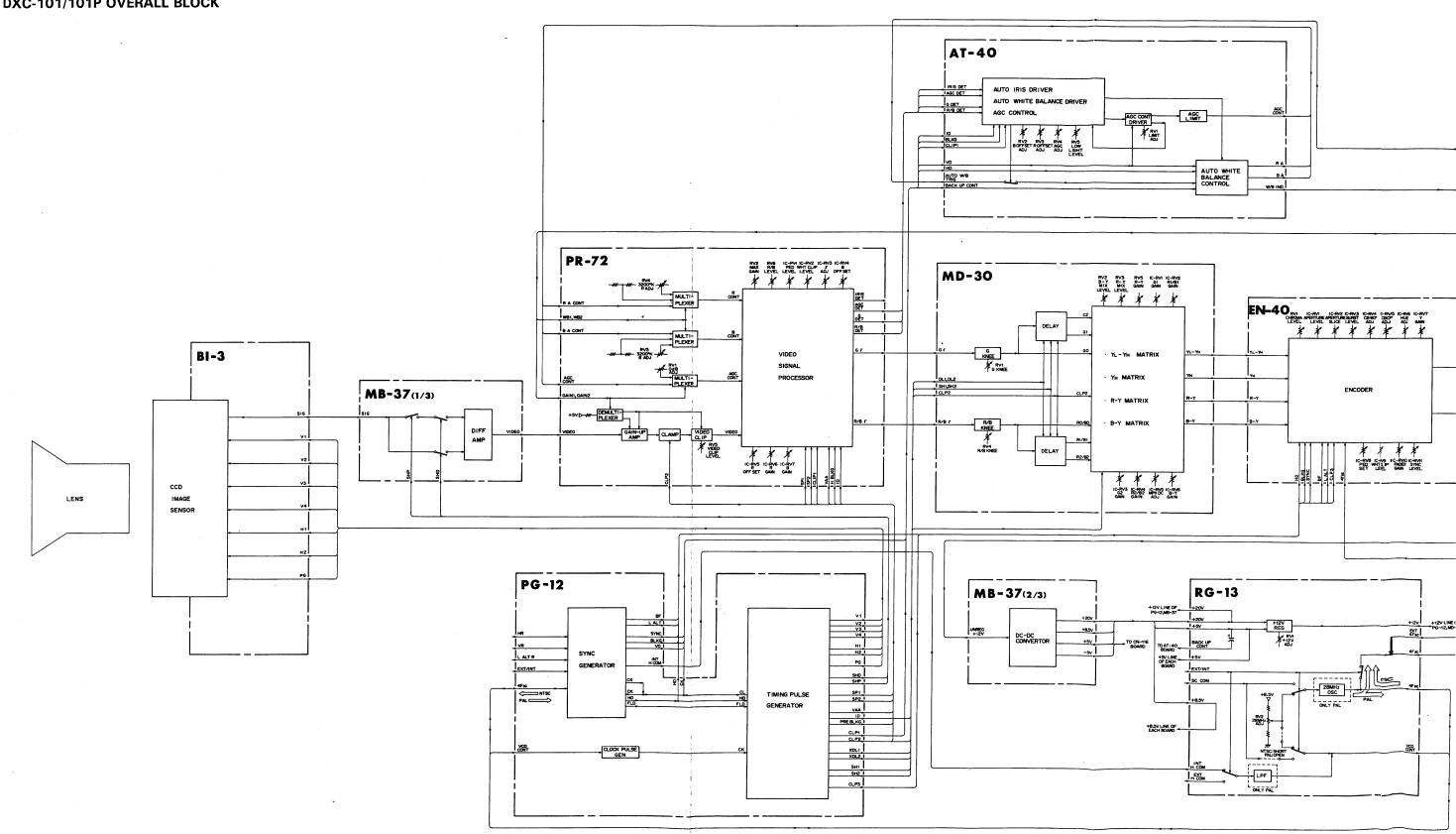


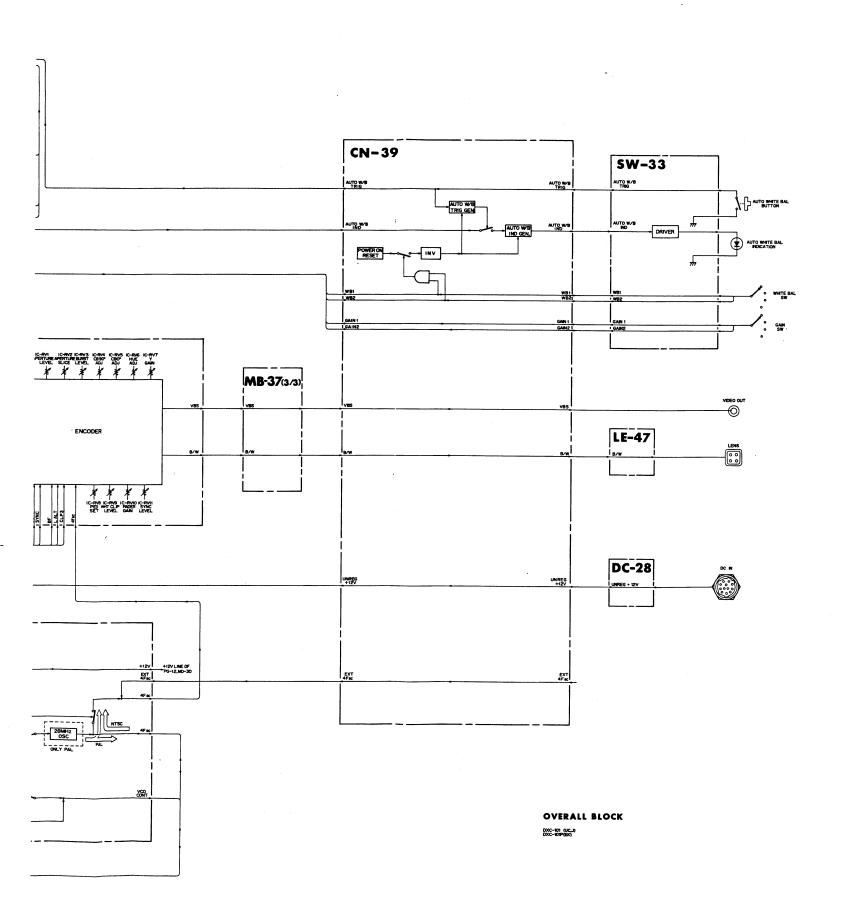


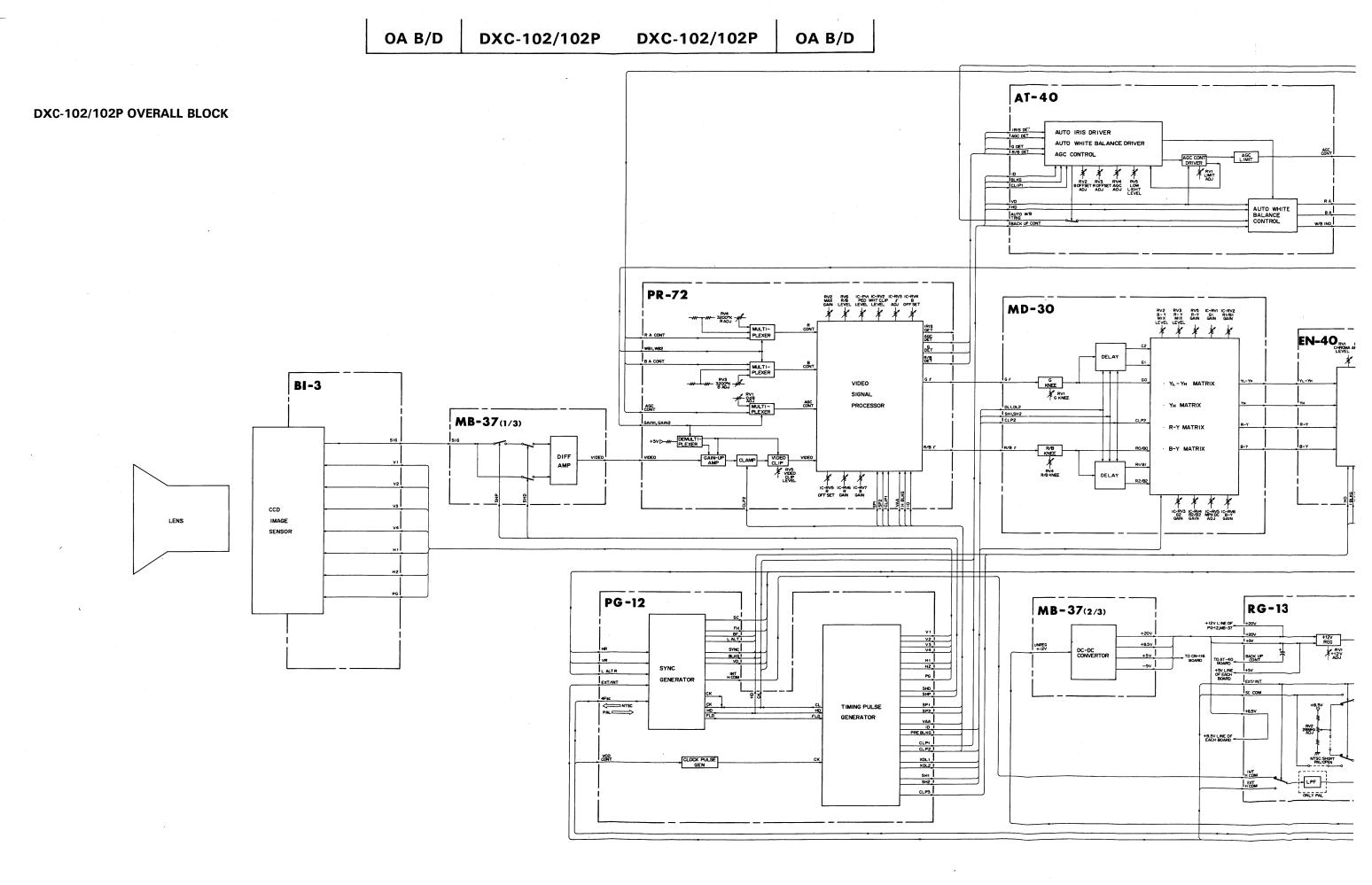
DXC-101/101P DXC-101/101P OA B/D OA B/D

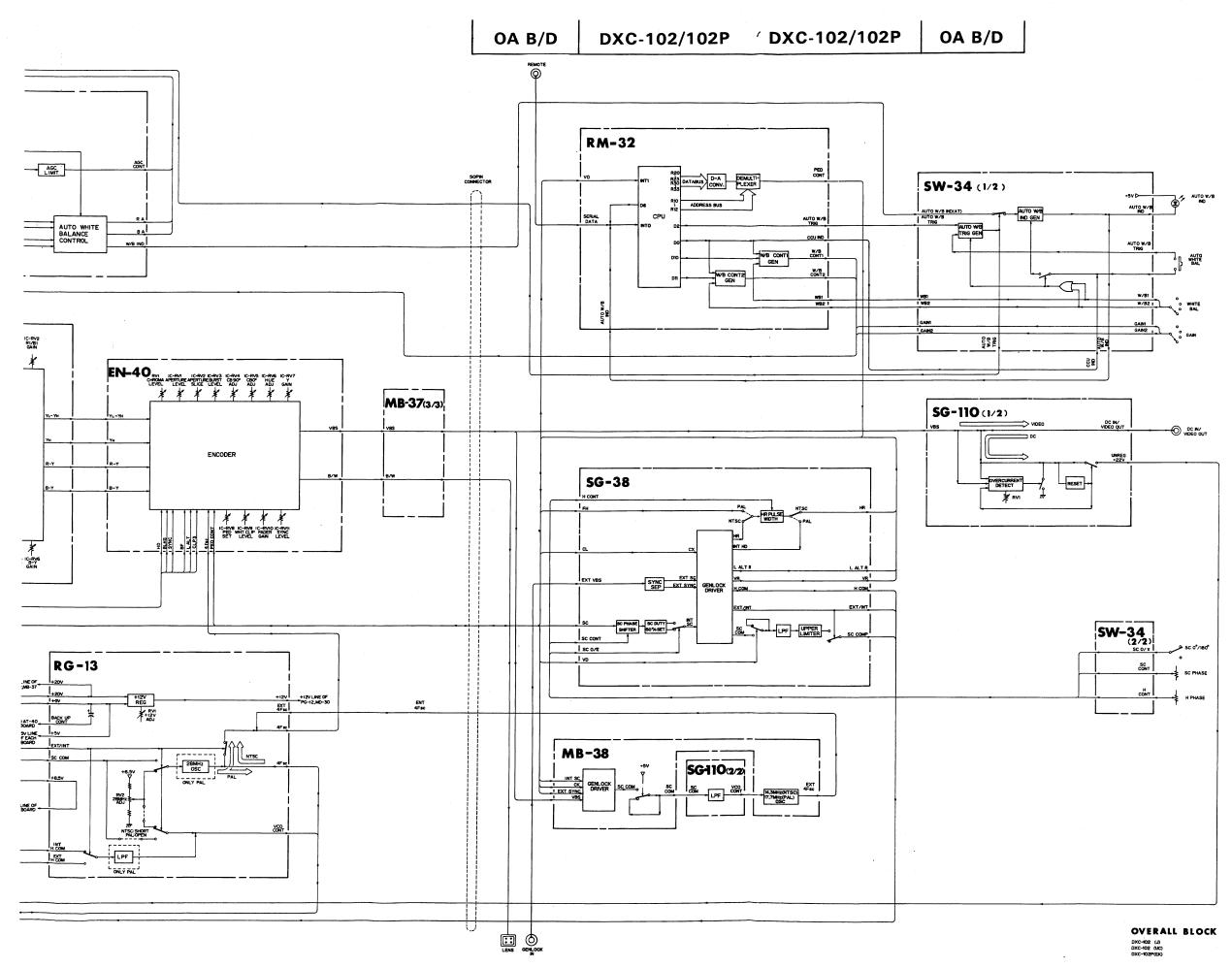
SECTION5 DIAGRAM

DXC-101/101P OVERALL BLOCK

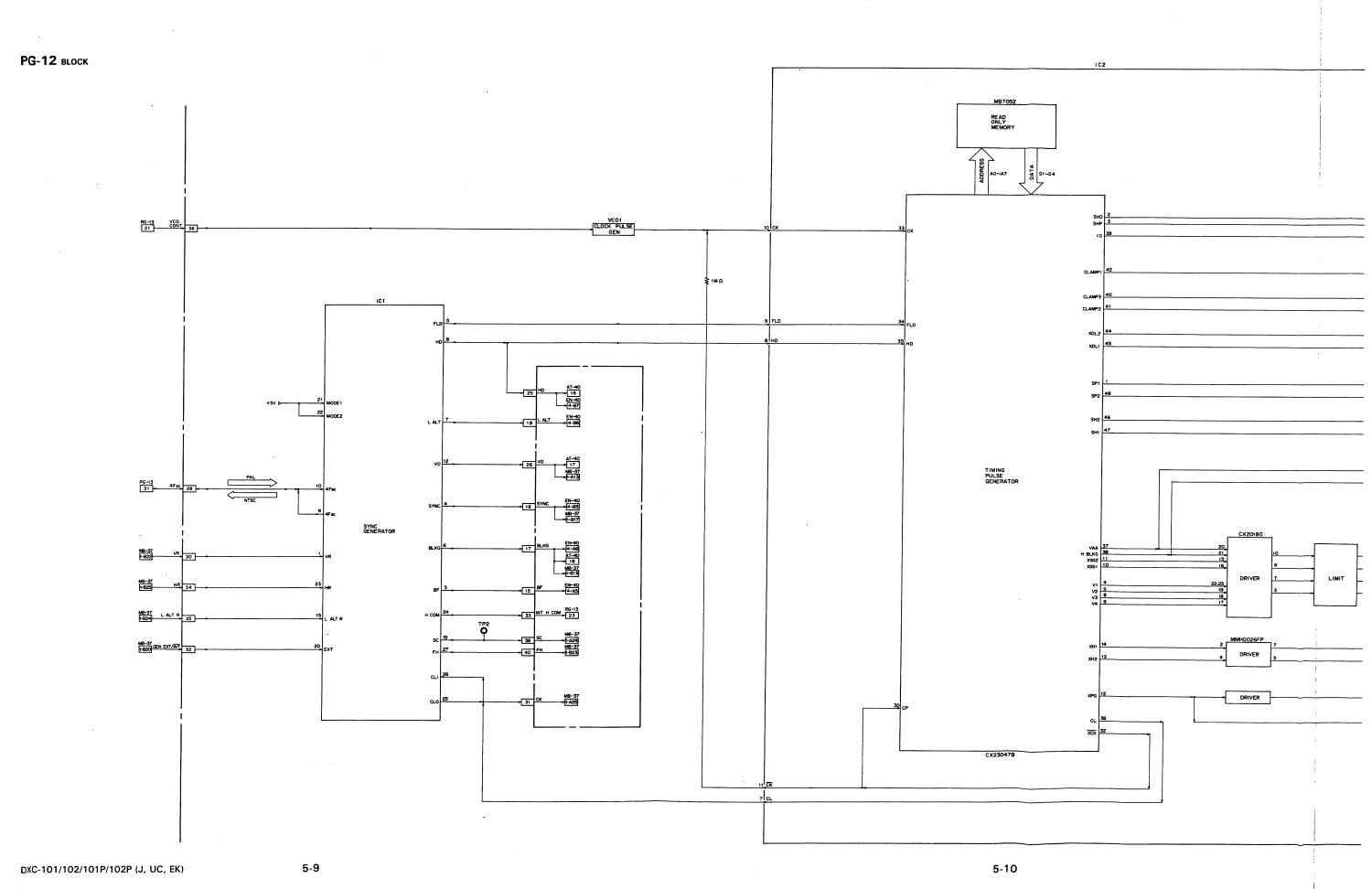


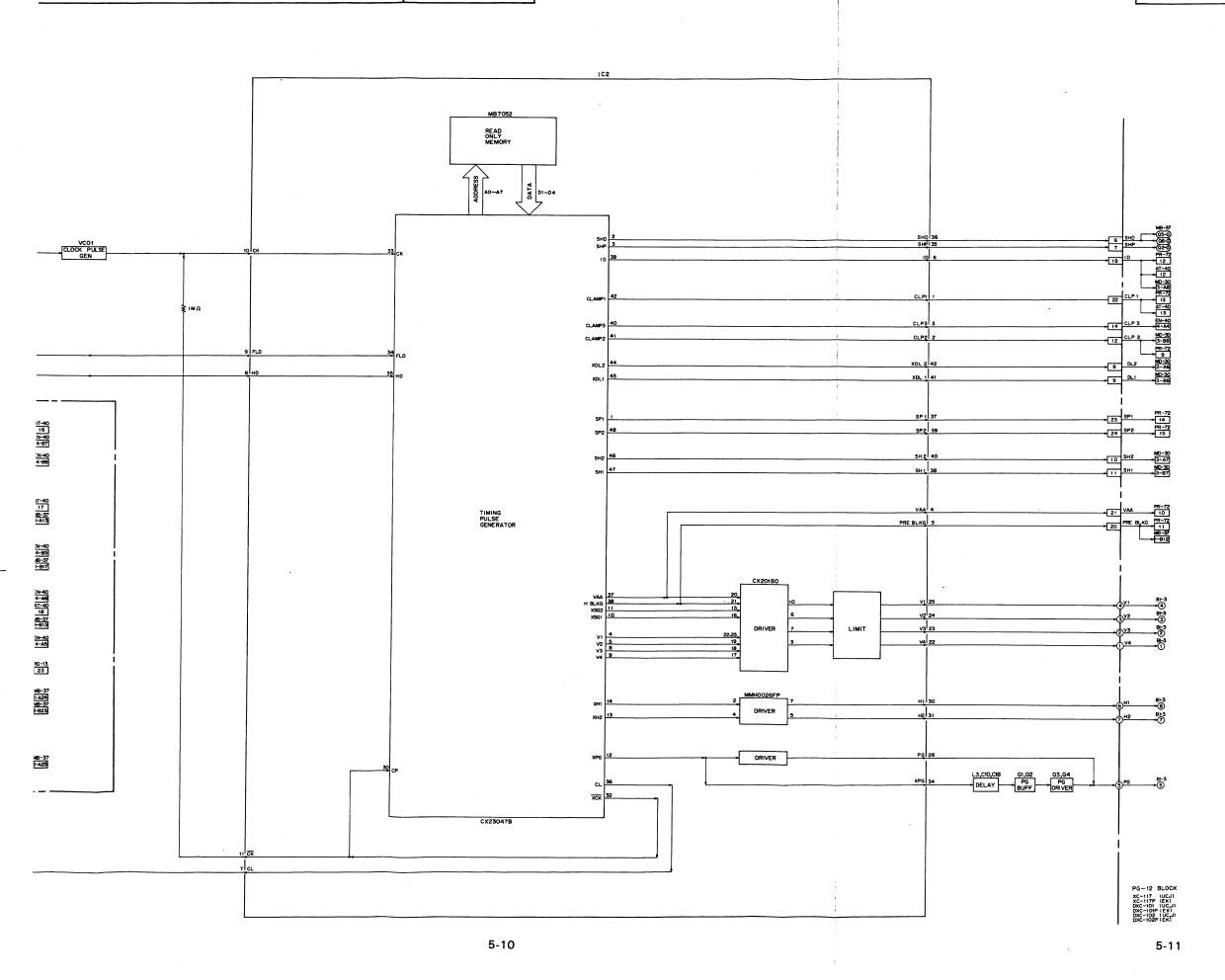






5-7

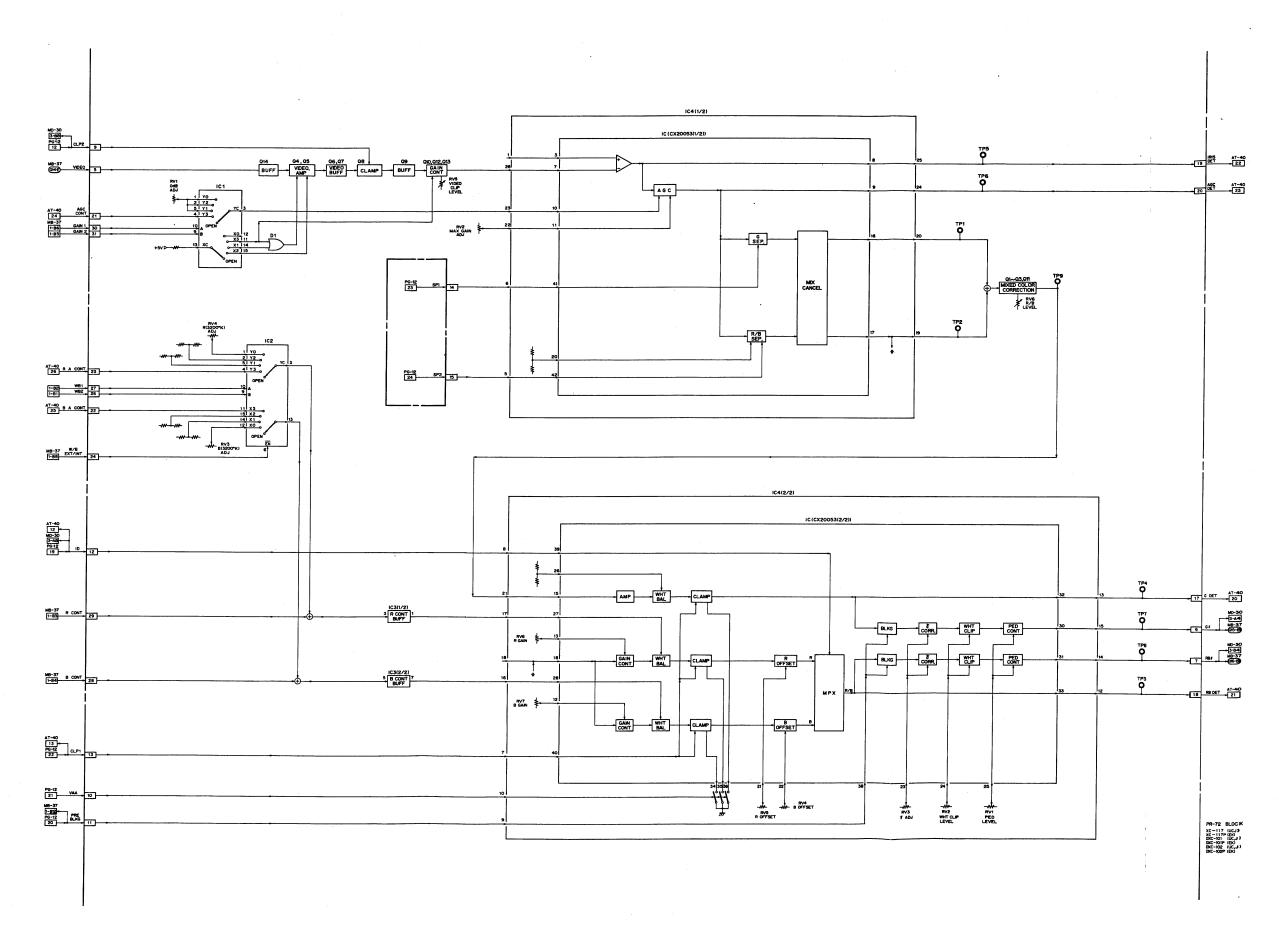


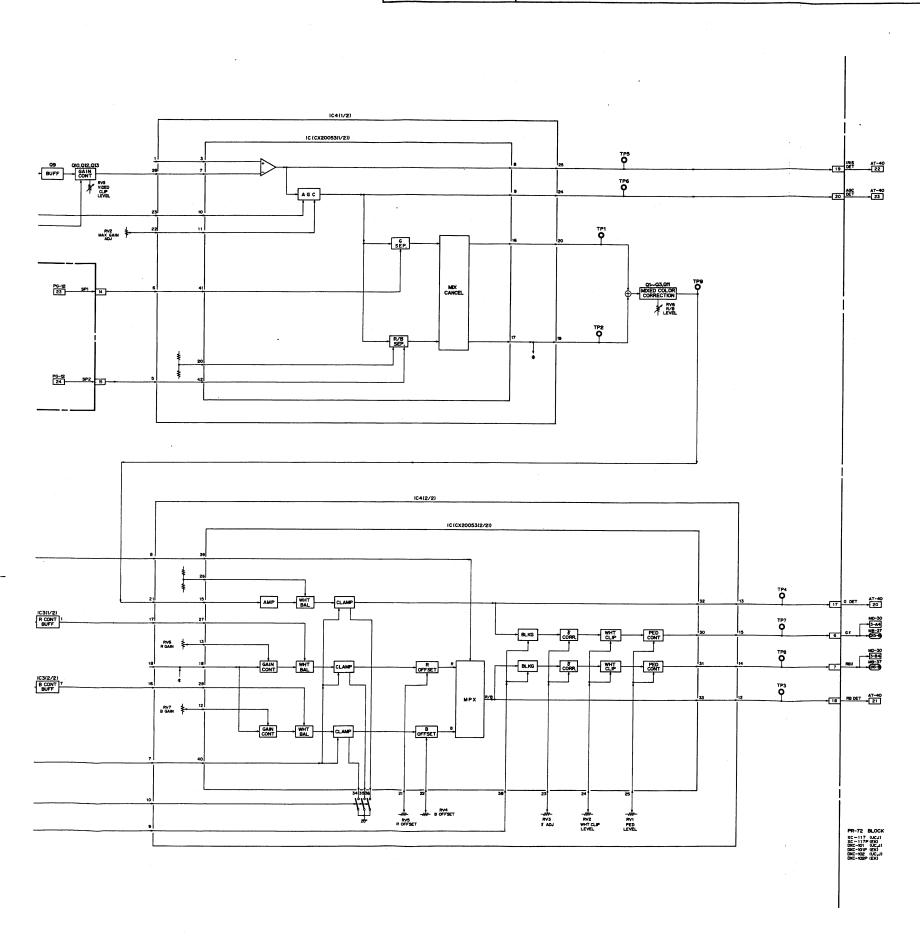


DXC-101/101P/102/102P

02/102P

PR-72 BLOCK





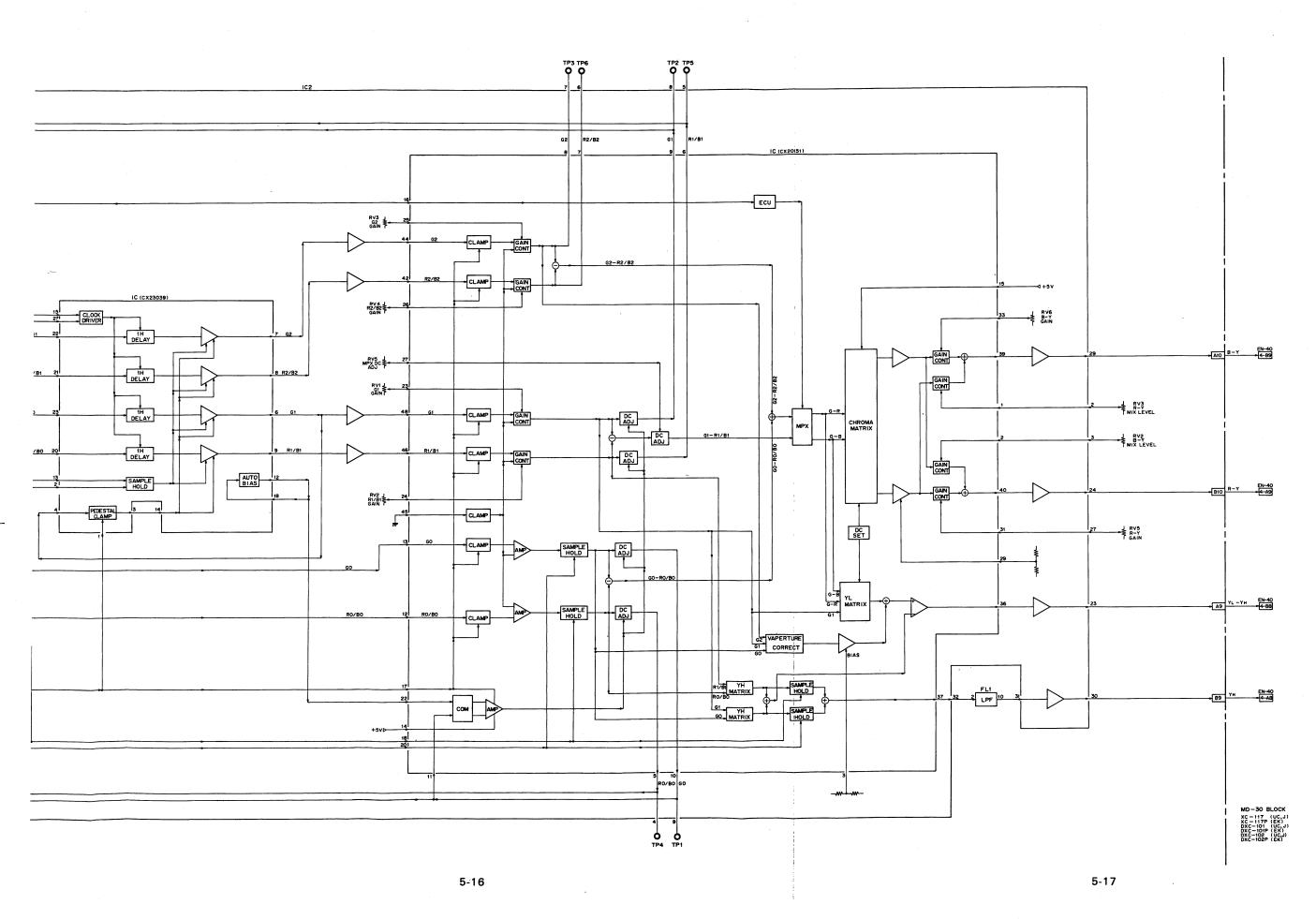
DXC-101/102/101P/102P (J, UC, EK)

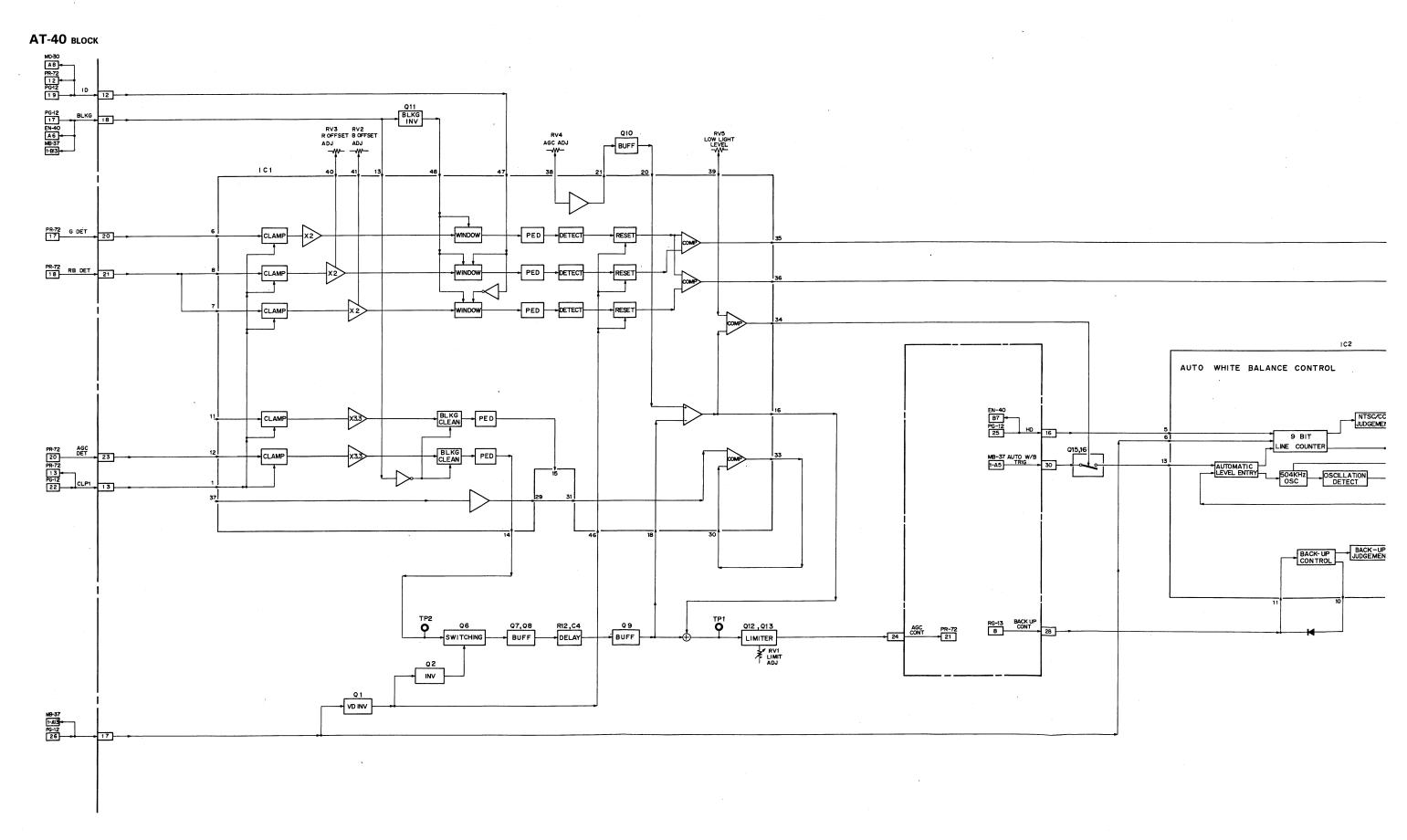
5-15

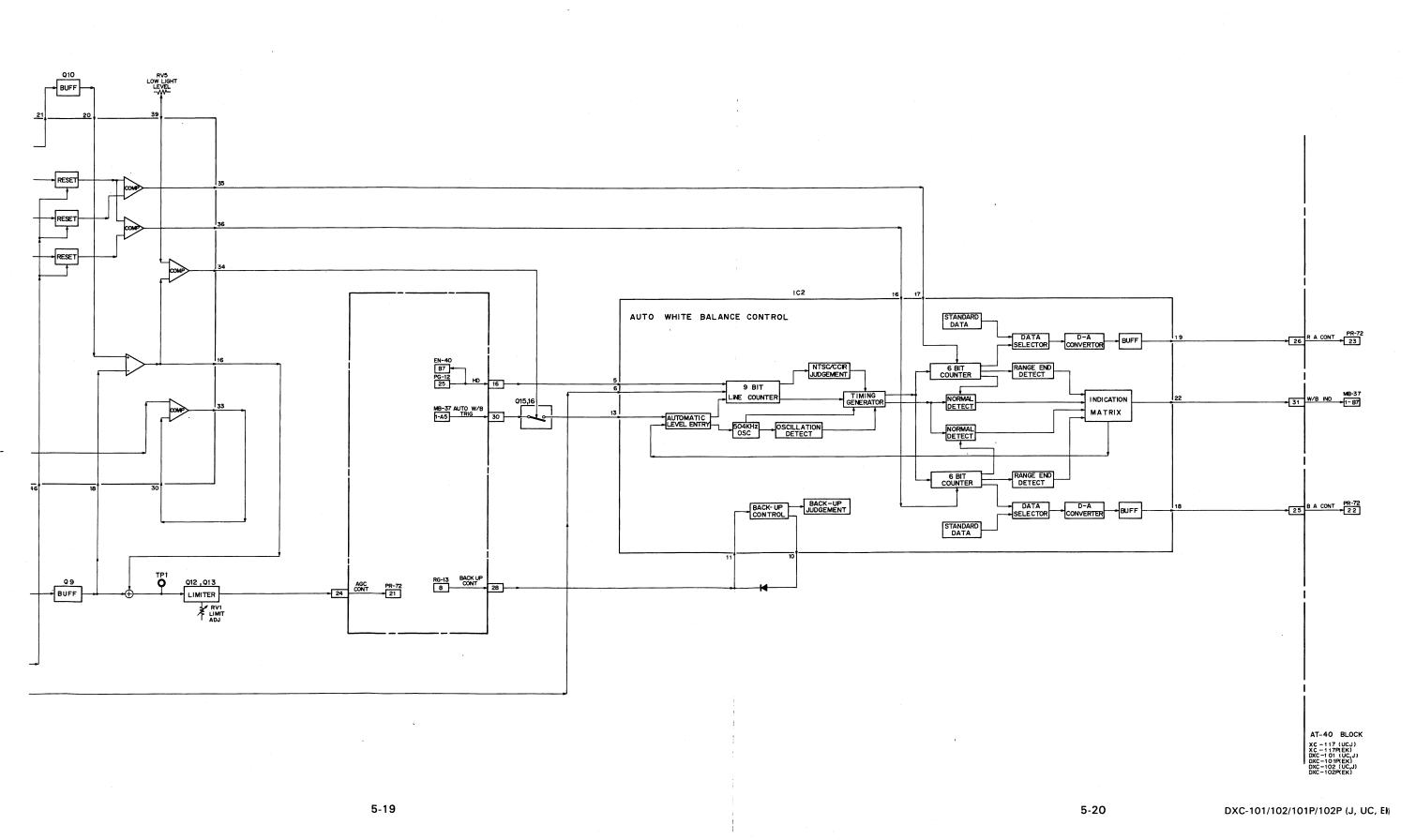
5-16

)2/102P





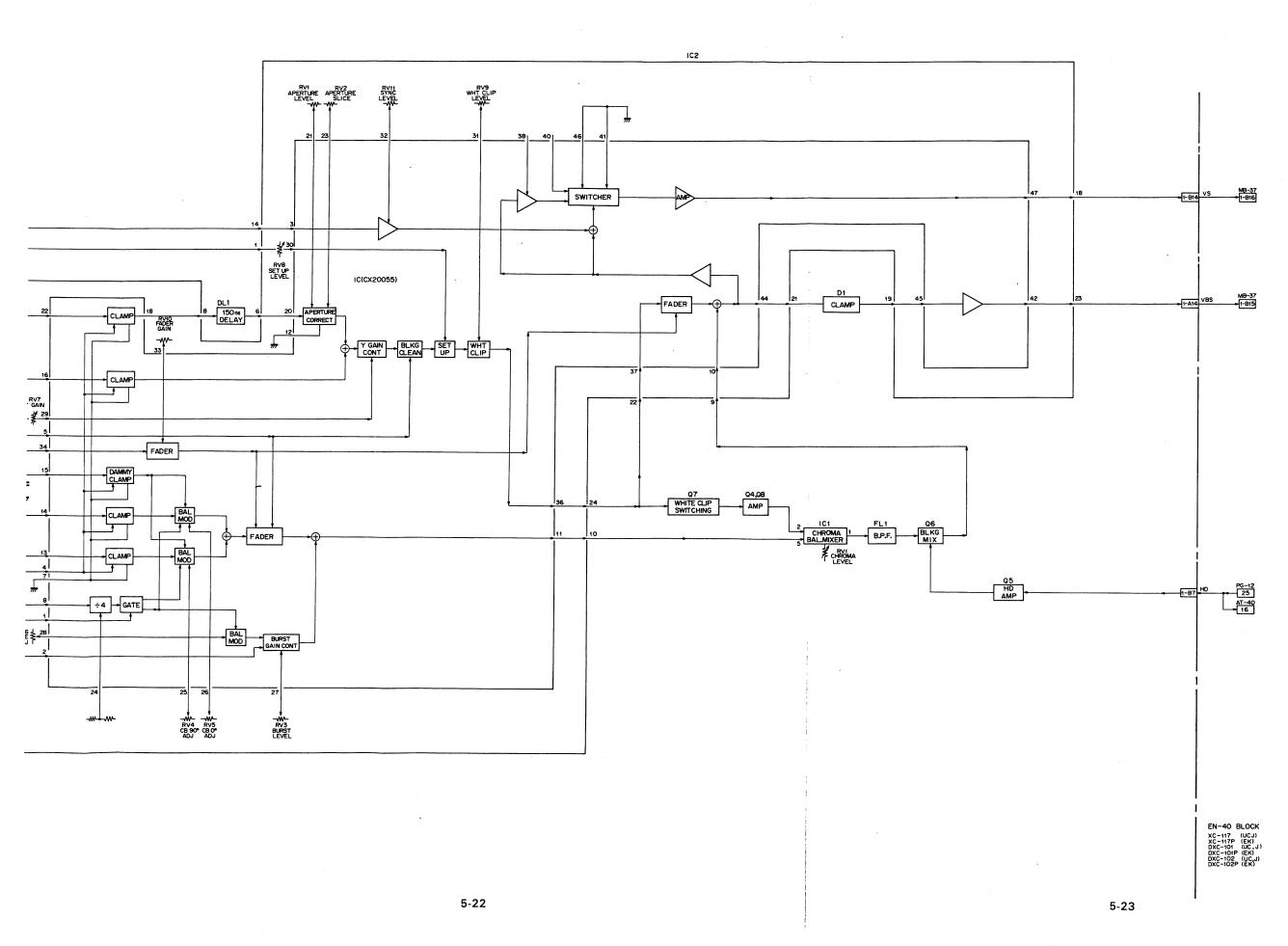


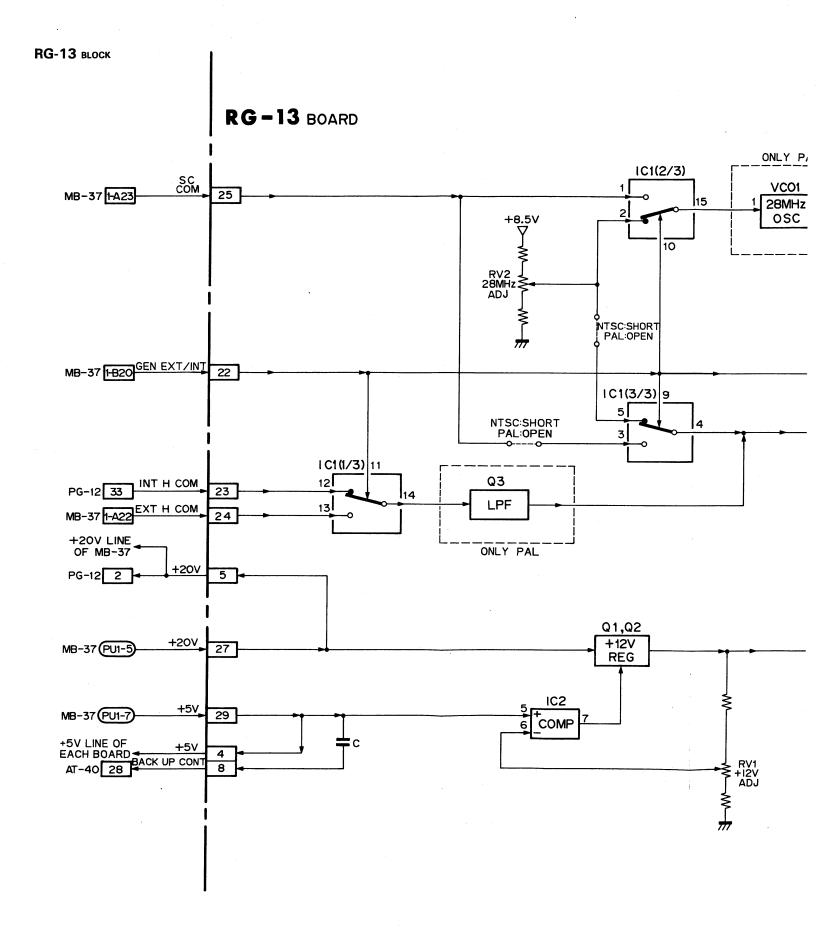


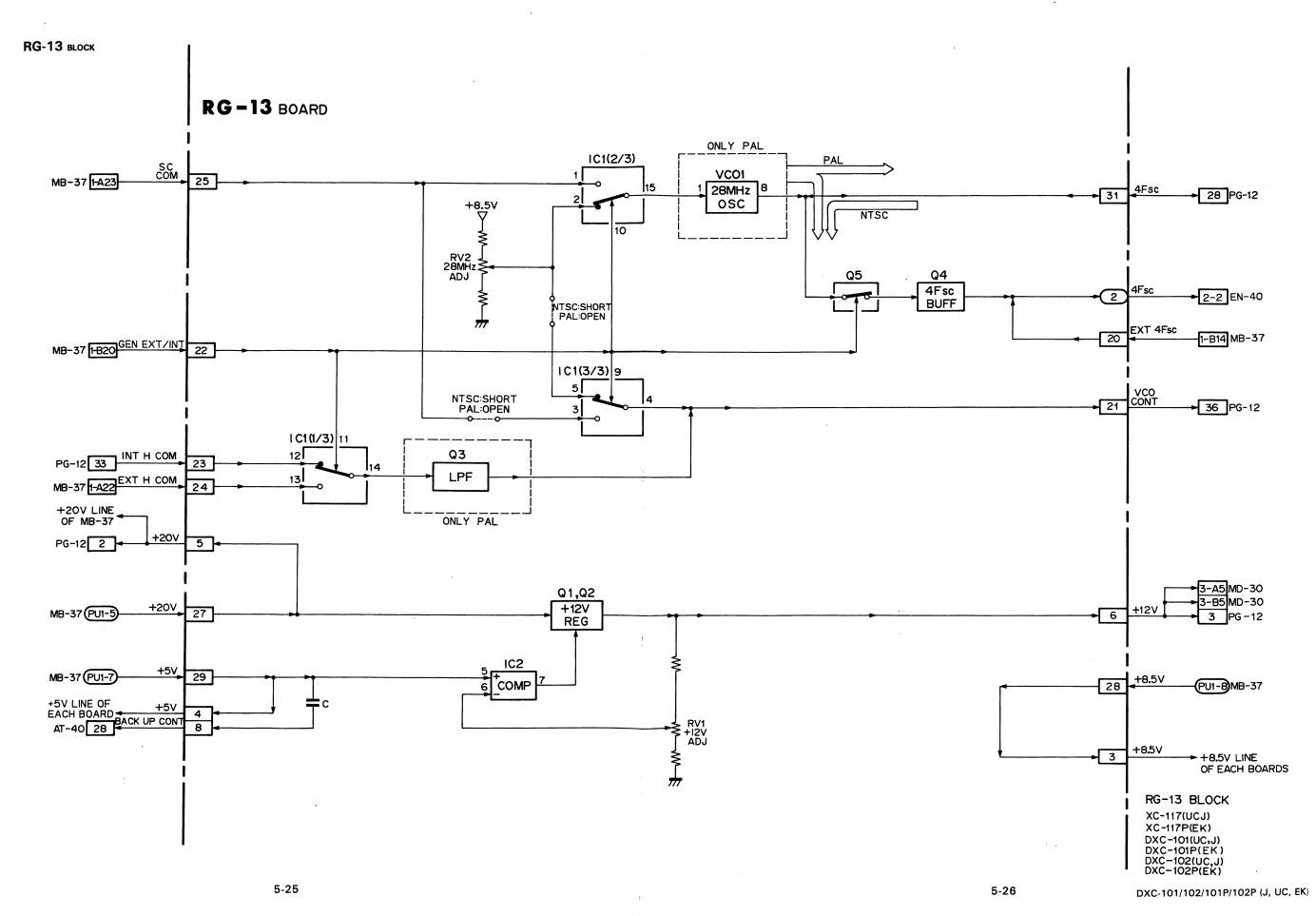
5-22

DXC-101/102/101P/102P (J, UC, EK)

5-21



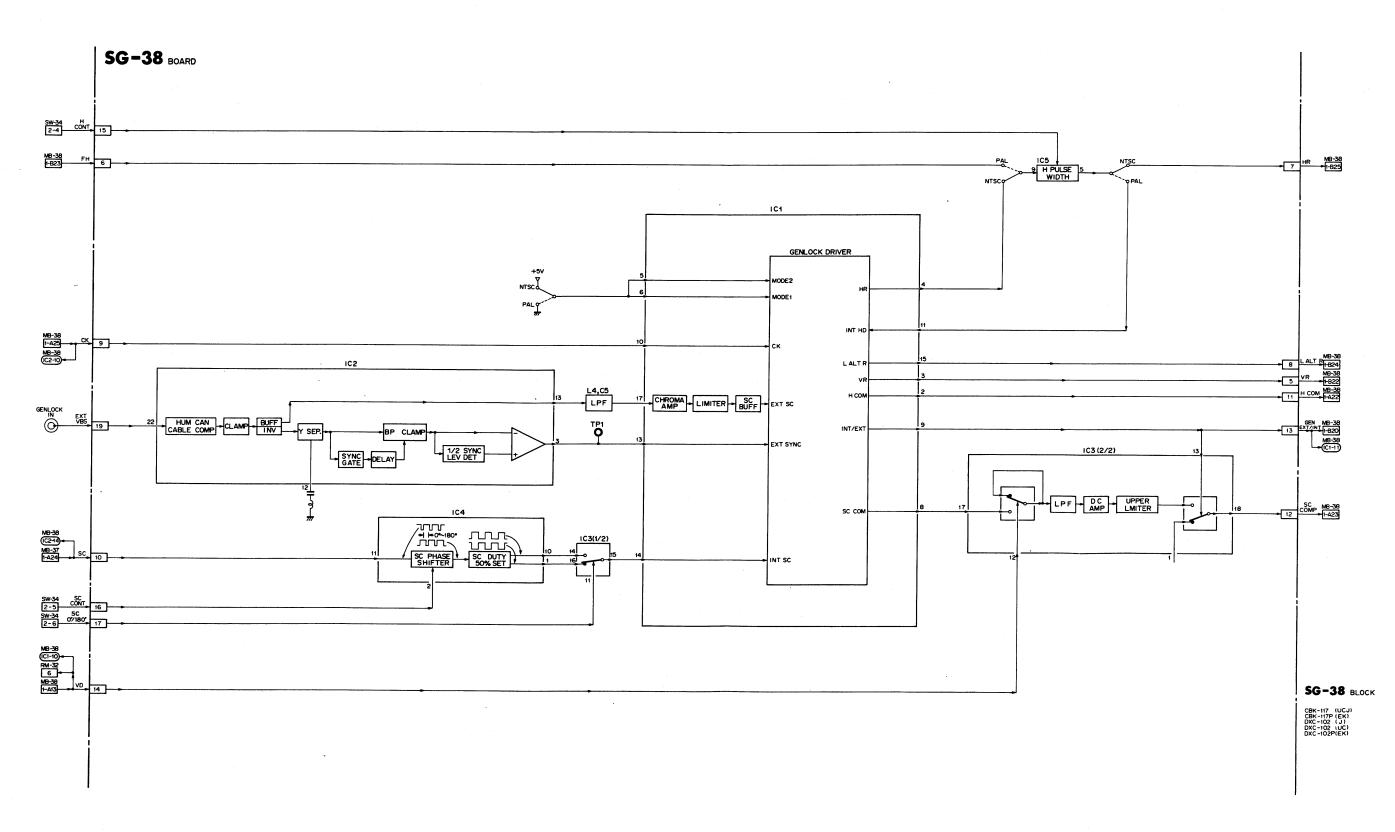




V03121 / Druck 18

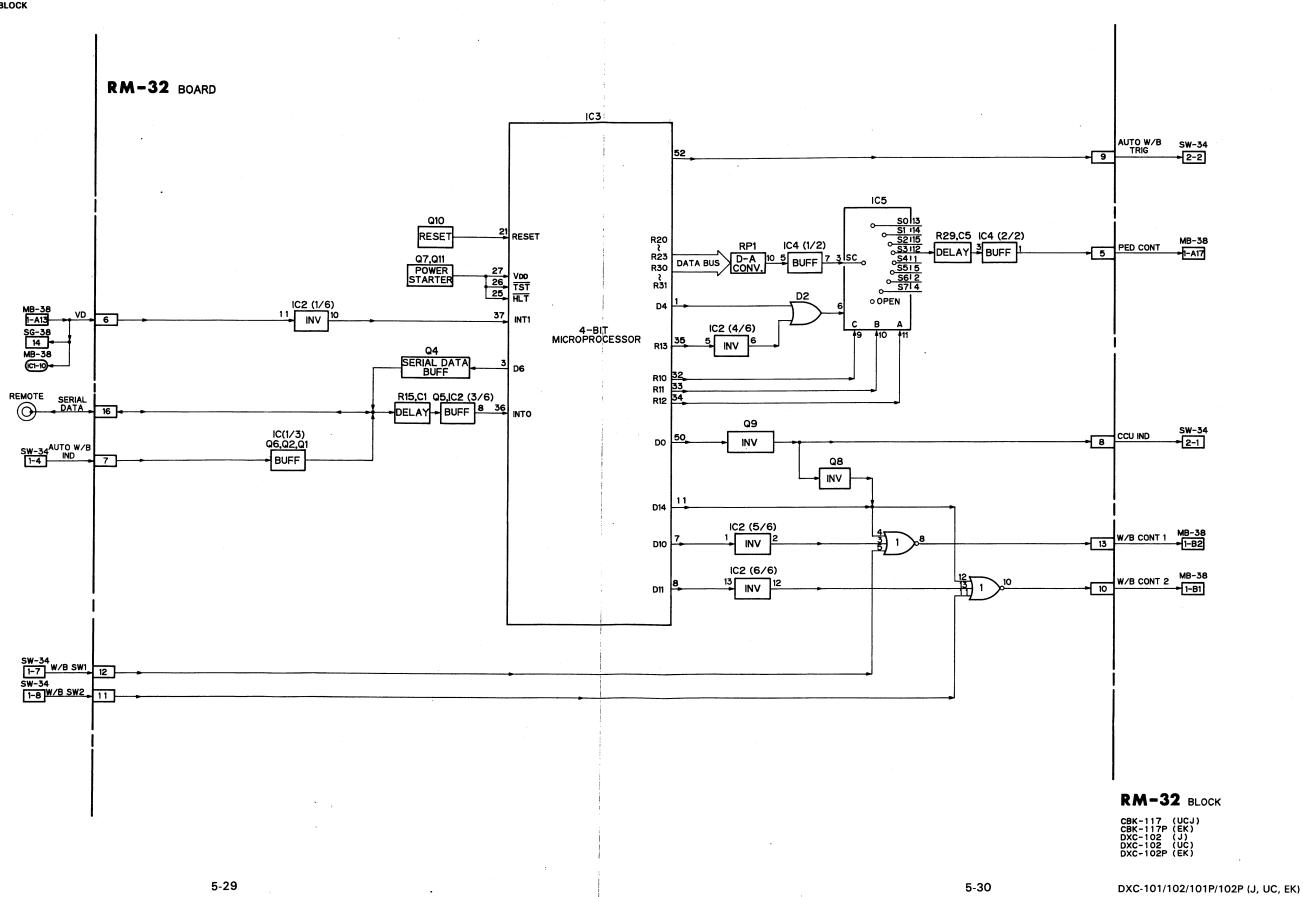
SG-38 B/D DXC-102/102P DXC-102/102P SG-38 B/D

SG-38 BLOCK



DXC-101/102/101P/102P (J, UC, EK)

RM-32 BLOCK



SECTION6

SCHEMATIC AND MOUNTING DIAGRAM

PG-12 BOARD

SERIAL NO.

DXC-101 (J) Up to 51290

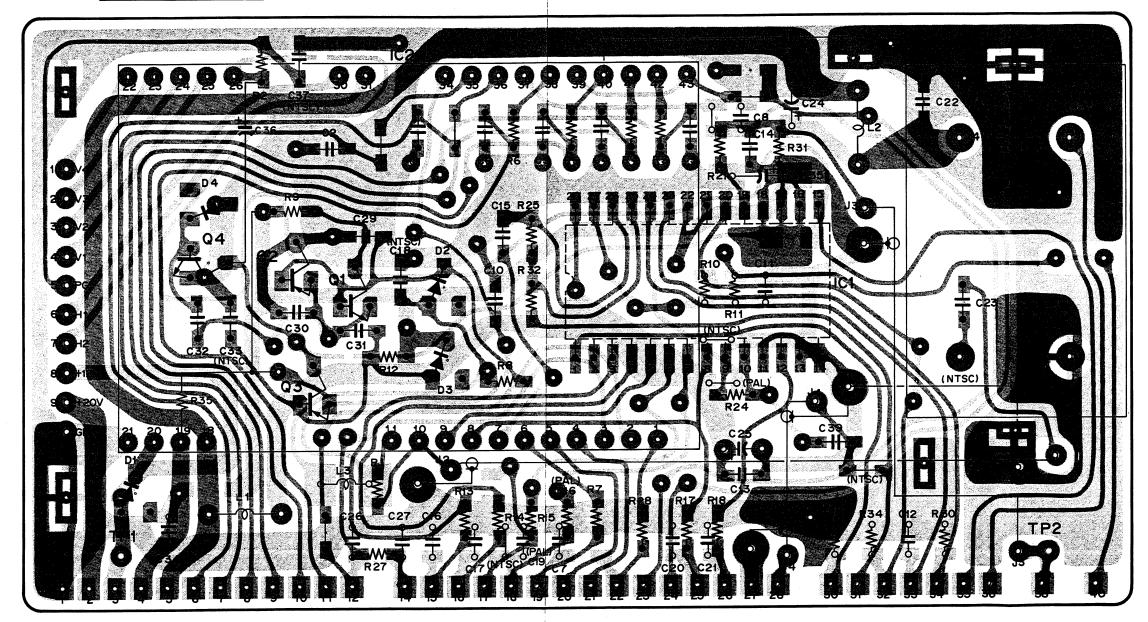
DXC-101 (UC) Up to 11180

DXC-101P (EK) Up to 12080

DXC-102 (J) Up to 10470

DXC-102 (UC) Up to 10660

DXC-102P (EK) Up to 11070



- SOLDERING SIDE-

PG-12 BOARD

1-617-210-11

XC -117 (UCJ) XC -117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK)

6-4(a)

PG-12

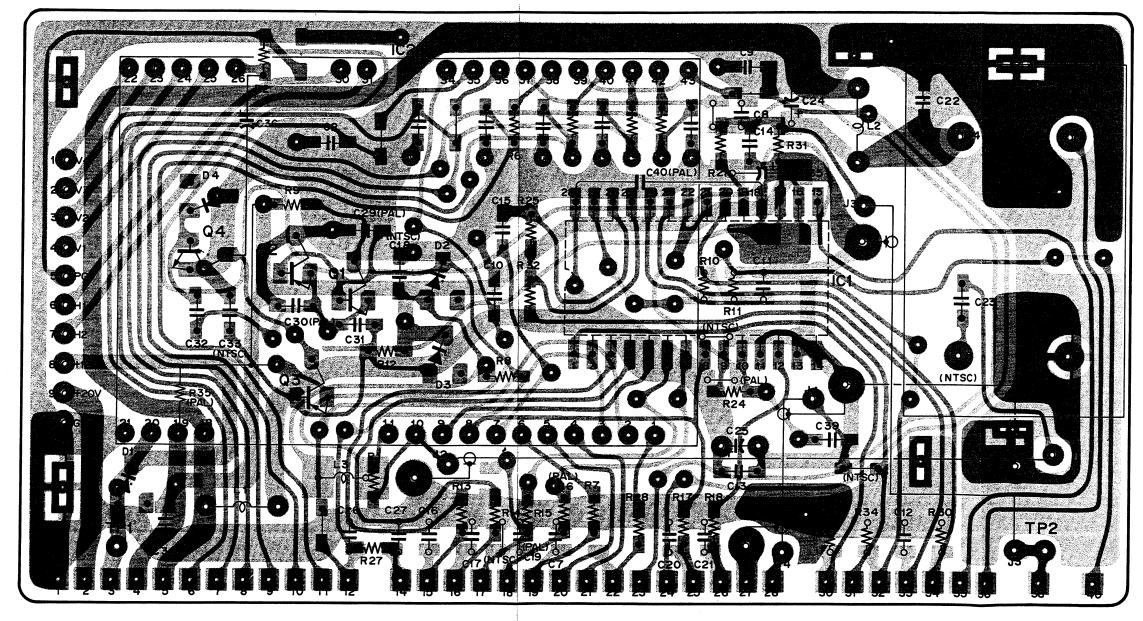
DXC-101/102/101P/102P (J, UC, EK)

PG-12 BOARD

SERIAL NO.

DXC-101 (J) 51291 and higher

DXC-101 (UC) 11181 and higher DXC-101P (EK) 12081 and higher DXC-102 (J) 10471 and higher DXC-102 (UC) 10661 and higher DXC-102P (EK) 11071 and higher



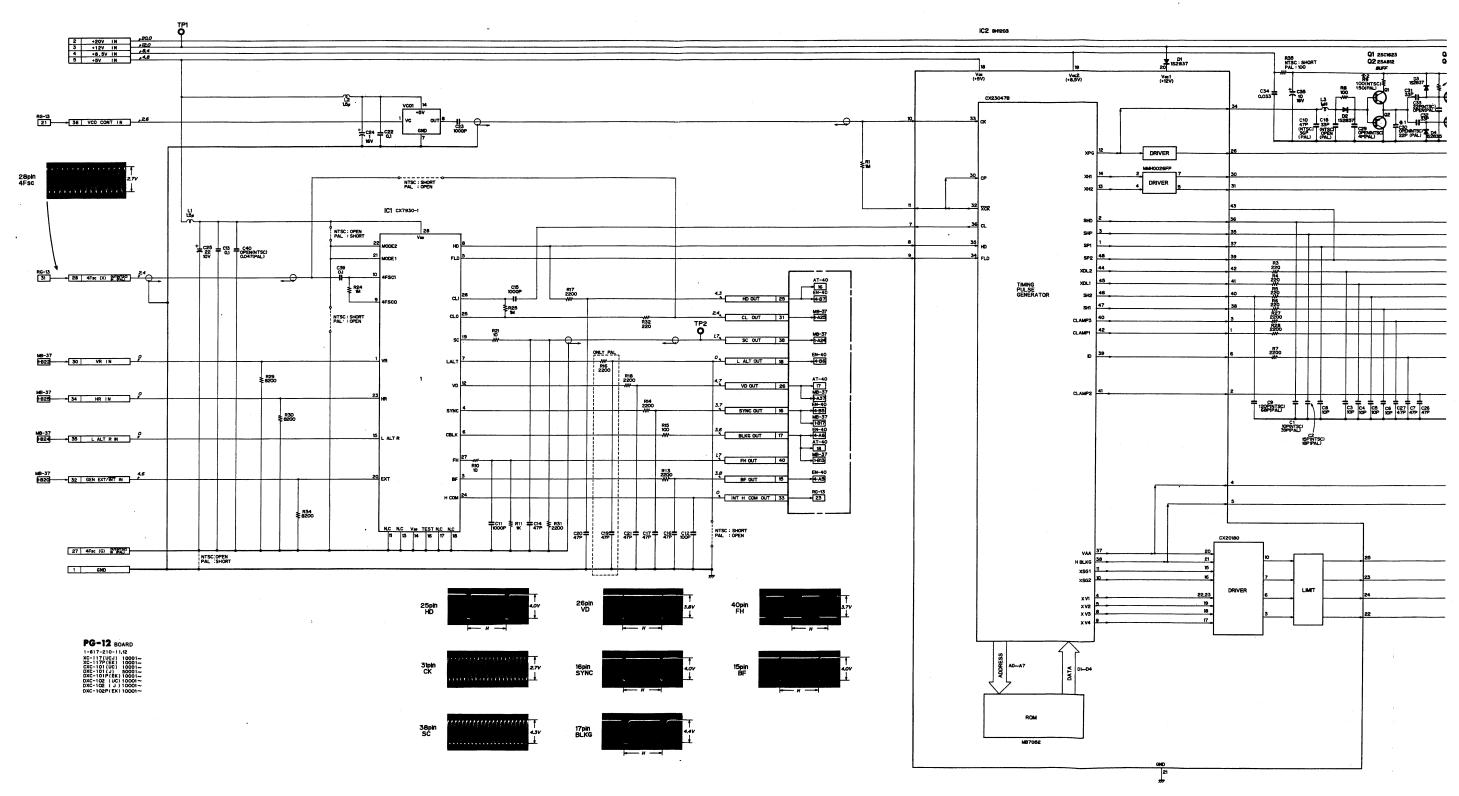
- SOLDERING SIDE-

PG-12 BOARD

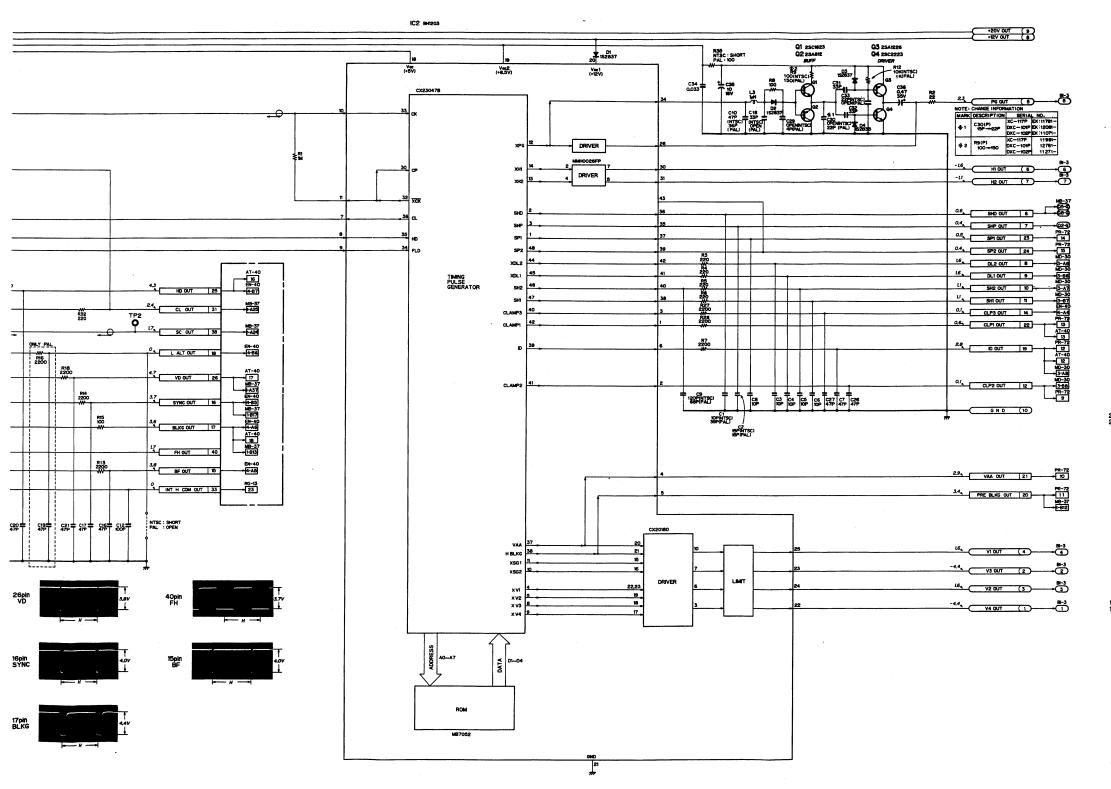
1-617-210-12

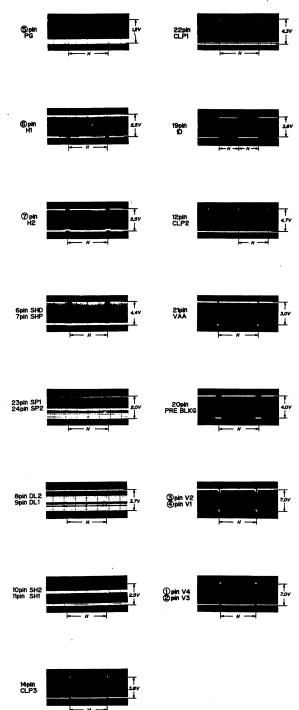
XC -117 (UCJ)
XC -117P (EK)
DXC -101 (UC,J)
DXC -101P (EK)
DXC - 102 (UC,J)

6-4(b)
DXC - 102P (EK)
DXC-101/102/101P/102P (J, UC, EK)



02/102P





注意

DC電圧はデジタル電圧計にて測定。

NOTE:

All voltage are mesured with a digital voltmeter (input resistance 10 $M\Omega$).

PR-72 BOARD

SERIAL NO.

DXC-101 (J) Up to 50430

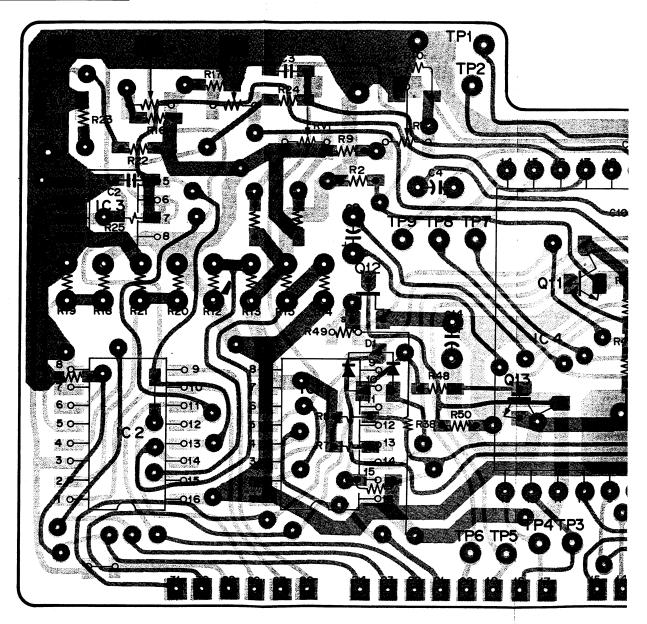
DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10260

DXC-102 (J) Up to 10190

DXC-102 (UC) Up to 10180

DXC-102P (EK) Up to 10310



PR-72 DXC-101/101P/102/102P DXC-101/101P/102/102P PR-72

PR-72 BOARD

SERIAL NO.

DXC-101 (J) Up to 50430

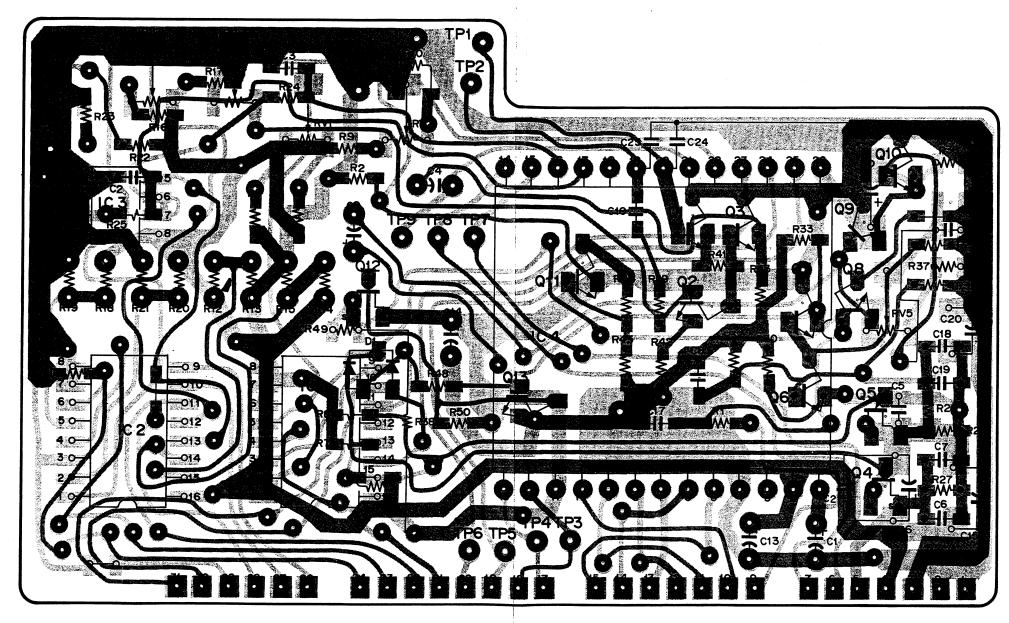
DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10260

DXC-102 (J) Up to 10190

DXC-102 (UC) Up to 10180

DXC-102P (EK) Up to 10310



- SOLDERING SIDE-

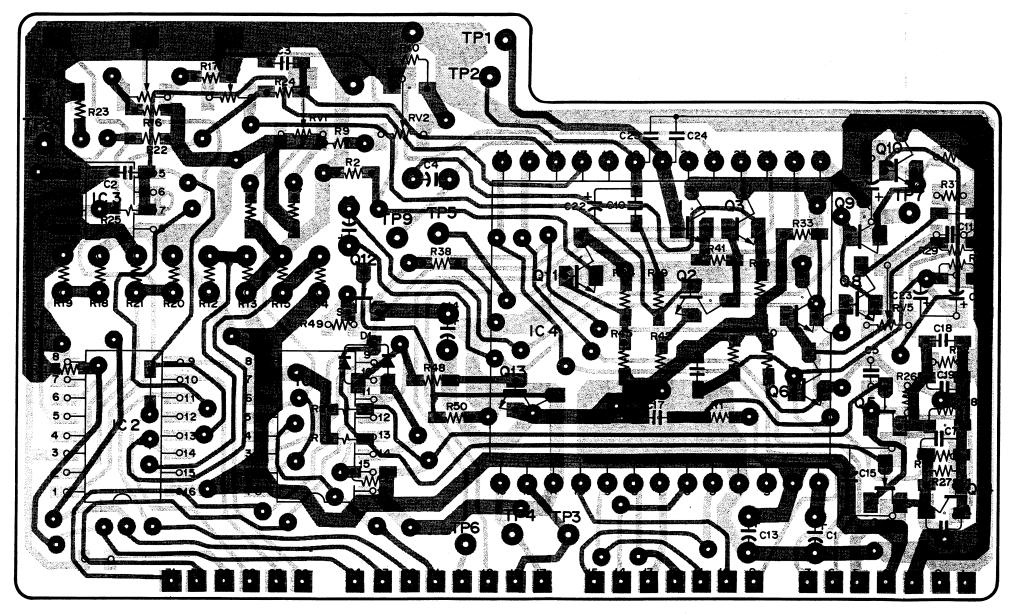
PR-72 BOARD

1-617-214-11

XC - 117 (UCJ) XC - 117P (EK) DXC - 101 (UC, J) DXC - 101P (EK) DXC - 102 (UC,J) DXC - 102P (EK) PR-72 BOARD

SERIAL NO.
DXC-101 (J) 50431 to 50790
DXC-101 (UC) 10221 to 10830
DXC-101P (EK) 10261 to 11080
DXC-102 (J) 10191 to 10380
DXC-102 (UC) 10181 to 10610
DXC-102P (EK) 10311 to 10920

PR-72



- SOLDERING SIDE-

PR-72 BOARD

1-617-214-12

XC - 117 (UCJ) XC - 117P (EK) DXC - 101 (UC, J) DXC - 101P (EK) DXC - 102P (EK) PR-72 DXC-101/101P/102/102P DXC-101/101P/102/102P PR-72

PR-72 BOARD

SERIAL NO.

DXC-101 (J) 50791 and higher

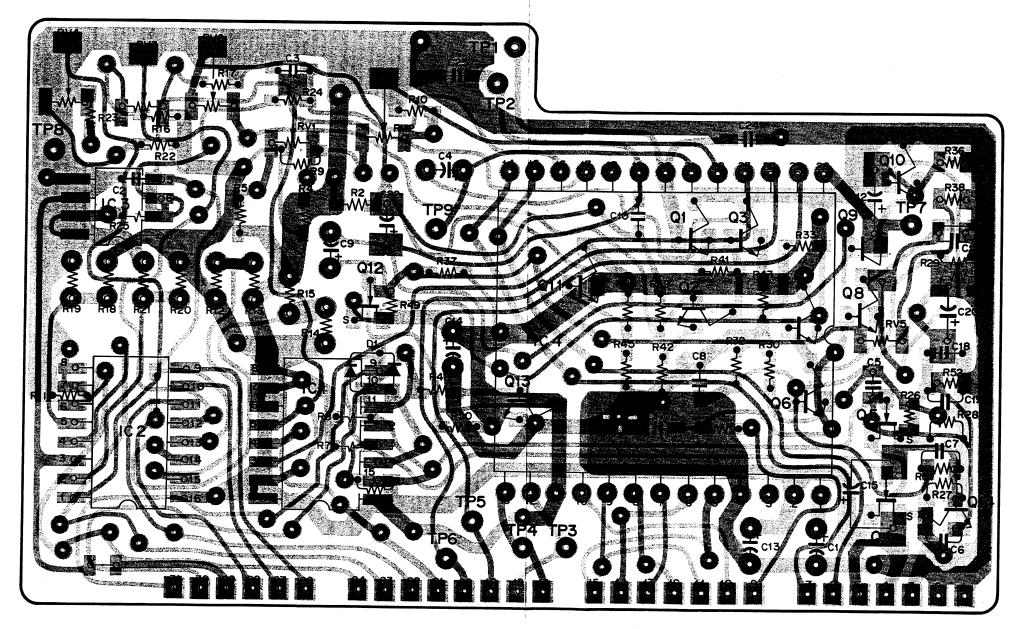
DXC-101 (UC) 10831 and higher

DXC-101P (EK) 11081 and higher

DXC-102 (J) 10381 and higher

DXC-102 (UC) 10611 and higher

DXC-102P (EK) 10921 and higher

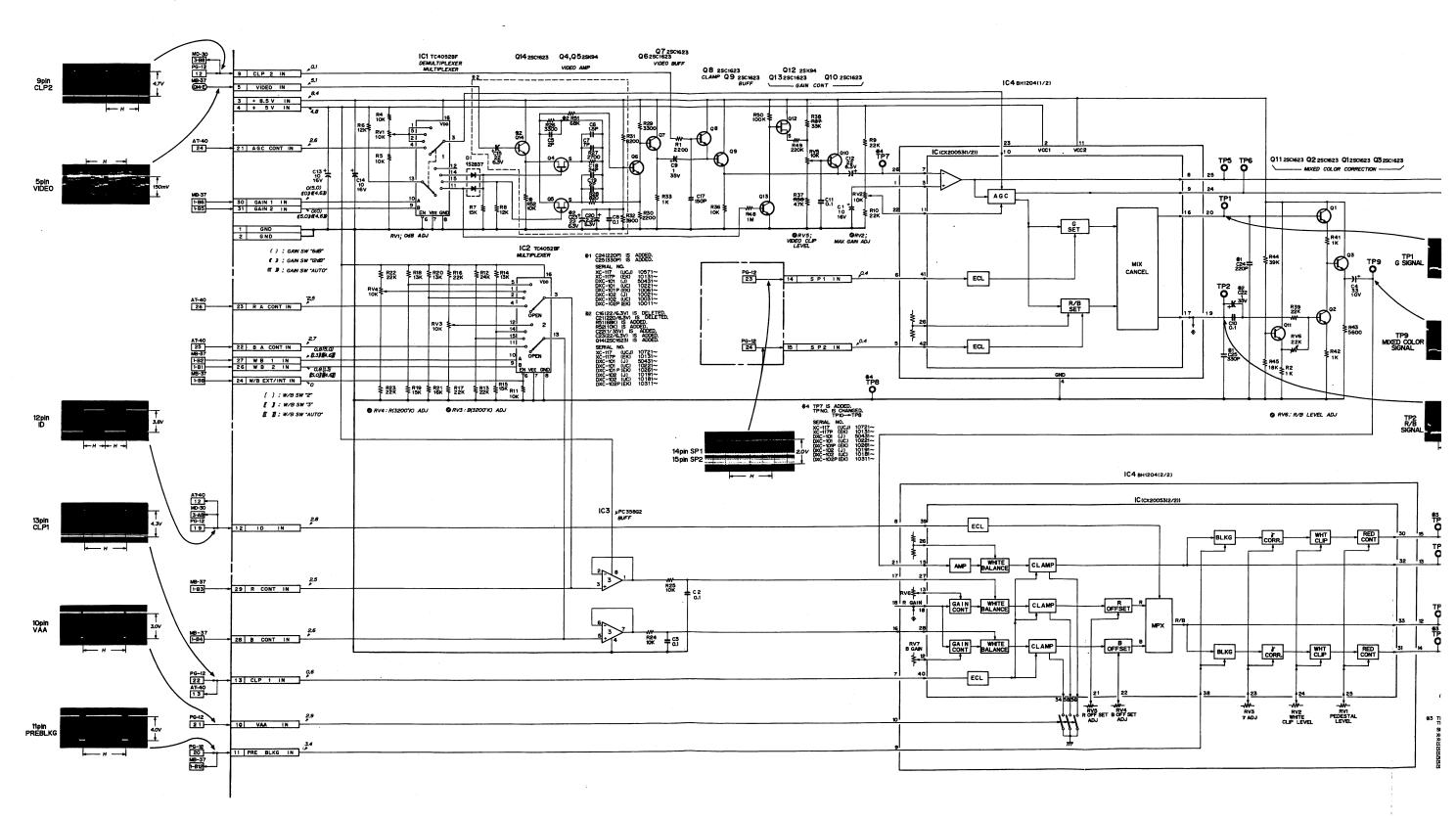


- SOLDERING SIDE-

PR-72 BOARD

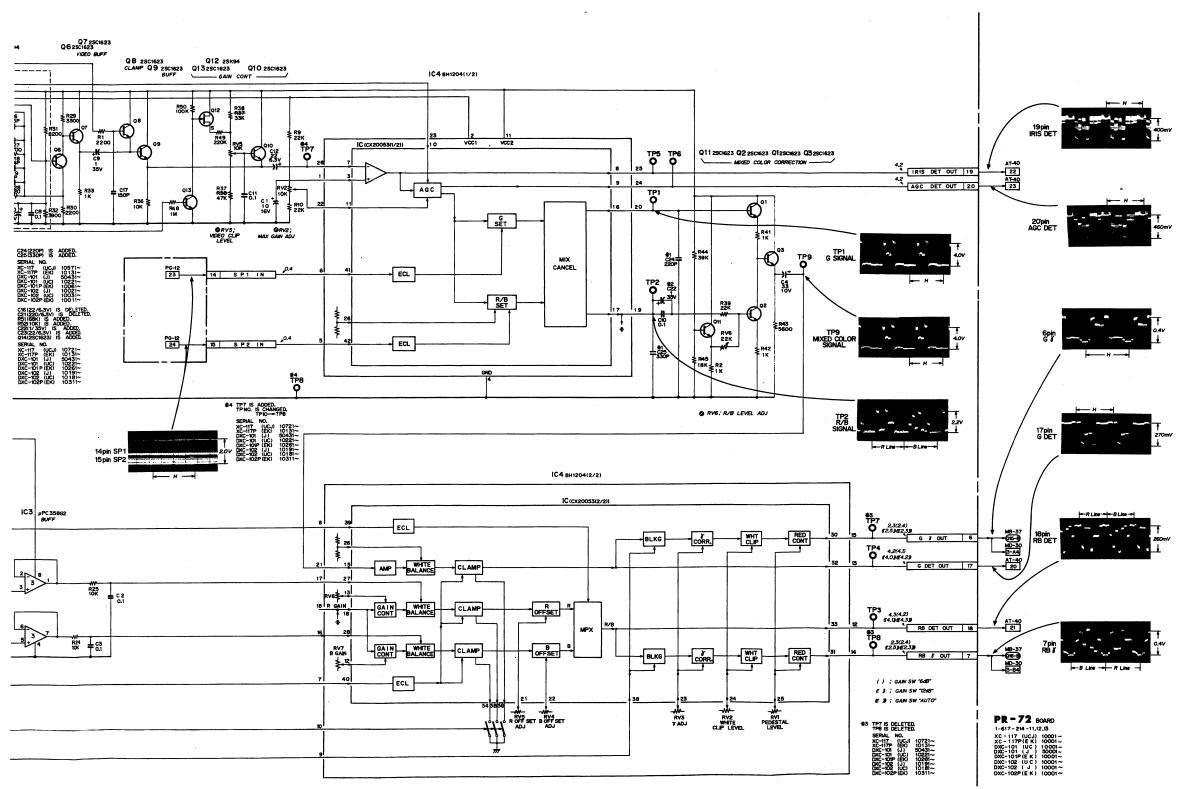
1-617-214-13

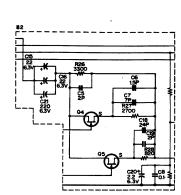
XC - 117 (UCJ) XC - 117P (EK) DXC - 101 (UC, J) DXC - 101P (EK) DXC - 102 (UC, J) DXC - 102P (EK)



02/102P

PR-72





- 1. DC電圧はデジタル電圧計による値。
- 2. 波形写真は下記条件で撮影。
 - ●MB-37基板, TP1にてカラーバーの白部分が150mVp-p に なる様レンズアイリスをセットする。 (F≒4, 波形モニターで100IRE)
 - ●WHITE BALスイッチ→ *1(3200°K) ″位置
 - ●GAINスイッチ→"0dB"位置

NOTE:

- 1. All voltage are dc, measured with a digital voltmeter (input resistance 10 MΩ).
- 2. All waveforms are taken in conditions below.
 - Shoot the color bar pattern on the pattern box. Adjust lens iris so that a white level at TP1/MB-37 board is 150 mV. [F≒4, White level on the waveform monitor is 100 IRE (700 mV for PAL)]
 - Set camera WHITE BAL switch to "1 (3200° K)".
 - Set camera GAIN switch to "O dB".

MD-30 BOARD

SERIAL NO.

DXC-101 (J) Up to 50180

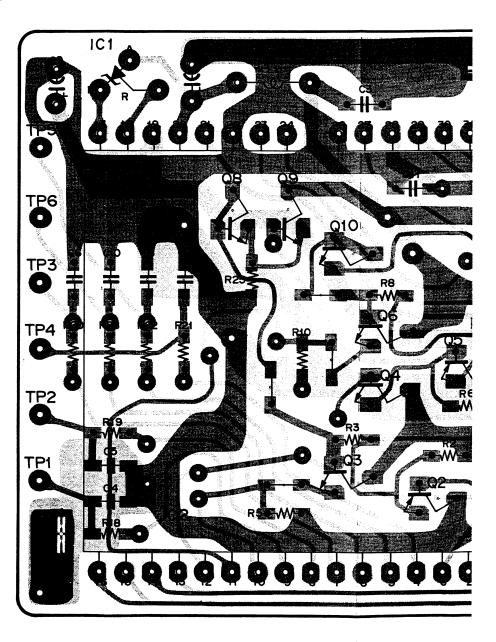
DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10060

DXC-102 (J) Up to 10020

DXC-102 (UC) Up to 10030

DXC-102P (EK) Up to 10010



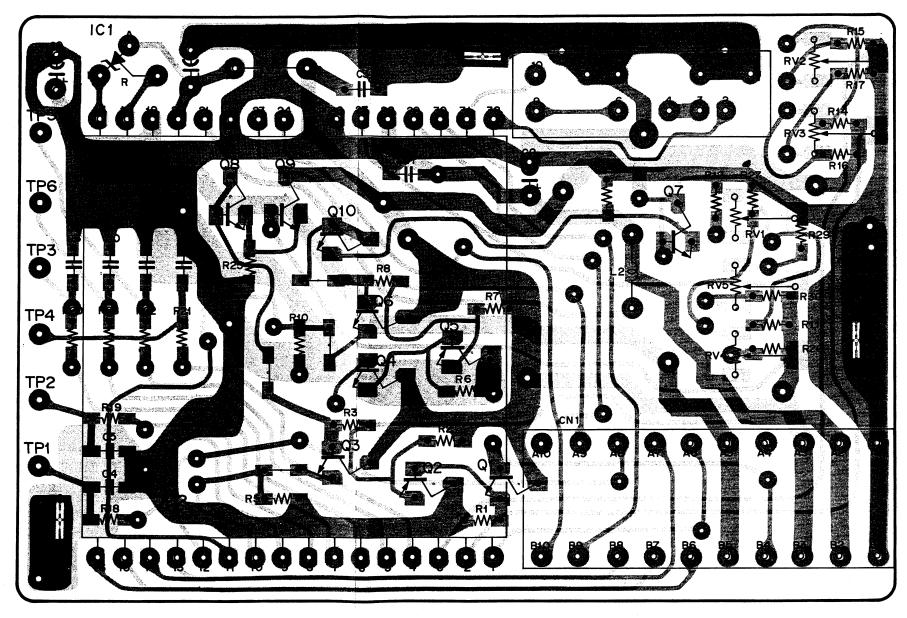
MD-30

DXC-101/101P/102/102P DXC-101/101P/102/102P

MD-30

MD-30 BOARD

SERIAL NO. DXC-101 (J) Up to 50180 DXC-101 (UC) Up to 10220 DXC-101P (EK) Up to 10060 DXC-102 (J) Up to 10020 DXC-102 (UC) Up to 10030 DXC-102P (EK) Up to 10010

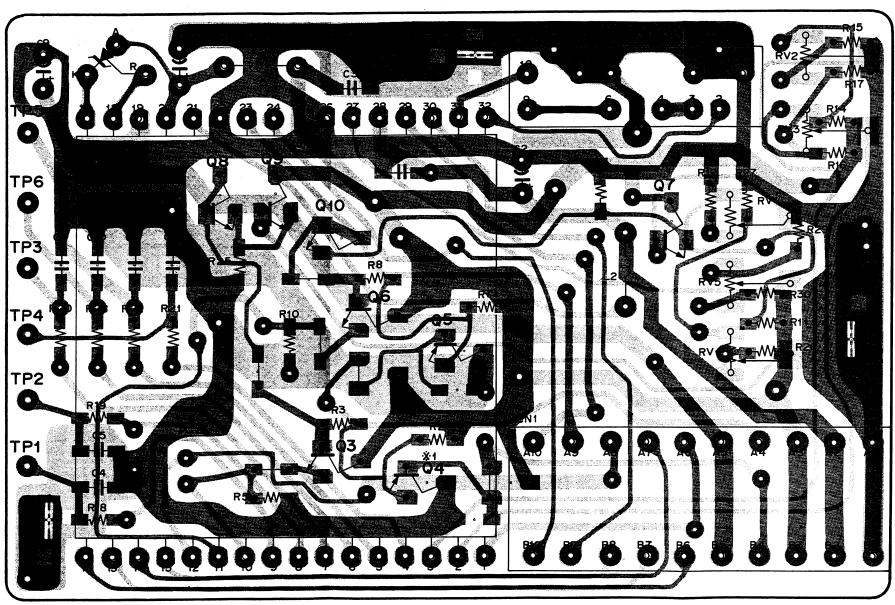


-SOLDERING SIDE-

MD-30 BOARD

1-617-212-11 XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) MD-30 BOARD

SERIAL NO. DXC-101 (J) 50181 to 51290 DXC-101 (UC) 10221 to 11180 DXC-101P (EK) 10061 to 12080 DXC-102 (J) 10021 to 10470 DXC-102 (UC) 10031 to 10660 DXC-102P (EK) 10011 to 11070



%1 QNO IS CHANGED Q2 → Q4

Q2 → Q4 SER. NO. XC-117 (UCJ) 10721~ XC-101 (EK) 10131~ DXC-101 (UC) 10221~ DXC-101(EK) 10261~ DXC-102 (J) 10191~ DXC-102 (UC) 10181~ DXC-102P(EK) 10311~

- SOLDERING SIDE-

MD - 30 BOARD

1-617-212-12

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK)

MD-30 BOARD

SERIAL NO.

DXC-101 (J) 51291 and higher

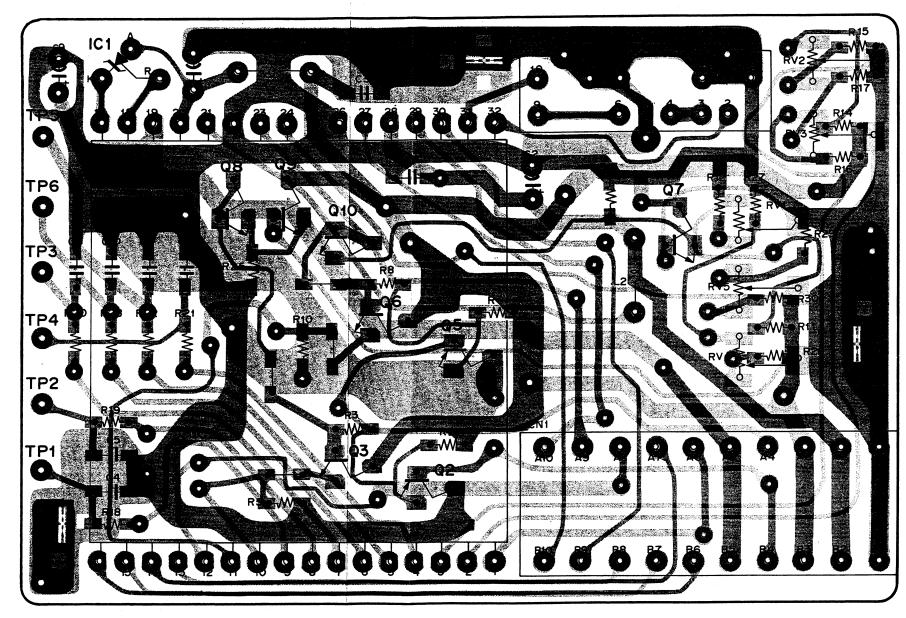
DXC-101 (UC) 11181 and higher

DXC-101P (EK) 12081 and higher

DXC-102 (J) 10471 and higher

DXC-102 (UC) 10661 and higher

DXC-102P (EK) 11071 and higher

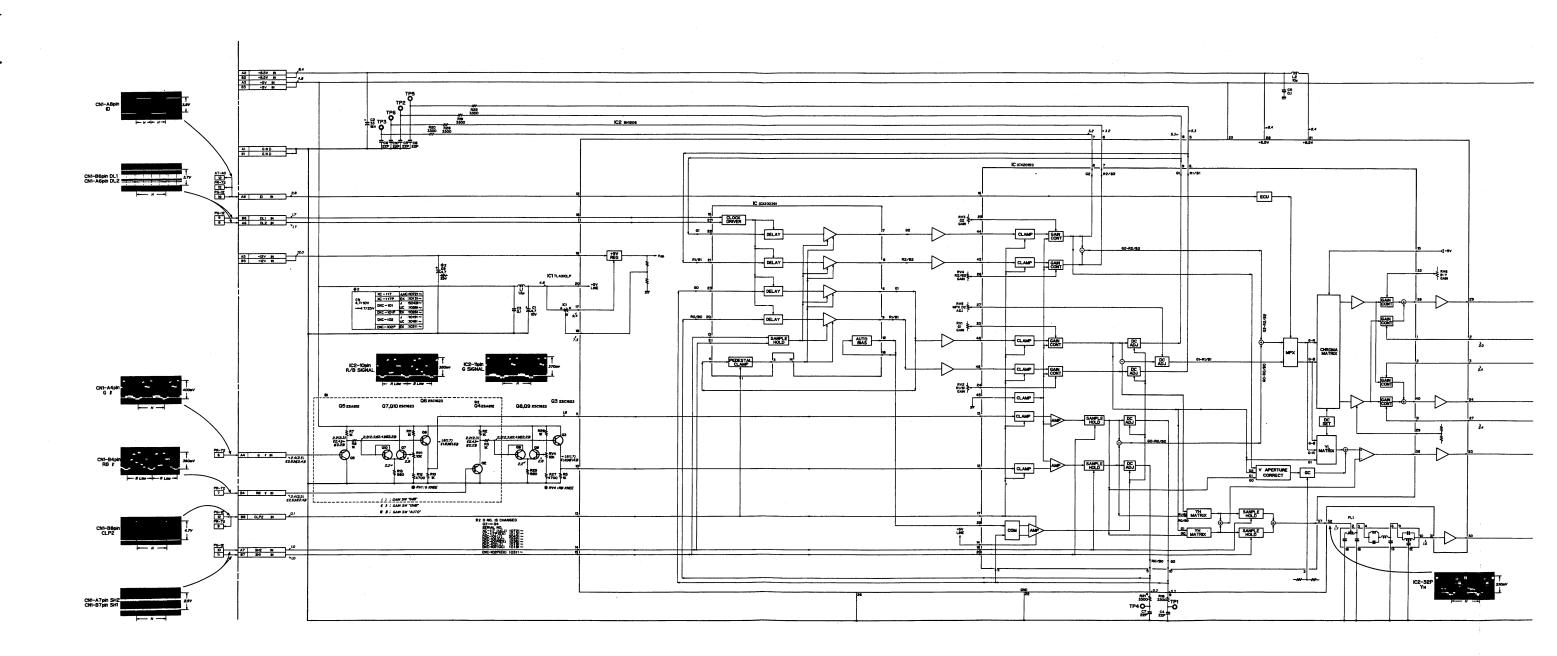


- SOLDERING SIDE-

MD-30 BOARD

1-617-212-13

XC -117 (UCJ) XC -117P (EK) DXC-101 (UC, J) DXC-101P (EK) DXC-102 (UC, J) DXC-102P (EK)



DXC-101/102/101P/102P (J, UC, EK)

6-17

6-18

DXC-101/101P/102/102P

02/102P

注意:

- 1. DC電圧はデジタル電圧計による値。
- 2. 波形写真は下記条件で撮影。
 - ●MB-37基板, TP1にてカラーバーの口部分が150mVp-pに なる様レンズアイリスをセットする。 (F≒4, 波形モニターで100IRE)
 - ●WHITE BALスイッチ→"1(3200°K)"位置
 - ●GAINスイッチ→"0dB"位置

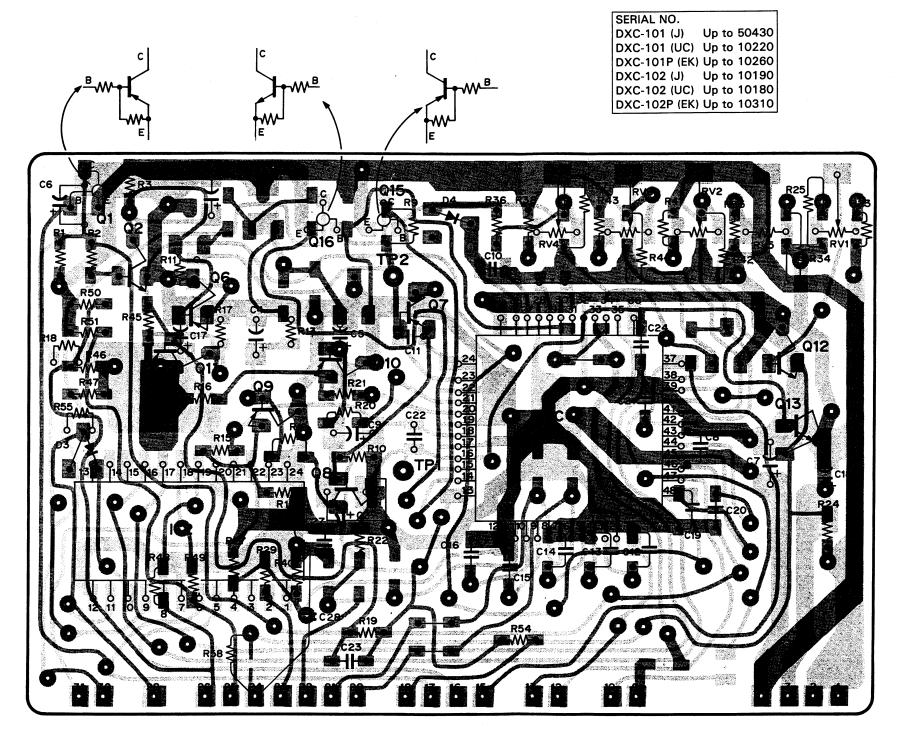
NOTE:

- 1. All voltage are dc, measured with a digital voltmeter (input resistance 10 MΩ).
- 2. All waveforms are taken in conditions below.
 - Shoot the color bar pattern on the pattern box. Adjust lens iris so that a white level at TP1/MB-37 board is 150 mV. [F≒4, White level on the waveform monitor is 100 IRE (700 mV for PAL)]
 - Set camera WHITE BAL switch to "1 (3200° K)".
 - Set camera GAIN switch to "0 dB".

6-18

6-19

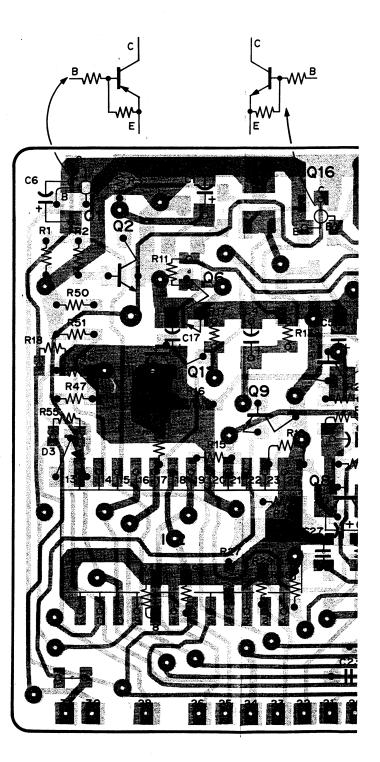
AT-40 BOARD





AT-40 BOARD

1-617-213-11 XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK)



SERIAL NO.

DXC-101 (J) Up to 50430

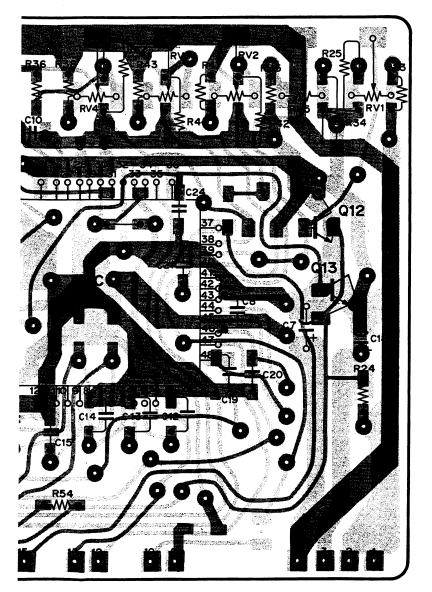
DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10260

DXC-102 (J) Up to 10190

DXC-102 (UC) Up to 10180

DXC-102P (EK) Up to 10310

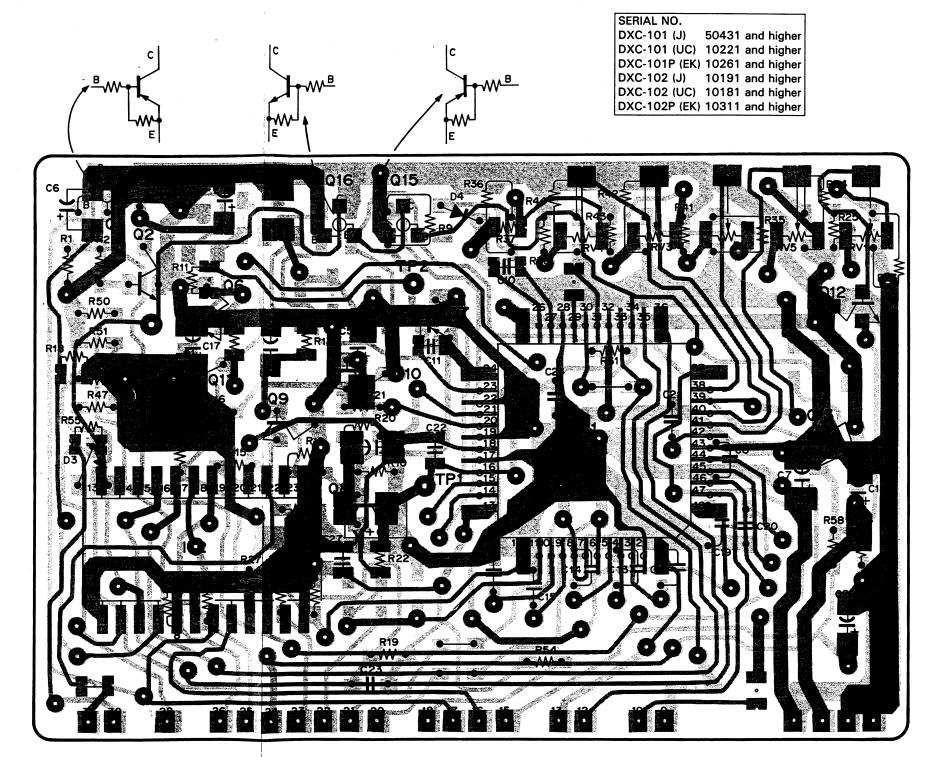


-SOLDERING SIDE-

AT-40 BOARD

1-617-213-11

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK)



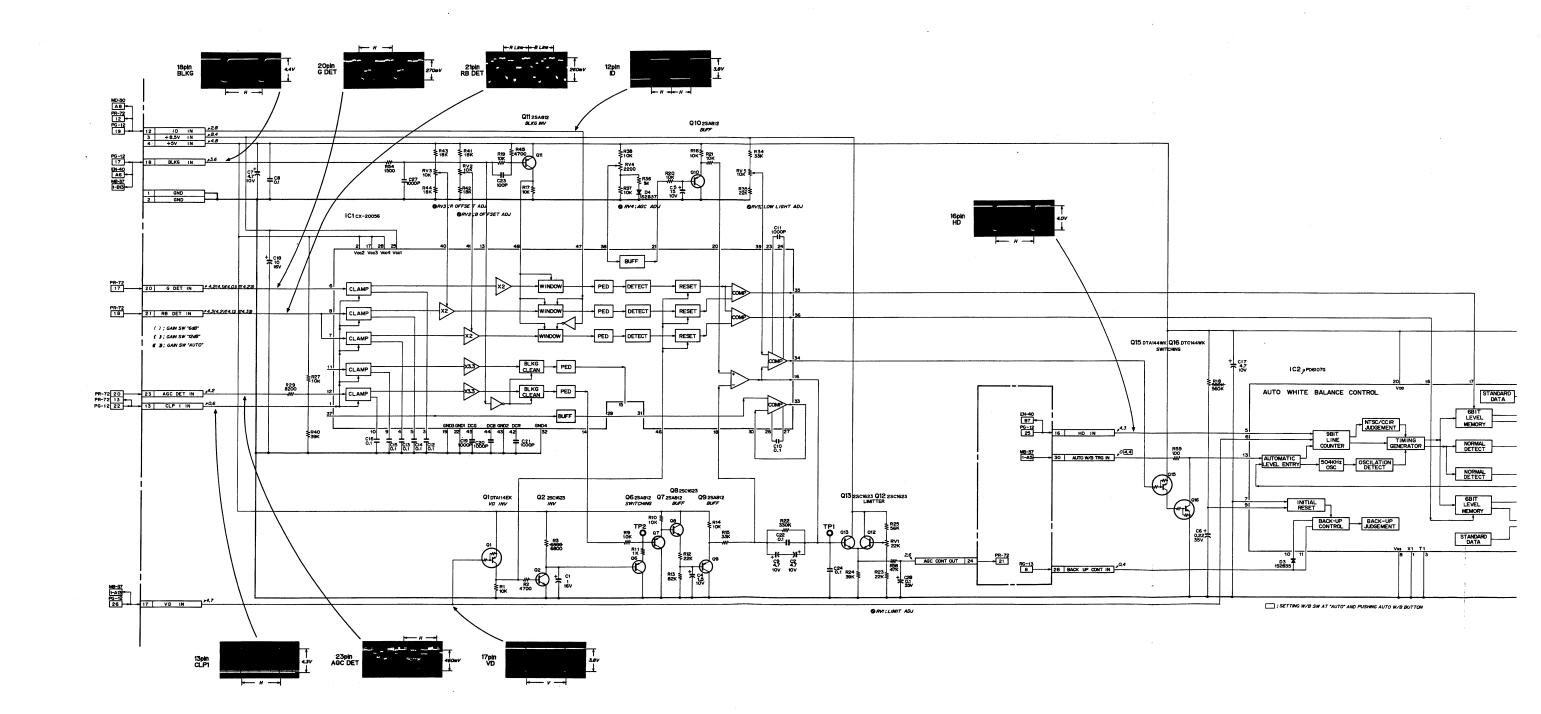
-SOLDERING SIDE-

AT-40 BOARD

1-617-213-12

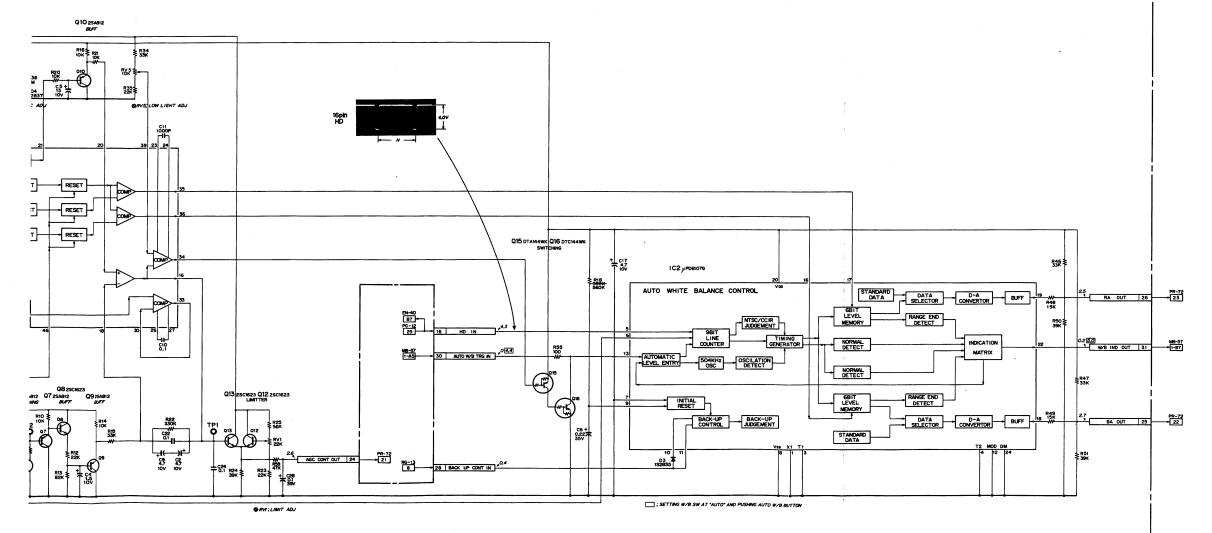
XC-117 (UCJ)
XC-117P (EK)
DXC-101 (UC,J)
DXC-101P (EK)
DXC-102 (UC,J)
DXC-102P (EK)

AT-40 BOARD (AUTO CONTROL)



AT-40





: 意:

- 1. DC電圧はデジタル電圧計による値。
- 2. 波形写真は下記条件で撮影。
- ●MB-37基板, TP1にてカラーバーの自部分が150mVp-pになる様レンズアイリスをセットする。 (F≒4, 波形モニターで100IRE)
- ●WHITE BALスイッチ→"1(3200°K)"位置
- ●GAINスイッチ→"0dB"位置

NOTE:

- 1. All voltage are dc, measured with a digital voltmeter (input resistance 10 $M\Omega).$
- 2. All waveforms are taken in conditions below.
- Shoot the color bar pattern on the pattern box.

 Adjust lens iris so that a white level at TP1/MB-37 b₂ and is

 150 mV. [F≒4, White level on the waveform molitor is

 100 IRE (700 mV for PAL)]
- Set camera WHITE BAL switch to "1 (3200° K)"
- Set camera GAIN switch to "0 dB".

AT - 40 BOARD 1-617-213-11,12 XC-117(IKCJ) 10001 ~ XC-101(UC) 10001 ~ DXC-101(UC) 10001 ~ DXC-101(UC) 10001 ~ DXC-102 4CC 10001 ~ DXC-102 4CC 10001 ~ DXC-102 (UT) 10001 ~

SERIAL NO.

DXC-101 (J) Up to 50180

DXC-101 (UC) Up to 10220

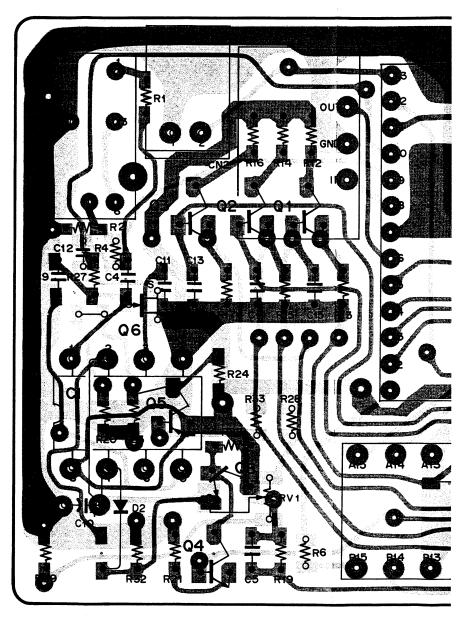
DXC-101P (EK) Up to 10060

DXC-102 (J) Up to 10020

DXC-102 (UC) Up to 10030

DXC-102P (EK) Up to 10010

EN-40 BOARD



EN-40

DXC-101/101P/102/102P

DXC-101/101P/102/102P

EN-40

EN-40 BOARD

SERIAL NO.

DXC-101 (J) Up to 50180

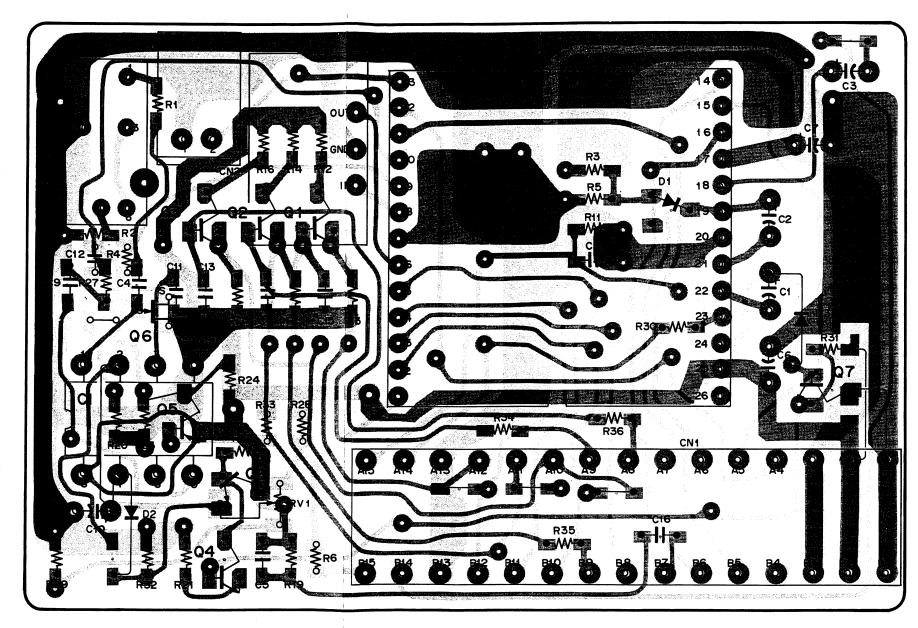
DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10060

DXC-102 (J) Up to 10020

DXC-102 (UC) Up to 10030

DXC-102P (EK) Up to 10010



-SOLDERING SIDE-

EN-40 BOARD

1-617-215-11

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK) EN-40 BOARD

SERIAL NO.

DXC-101 (J) 50181 to 51290

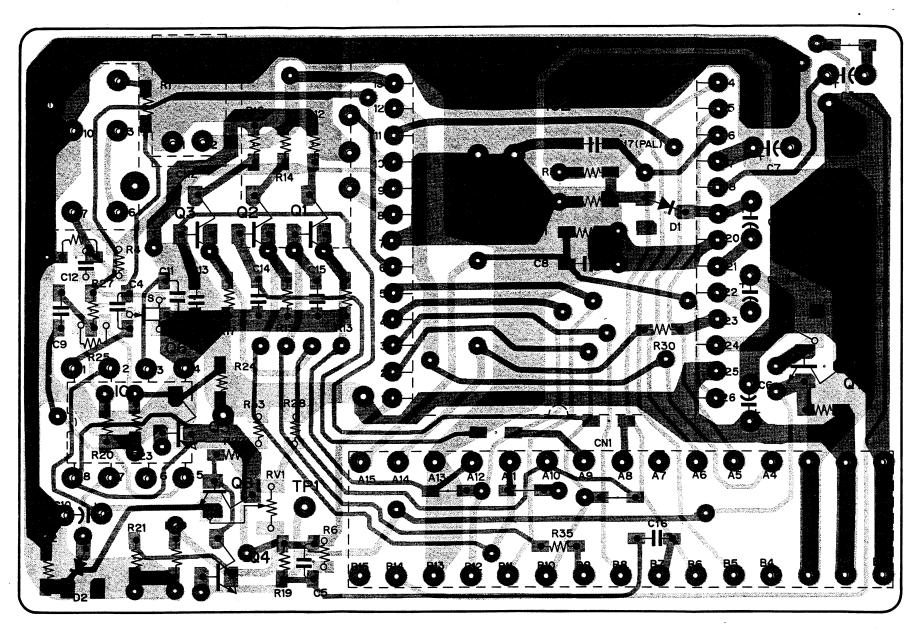
DXC-101 (UC) 10221 to 11180

DXC-101P (EK) 10061 to 12080

DXC-102 (J) 10021 to 10470

DXC-102 (UC) 10031 to 10660

DXC-102P (EK) 10011 to 11070



-SOLDERING SIDE-

EN-40 BOARD

1-617-215-13

XC -117 (UCJ) XC -117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK) EN-40 DXC-101/101P/102/102P DXC-101/101P/102/102P EN-40

EN-40 BOARD

SERIAL NO.

DXC-101 (J) 51291 and higher

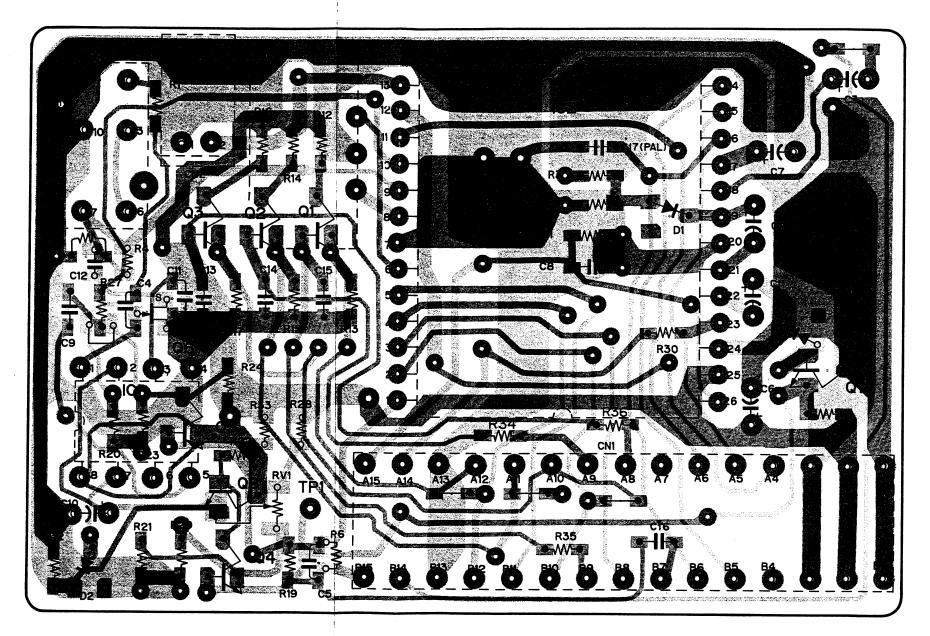
DXC-101 (UC) 11181 and higher

DXC-101P (EK) 12081 and higher

DXC-102 (J) 10471 and higher

DXC-102 (UC) 10661 and higher

DXC-102P (EK) 11071 and higher

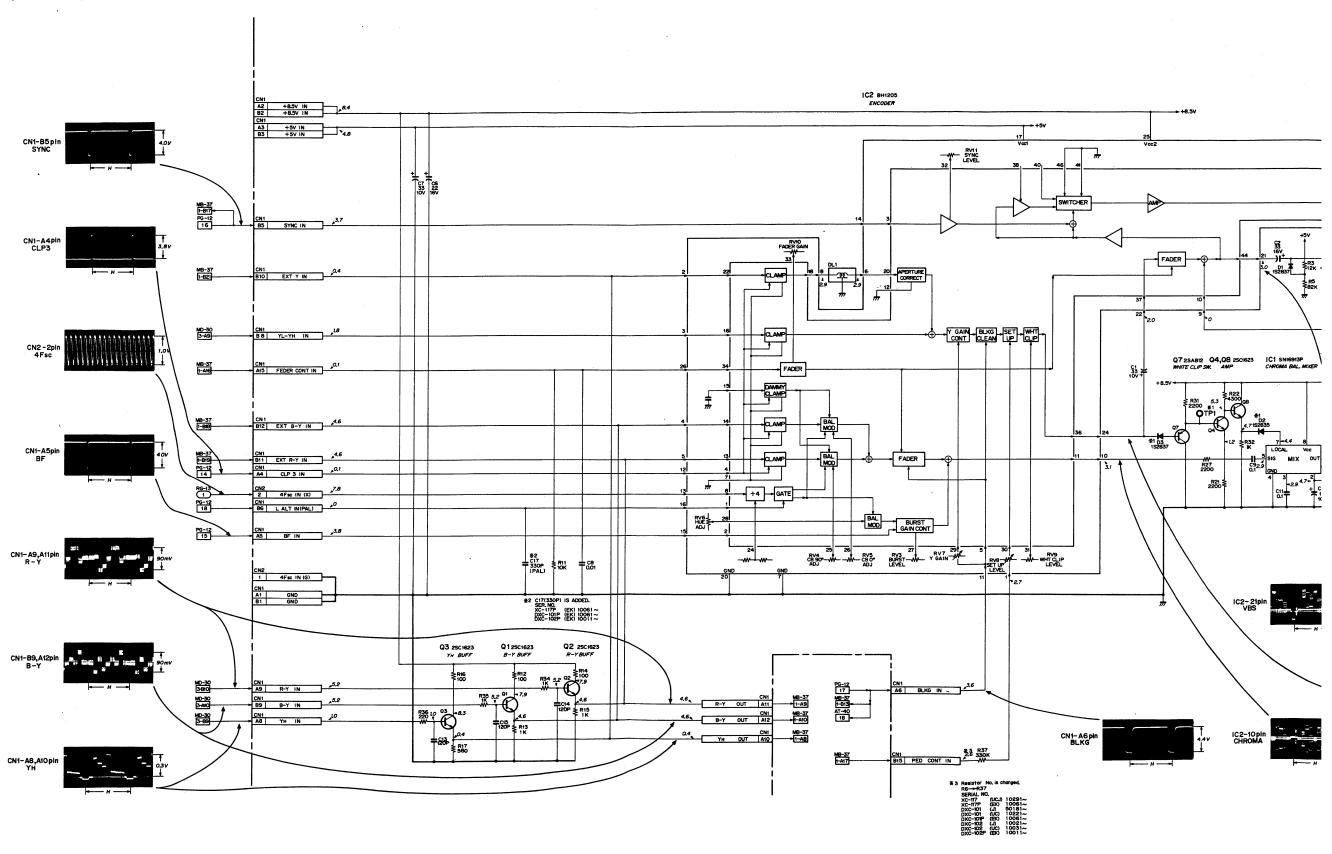


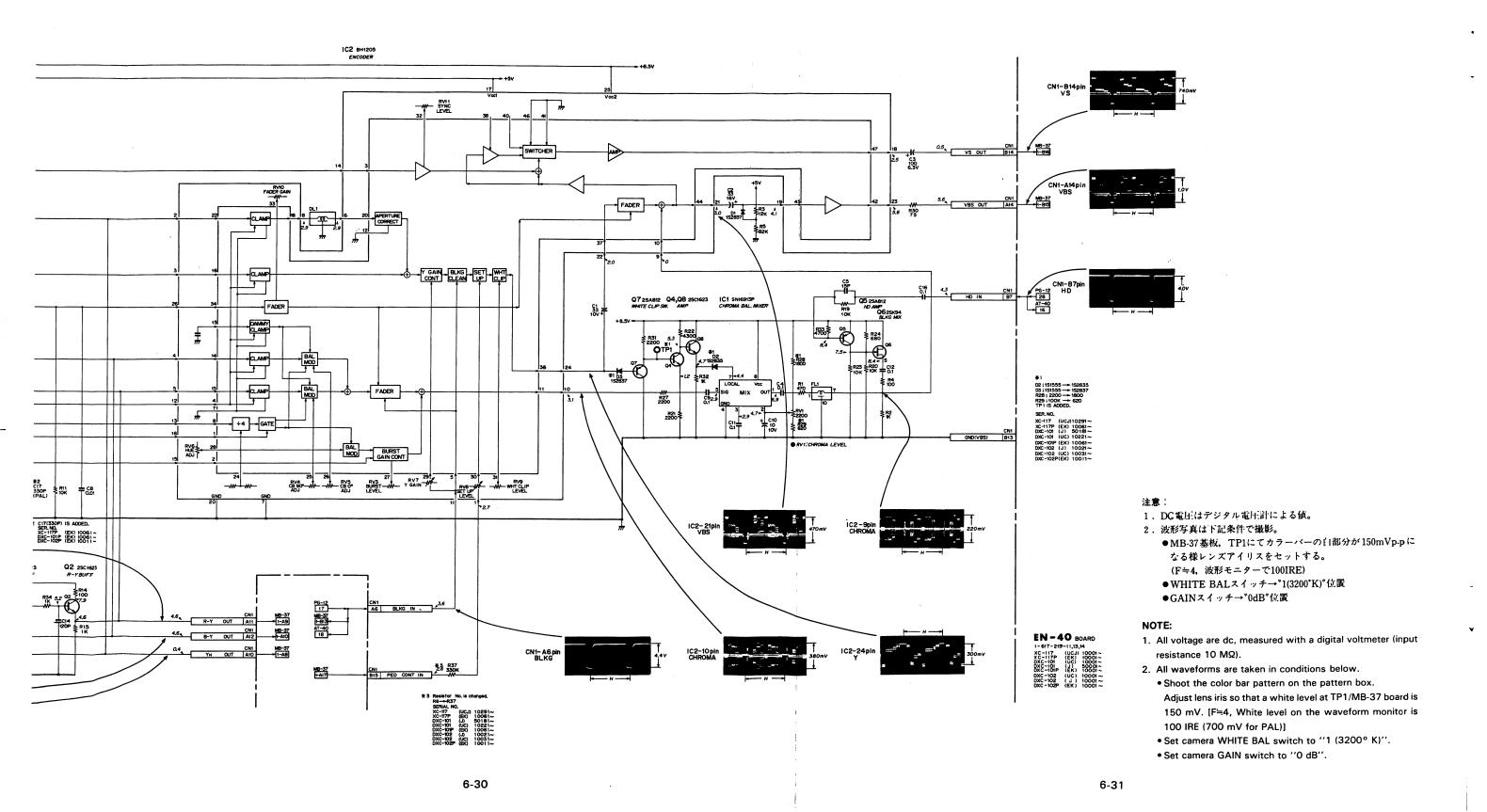
-SOLDERING SIDE-

EN-40 BOARD

1-617-215-14

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P (EK)





RG-13 BOARD

SERIAL NO.

DXC-101 (J) Up to 50430

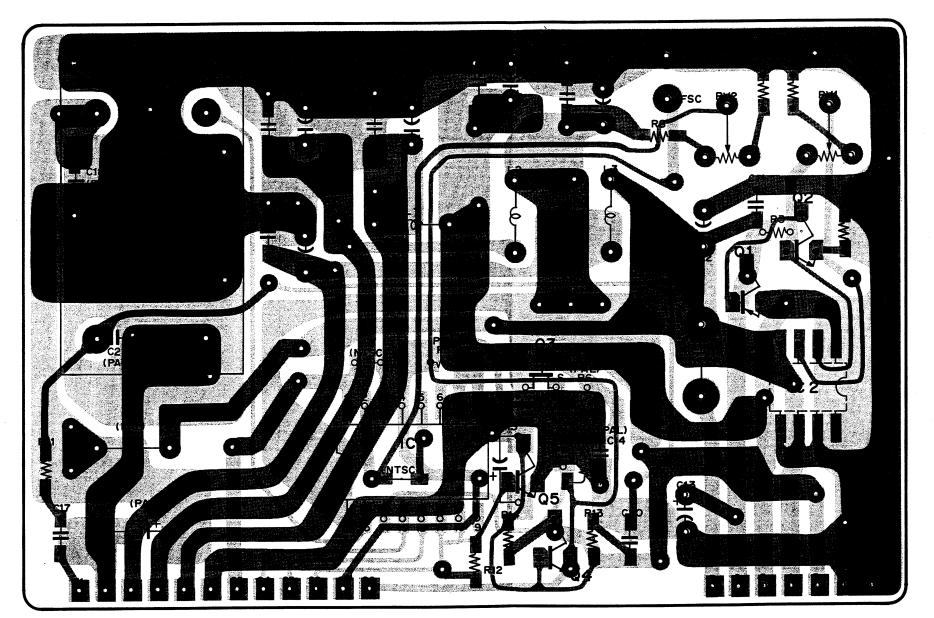
DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10260

DXC-102 (J) Up to 10190

DXC-102 (UC) Up to 10180

DXC-102P (EK) Up to 10310

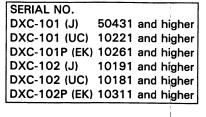


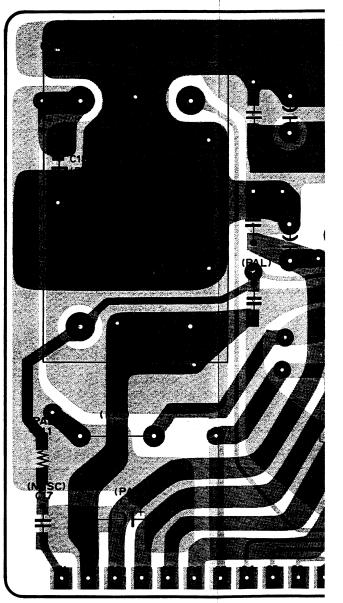
-SOLDERING SIDE-

RG-13 BOARD

1-617-211-11

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P(EK)

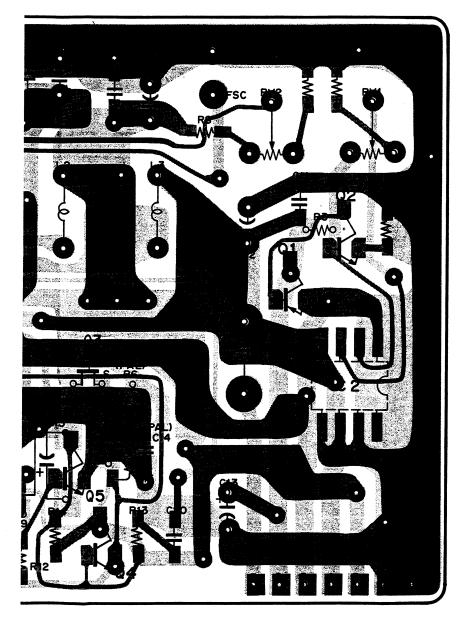




RG-13

SERIAL NO.

DXC-101 (J) 50431 and higher DXC-101 (UC) 10221 and higher DXC-101P (EK) 10261 and higher DXC-102 (J) 10191 and higher DXC-102 (UC) 10181 and higher DXC-102P (EK) 10311 and higher

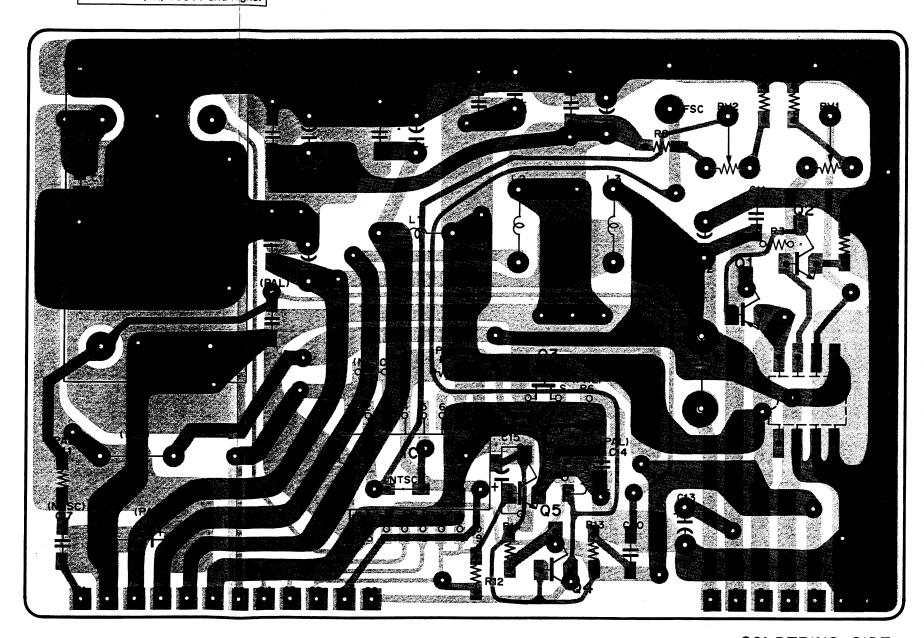


-SOLDERING SIDE-

RG-13 BOARD

1-617-211-11

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P(EK)



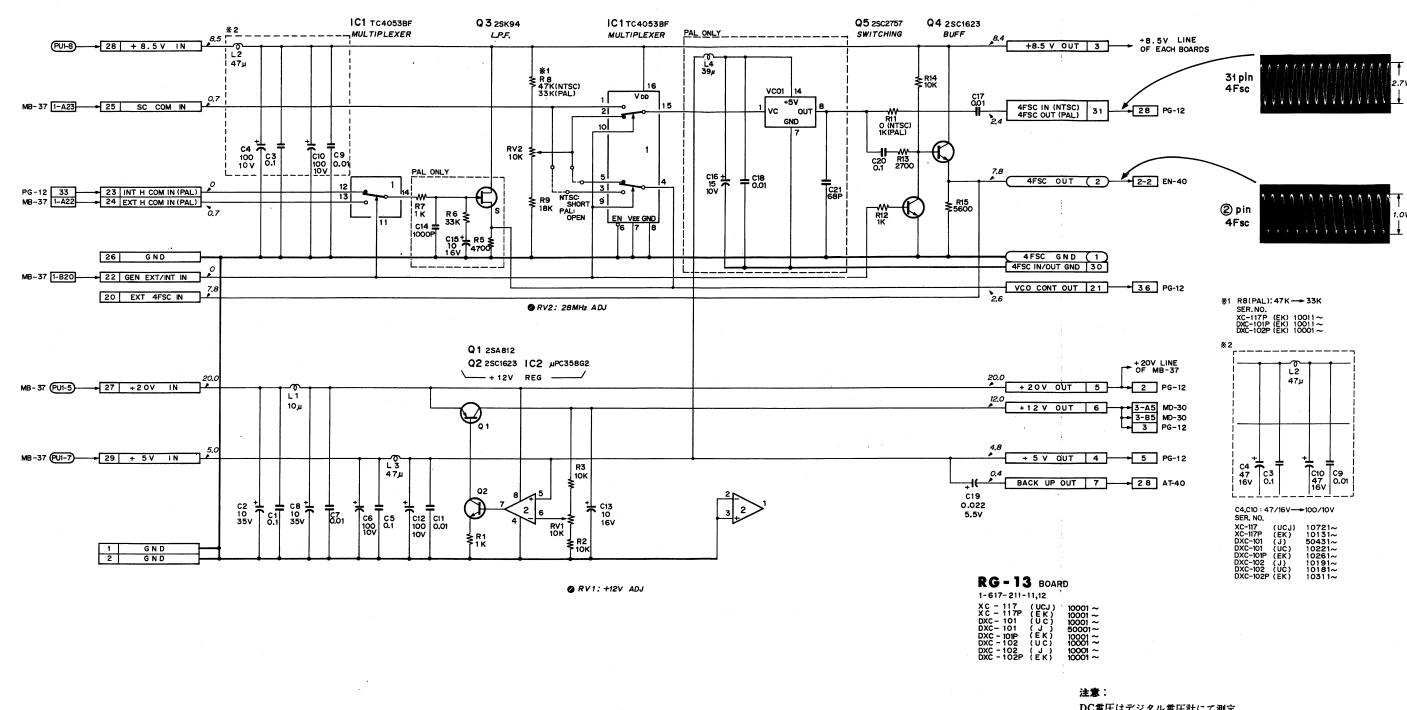
-SOLDERING SIDE-

RG-13 BOARD

1-617-211-12

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P (EK) DXC-102 (UC,J) DXC-102P(EK)

RG-13 BOARD



DC電圧はデジタル電圧計にて測定。

All voltage are mesured with a digital voltmeter (input resistance 10 MΩ).

6-36

SG-38 DXC-102/102P DXC-102/102P SG-38

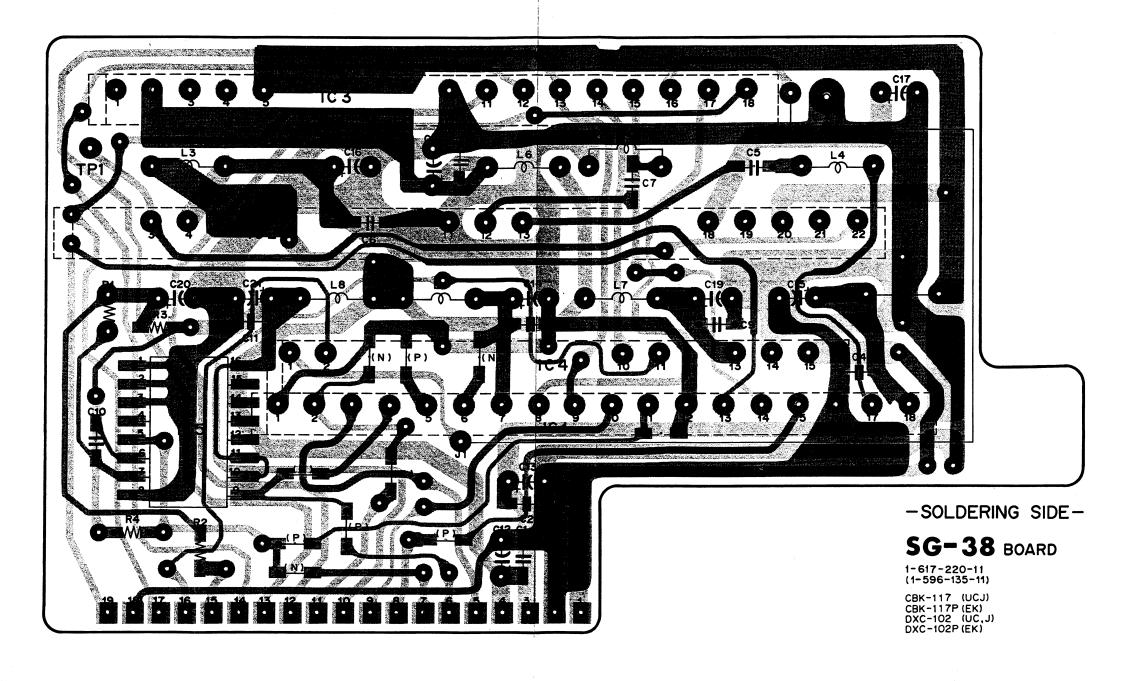
SG-38 BOARD

SERIAL NO.

DXC-102 (J) Up to 11190

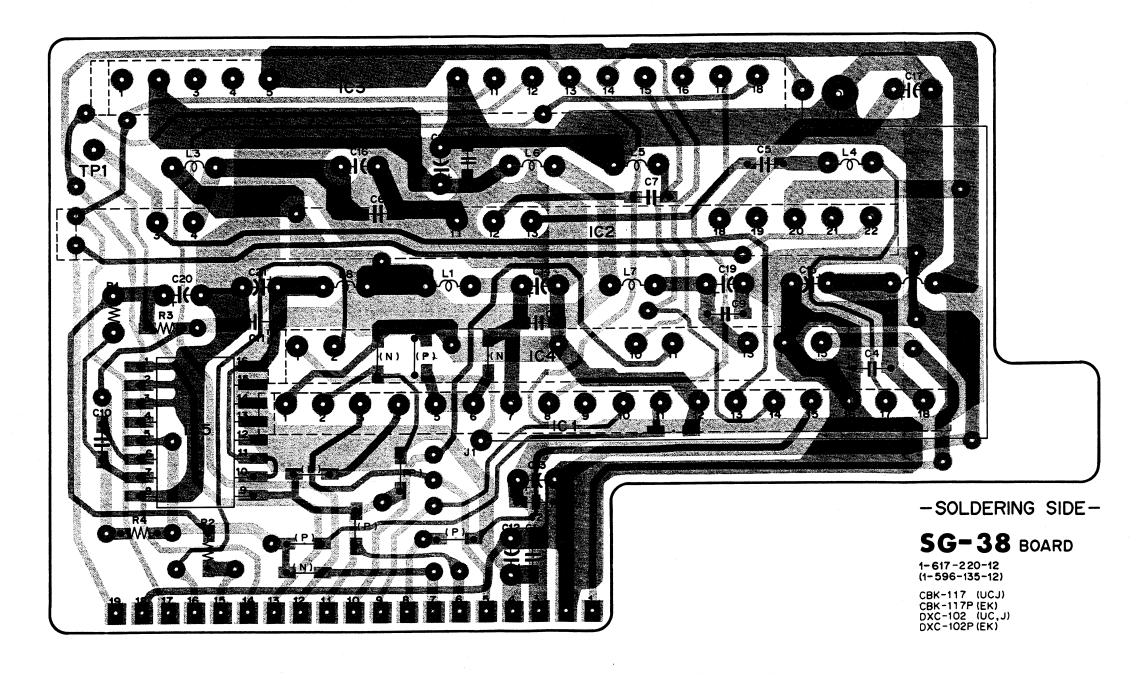
DXC-102 (UC) Up to 10180

DXC-102P (EK) Up to 10310



SG-38 BOARD

SERIAL NO.
DXC-102 (J) 10191 to 10470
DXC-102 (UC) 10181 to 10660
DXC-102P (EK) 10311 to 11070



SG-38 DXC-102/102P DXC-102/102P SG-38

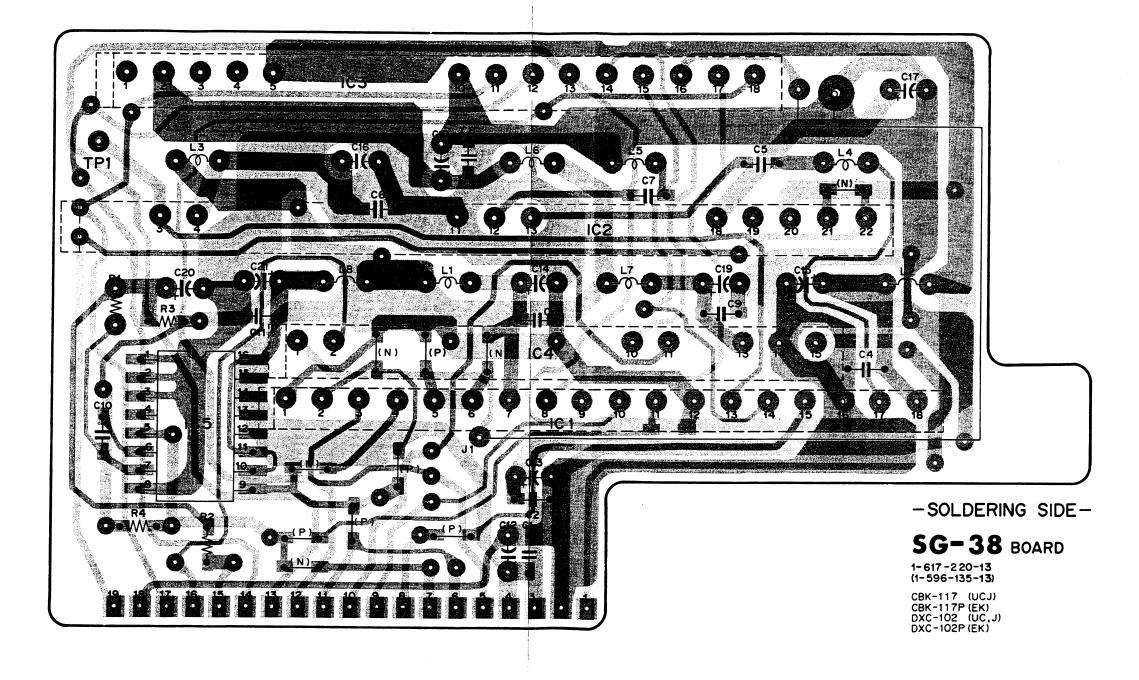
SG-38 BOARD

SERIAL NO.

DXC-102 (J) 10471 and higher

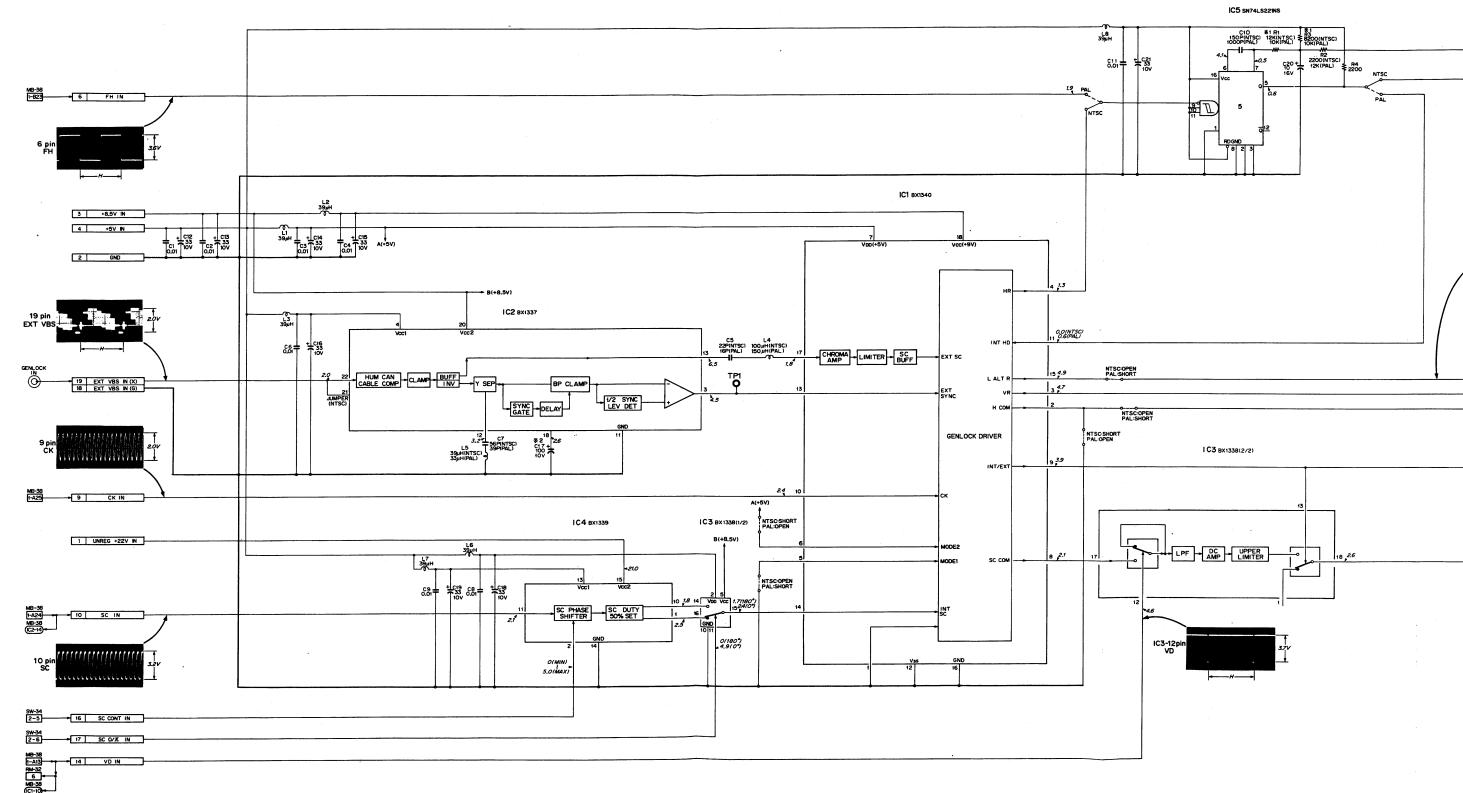
DXC-102 (UC) 10661 and higher

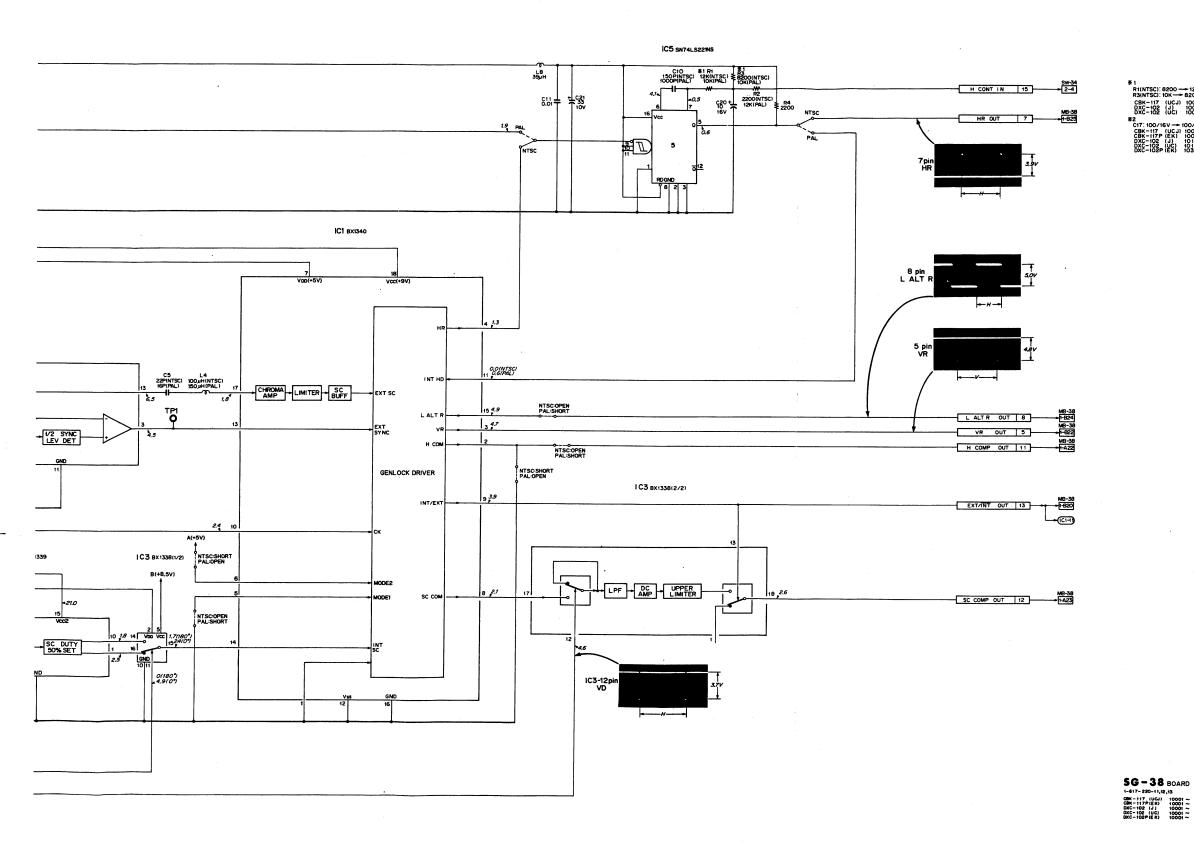
DXC-102P (EK) 11071 and higher



SG-38 DXC-102/102P DXC-102/102P SG-38

SG-38 BOARD





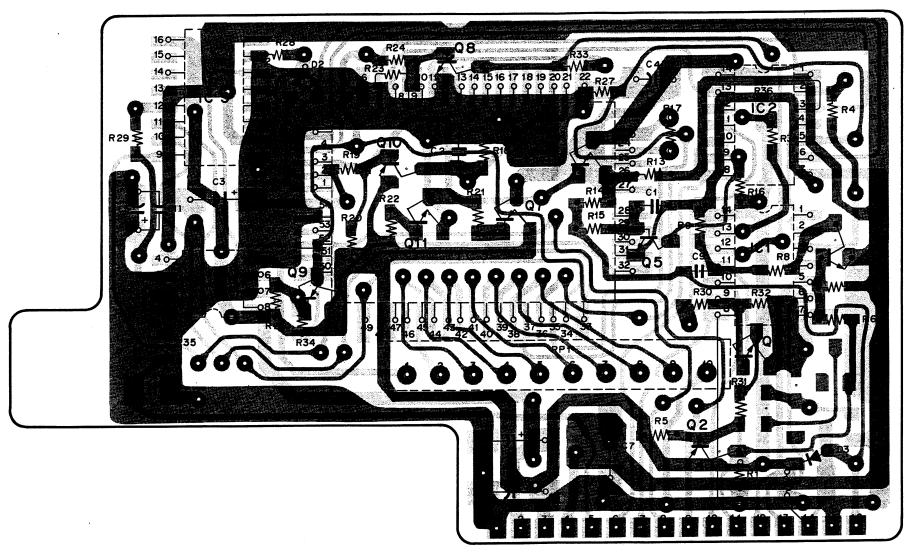
1. DC電圧はデジタル電圧計による値。

2. 波形写真はGENLOCK IN端子よりカラーバー信号を入りす

- 1. All voltage are dc, measured with a digital voltmeter in put resistance 10 MΩ).
- 2. All waveforms are taken in condition below.
 - Supply a color bar signal to the GENLOCK terminal.

RM-32 BOARD

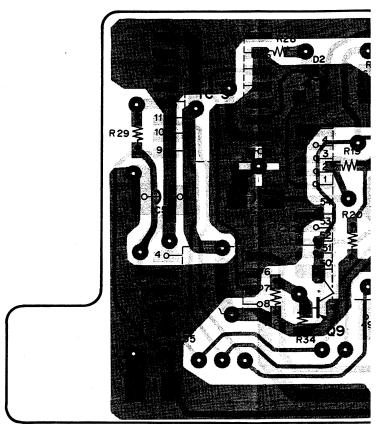
SERIAL NO.
DXC-102 (J) Up to 10190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310



-SOLDERING SIDE-

RM-32 BOARD

1-617-219-11 CBK-117 (UCJ) CBK-117P (EK) DXC-102 (UC,J) DXC-102P (EK) SERIAL NO.
DXC-102 (J) 10191 and higher
DXC-102 (UC) 10181 and higher
DXC-102P (EK) 10311 and higher



RM-32

DXC-102/102P

DXC-102/102P

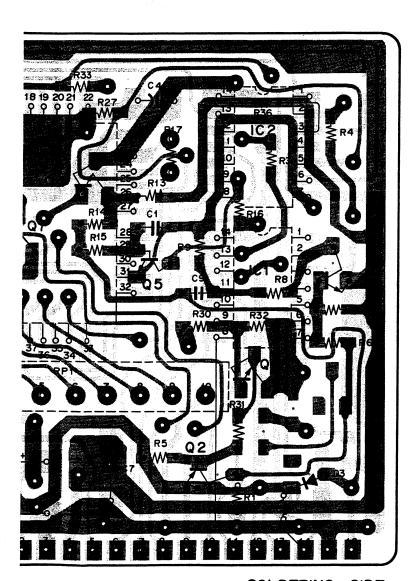
RM-32

SERIAL NO.

DXC-102 (J) 10191 and higher

DXC-102 (UC) 10181 and higher

DXC-102P (EK) 10311 and higher

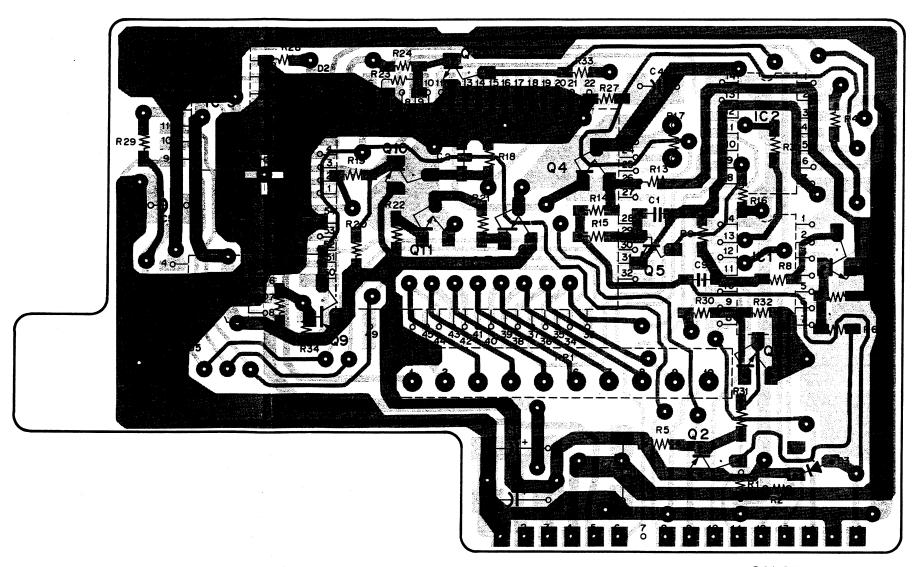


-SOLDERING SIDE-

RM-32 BOARD

1-617-219-11

CBK-117 (UCJ) CBK-117P (EK) DXC-102 (UC,J) DXC-102P (EK)



-SOLDERING SIDE-

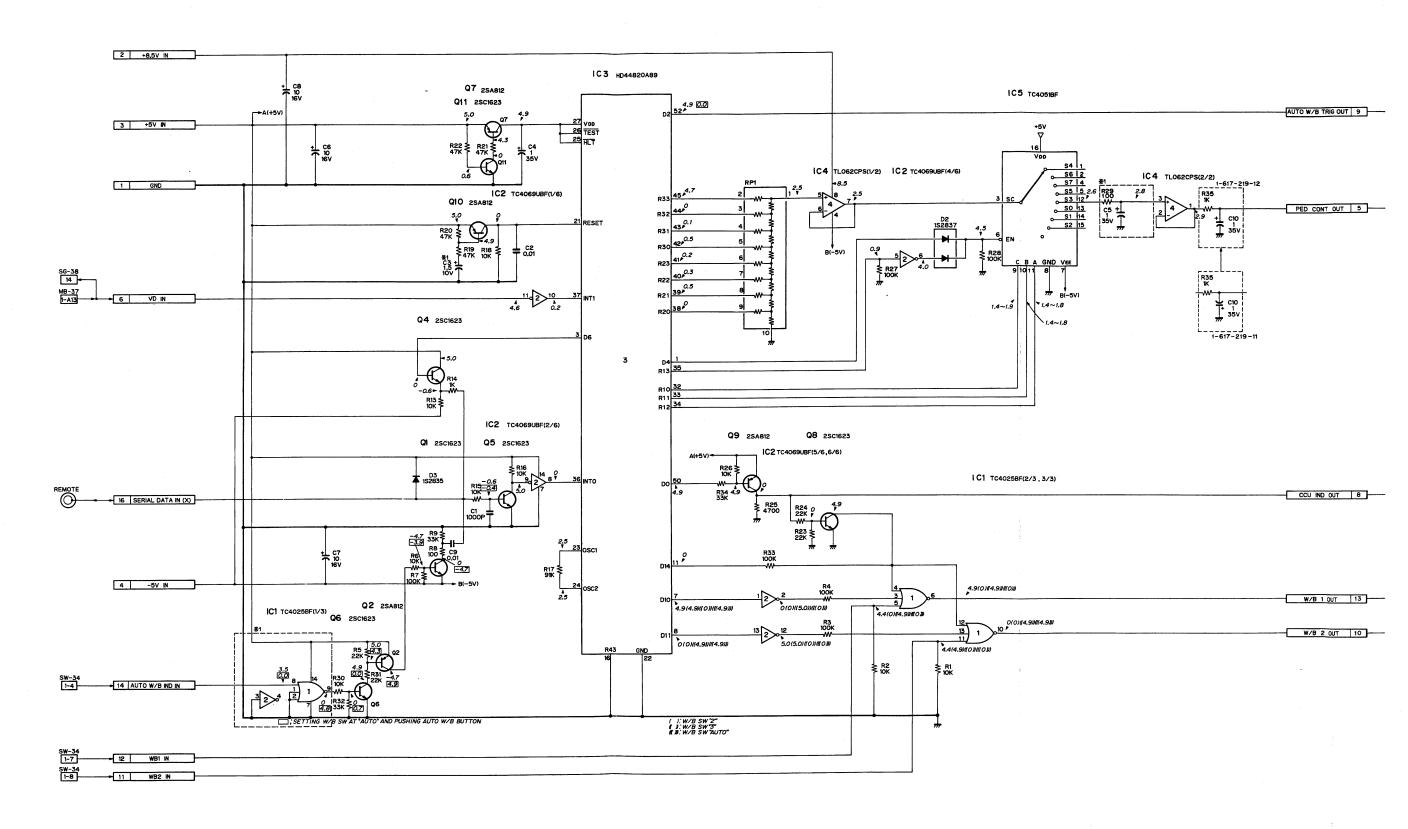
RM-32 BOARD

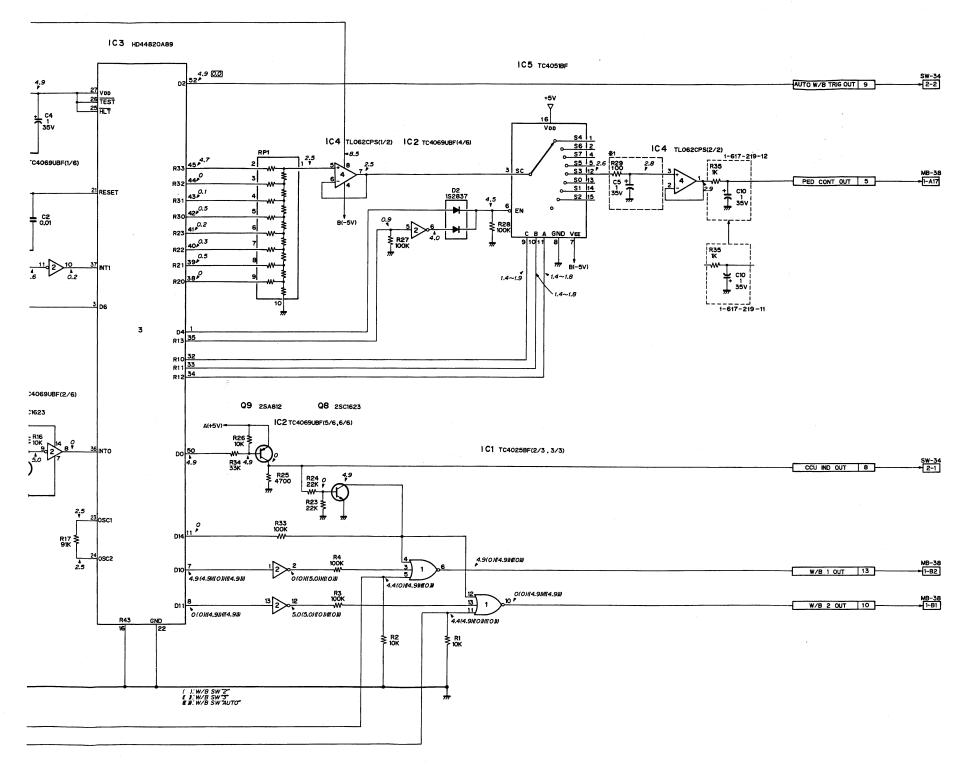
1-617-219-12

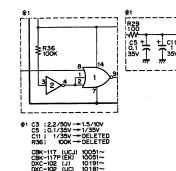
CBK-117 (UCJ) CBK-117P (EK) DXC-102 (UC,J) DXC-102P (EK)

6-43









RM-32 BOARD 1-617-219-11,12

注意:

DC電圧は下記条件による値。

●デジタル電圧計で測定。

●REMOTE端子にカメラアダプターCMA-10を接続。 CMA-10セッティング;

PEDESTAL:メカニカルセンター WHITE BAL:"1"位置

NOTE:

All voltage are taken in condition below.

• Digital voltmeter.

 Connect REMOTE terminal to camera adaptor CMA-10/10CE.

CMA-10/10CE setting;

PEDESTAL: mechanicalcenter WHITE BAL: "1" position.

DXC-101 (J) Up to 50180 DXC-101 (UC) Up to 10220 DXC-101P (EK) Up to 10060

SERIAL NO.

SERIAL NO. DXC-101(J) DXC-101(UC) DXC-101P(EK)

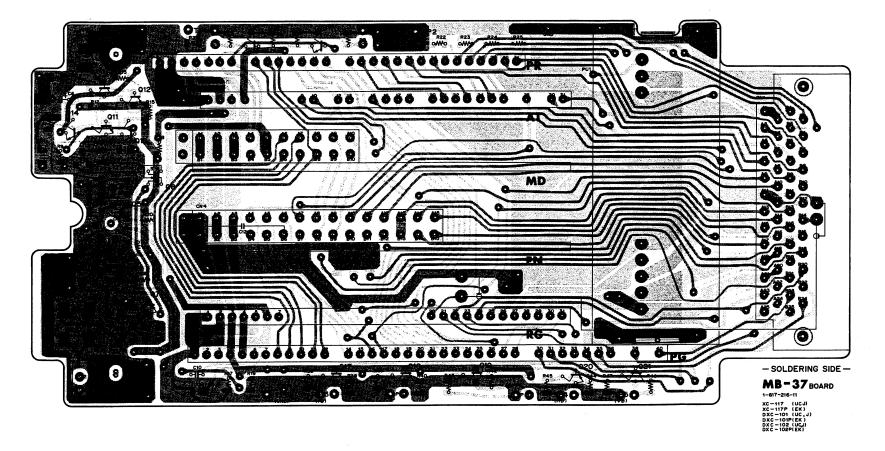
MB-37 BOARD BI-3 BOARD CN-39 BOARD SW-33 BOARD DC-28 BOARD LE-47 BOARD

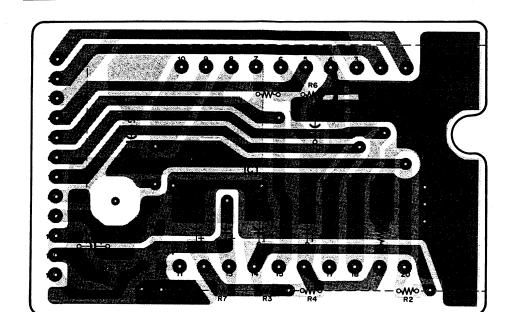
SERIAL NO.

DXC-101 (J) Up to 50430

DXC-101 (UC) Up to 10220

DXC-101P (EK) Up to 10260

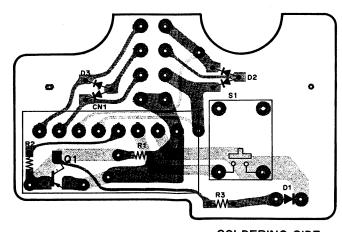




- SOLDERING SIDE -

BI-3 BOARD

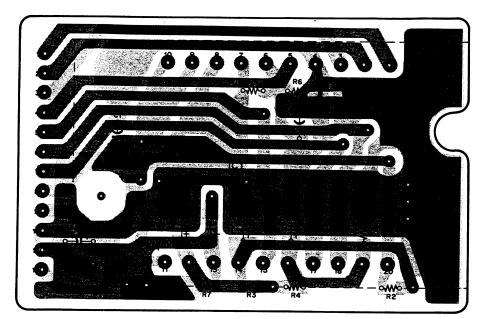
1-617-209-11 XC-117 (UCJ) XC-117P (EK) DXC-101 (UC, J) DXC-101P(EK)



-SOLDERING SIDE -

SW-33 BOARD

1-617-218-11 DXC-101 (UC, J) DXC-101P (EK) SERIAL NO. DXC-101 (J) Up to 50180 DXC-101 (UC) Up to 10220 DXC-101P (EK) Up to 10060

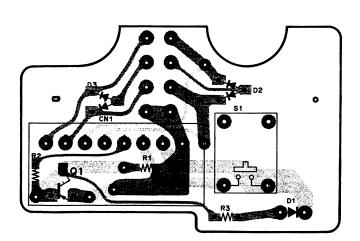


- SOLDERING SIDE -

BI-3 BOARD

1-617-209-11

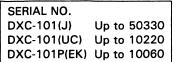
XC-117 (UCJ) XC-117P (EK) DXC-101 (UC, J) DXC-101P(EK)

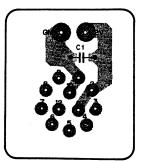


-SOLDERING SIDE -

SW-33 BOARD

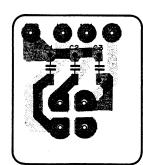
1-617-218-11 DXC-101 (UC, J) DXC-101P (EK)





-SOLDERING SIDE-

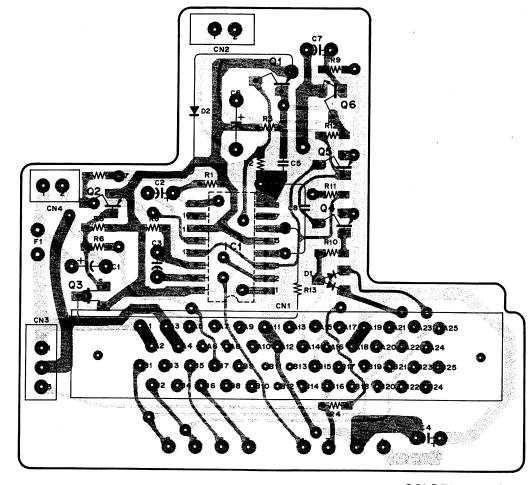
DC-28 BOARD 1-617-768-11 DXC-101 (UC, J) DXC-101P(EK)



-SOLDERING SIDE-

LE-47 BOARD

1-617-767-11 DXC - 101 (UC,J) DXC - 101P (EK) DXC - 102 (UC,J) DXC - 102P (EK)



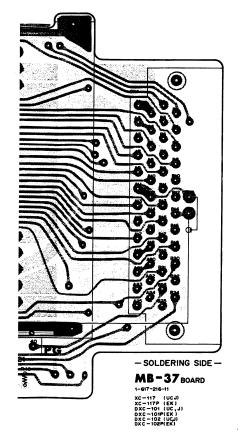
-SOLDERING SIDE-

CN-39 BOARD

DXC-101 (UC,J) DXC-101P (EK)

6-50(a)

DXC-101/102/101P/102P (J, UC, EK)

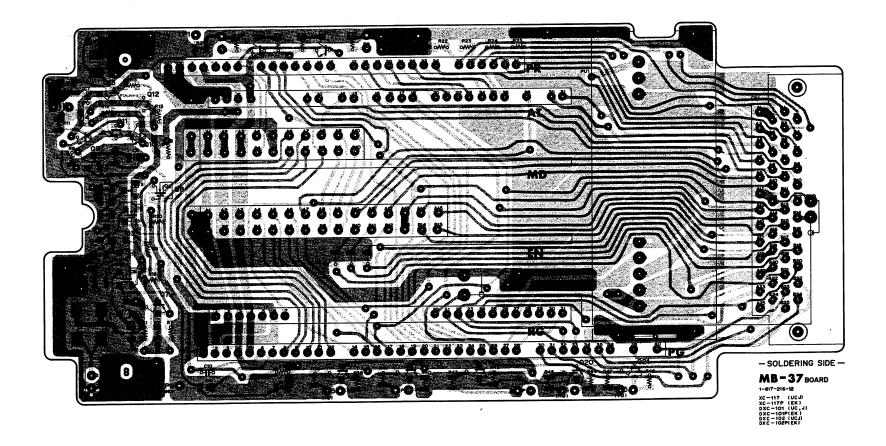


6-49(a)

MB-37 BOARD BI-3 BOARD CN-39 BOARD SW-33 BOARD DC-28 BOARD LE-47A BOARD

> SERIAL NO. DXC-101 (J) 50431 to 50610

> DXC-101 (UC) 10221 to 10630 DXC-101P (EK) 10261 to 10580

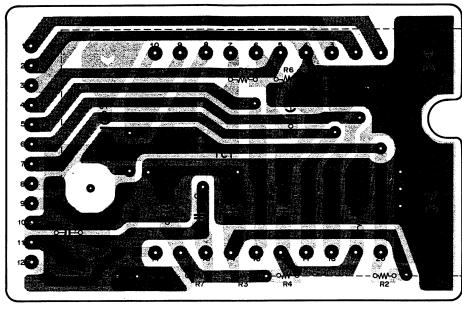


SERIAL NO.

DXC-101 (J) 50181 and higher

DXC-101 (UC) 10221 and higher

DXC-101P (EK) 10061 and higher

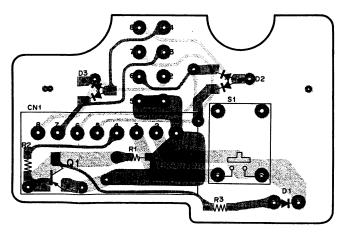


- SOLDERING SIDE-

BI-3 BOARD

1-617-209-12

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P(EK) DXC-102 (UCJ) DXC-102P(EK)



-SOLDERING SIDE -

SW-33 BOARD

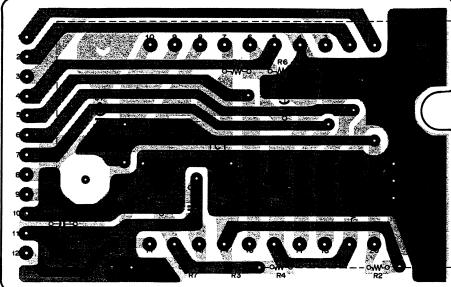
1-617-218-12 DXC-101 (UC,J) DXC-101P(EK)

- SOLDERING SIDE -MB-37BOARD

SERIAL NO.

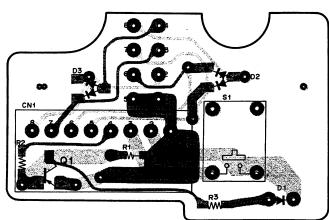
DXC-101 (J) 50181 and higher DXC-101 (UC) 10221 and higher DXC-101P (EK) 10061 and higher

MB37, BI-3, SW-39, SW-33, DC-28 LE-47A



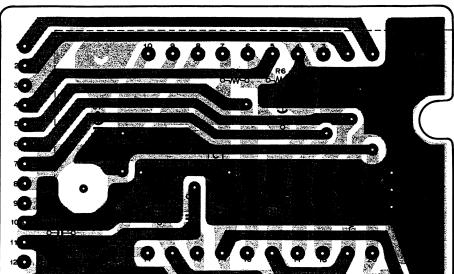
1-617-209-12

XC-117 (UCJ) XC-117P (EK) DXC-101 (UC,J) DXC-101P(EK) DXC-102 (UCJ) DXC-102P(EK)



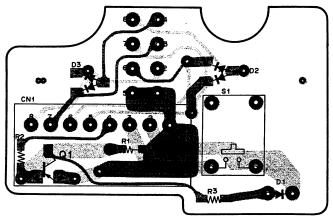
-SOLDERING SIDE -

1-617-218-12



- SOLDERING SIDE-

BI-3 BOARD

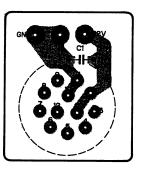


SW-33 BOARD

DXC-101 (UC.J)

SERIAL NO.

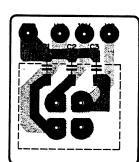
DXC-101 (J) 50331 and higher DXC-101 (UC) 10221 and higher DXC-101P (EK) 10061 and higher



-SOLDEING SIDE-

DC-28 BOARD

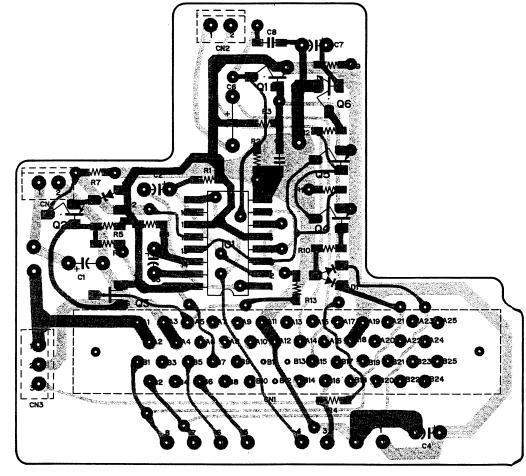
1-617-768-12 DXC-101 (UC,J) DXC-101P (EK)



-SOLDERING SIDE-

LE-47ABOARD

1-617-768-12 DXC-101 (UC,J) DXC-101P (EK)



-SOLDERING SIDE -

CN-39 BOARD

1-617-217-12 DXC-101 (UC,J) DXC-101P (EK)

6-49 (b)

6-50(b)

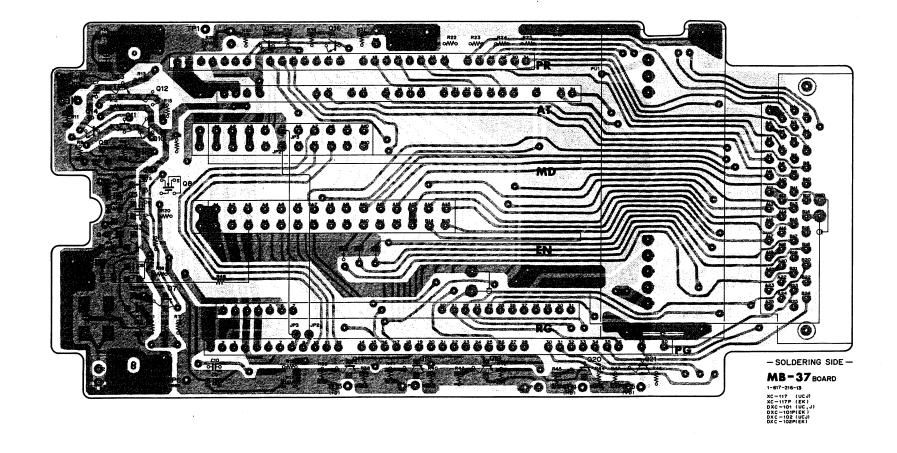
MB-37 BOARD

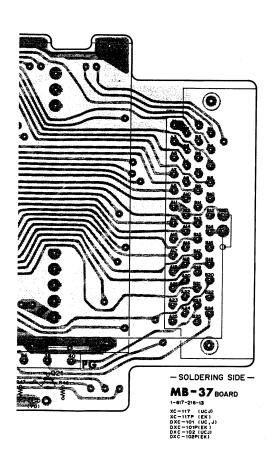
SERIAL NO.

DXC-101 (J) 50611 and higher

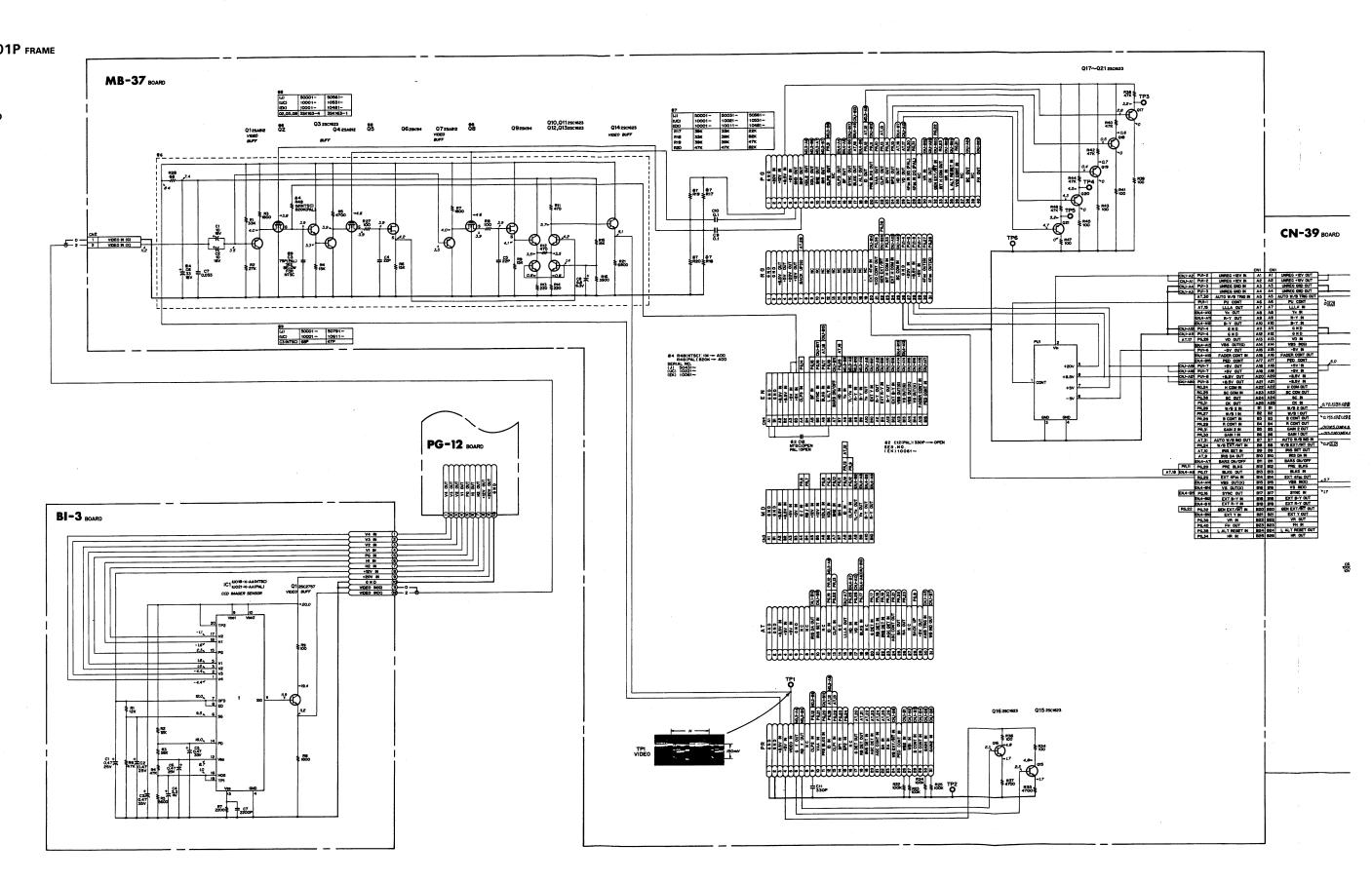
DXC-101 (UC) 10631 and higher

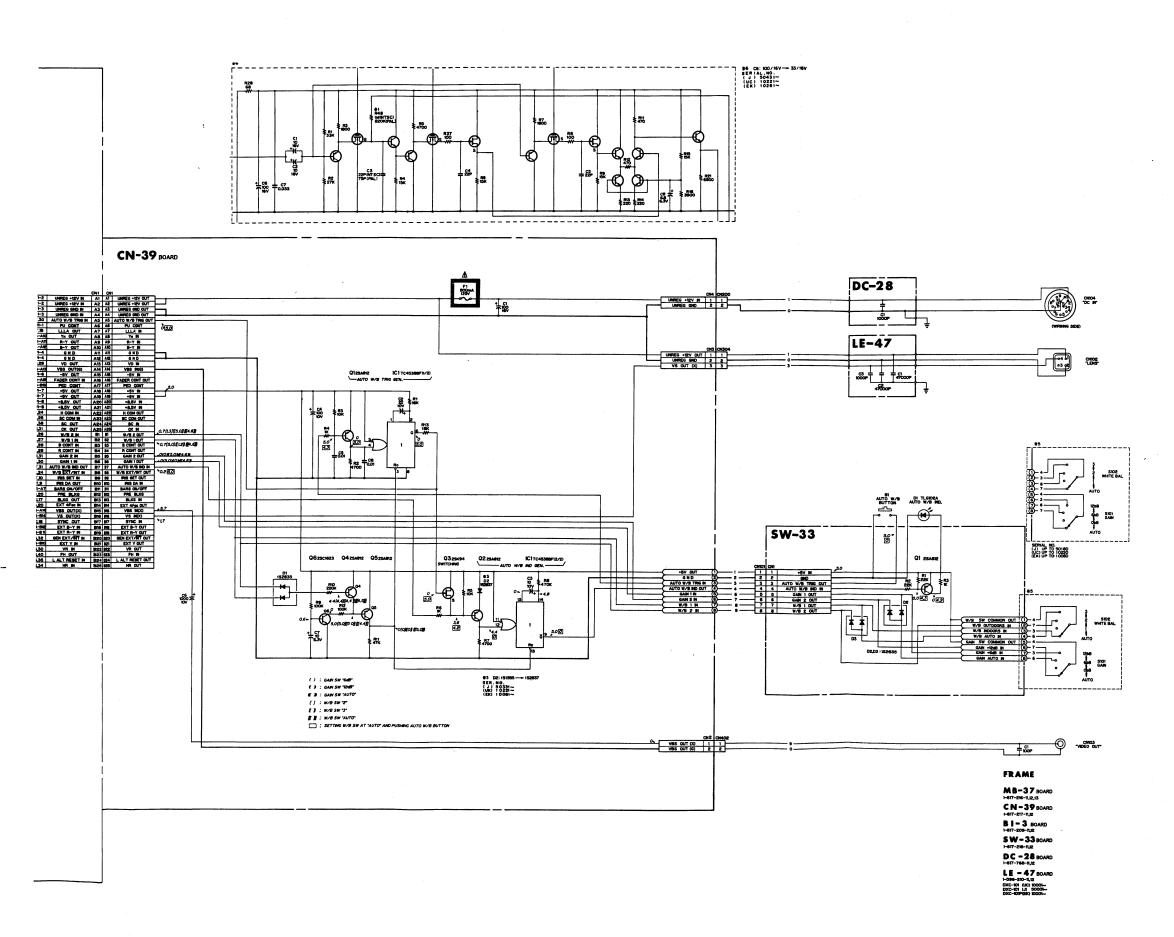
DXC-101P (EK) 10581 and higher





DXC-101/101P FRAME MB-37 BOARD BI-3 BOARD CN-39 BOARD SW-33 BOARD DC-28 BOARD LE-47 BOARD





注意:

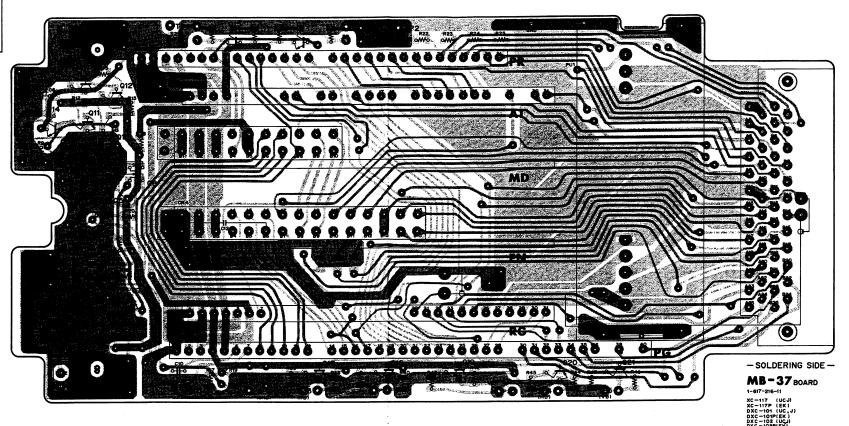
- 1. DC電圧はデジタル電圧計による値。
- 2. 波形写真は下記条件で撮影。
 - MB-37基板、TP1にてカラーバーの白部分が150mVp-pになる様レンズアイリスをセットする。 (F = 4、波形モニターで100IRE)
 - ●WHITE BALスイッチ←1(3200°K)″位置
- ●GAINスイッチ→*0dB″位置
- 3. Δ印及び で囲まれた部品は安全性を維持するために重要な部品です。従って交換する時は必ず指定の部品を使ってて下さい。

NOTE:

- 1. All voltage are dc, measured with a digital voltmeter (input resistance 10 M Ω).
- 2. All waveforms are taken in conditions below.
 - Shoot the color bar pattern on the pattern box.

 Adjust lens iris so that a white level at TP1/MB-37 board is
 150 mV. [F≒4, White level on the waveform monitor is
 100 IRE (700 mV for PAL)]
- Set camera WHITE BAL switch to "1 (3200°K)".
- Set camera GAIN switch to "O dB".
- The shaded and △ marked components are critical to safety.
 Replace only with same components as specified.

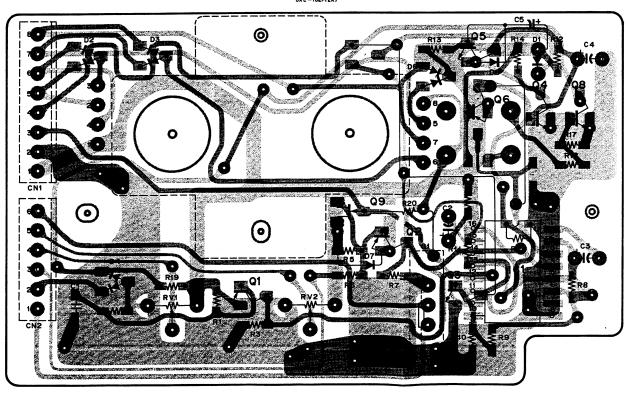
MB-37 BOARD MB-38 BOARD BI-3 BOARD SG-110 BOARD SW-34 BOARD LE-47 BOARD SERIAL NO.
DXC-102 (J) Up to 10190
DXC-102 (UC) Up to 10180
DXC-102P (EK) Up to 10310



- SOLDERING SIDE -

BI-3 BOARD

1-617-209-11 XC-117 (UCJ) XC-117P (EK) DXC-101 (UC, J) DXC-101P(EK)



-SOLDERING SIDE-

SERIAL NO.

DXC-102 (J) Up to 10190

DXC-102 (UC) Up to 10180

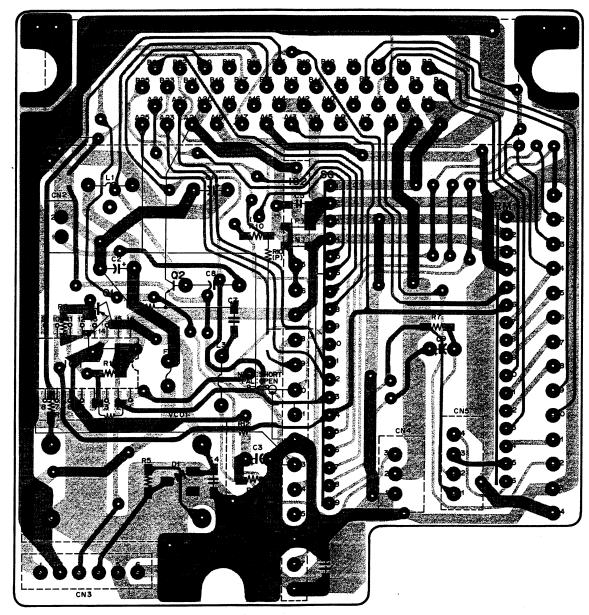
DXC-102P (EK) Up to 10310

SW - 34 BOARD 1-617-223-11 DXC-102 (UC,J) DXC-102P (EK)

6-55 (a)

6-56(a)

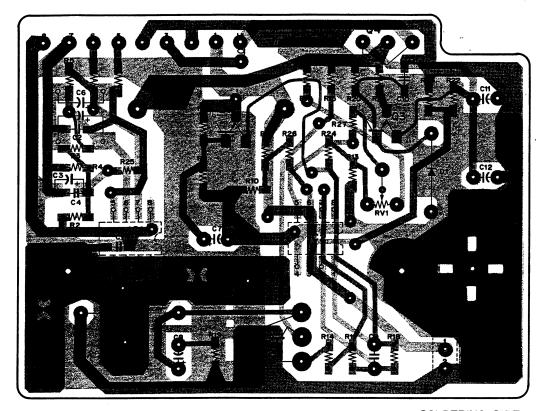
DXC-102 (UC) Up to 10180 DXC-102P (EK) Up to 10310



-SOLDERING SIDE-

MB-38 BOARD

1-617-213-11



-SOLDERING SIDE-

SG-110 BOARD

1-617-222-11

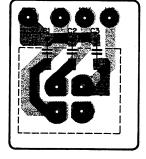


-SOLDERING SIDE-

LE-47 BOARD

1-617-767-11

SERIAL NO. DXC-102(J) Up to 10020 DXC-102(UC) Up to 10030 DXC-102P(EK) Up to 10010



-SOLDERING SIDE-

LE-47BBOARD

1-617-768-21 DXC-102 (UC,J) DXC-102P(EK)

SERIAL NO.

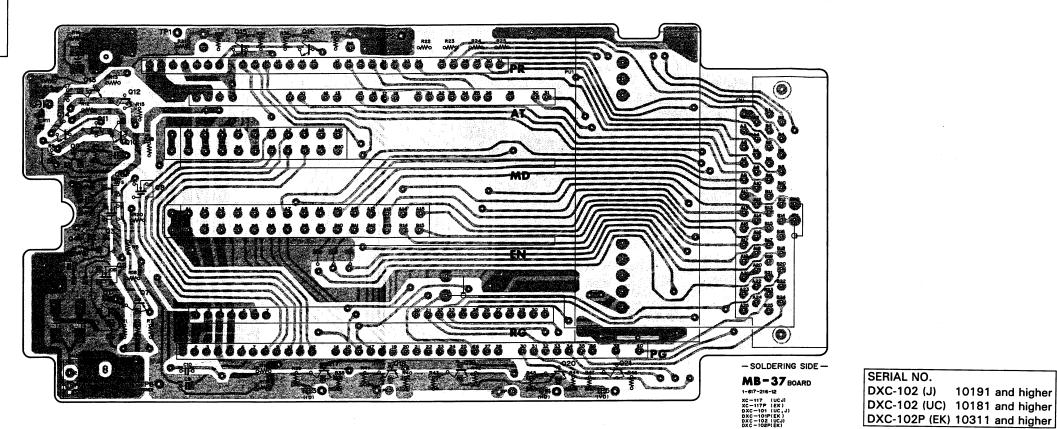
DXC-102(J) 10021 and higher DXC-102(UC) 10031 and higher DXC-102P(EK) 10011 and higher

6-57(a)

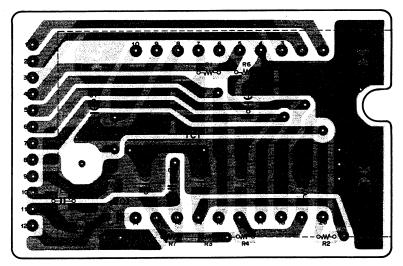
6-58(a)

DXC-101/102/101P/102P (J, UC, EK)

MB-37 BOARD MB-38 BOARD BI-3 BOARD SW-34 BOARD SERIAL NO. DXC-102 (J) 10191 to 10300 DXC-102 (UC) 10181 to 10410 DXC-102P (EK) 10311 to 10570

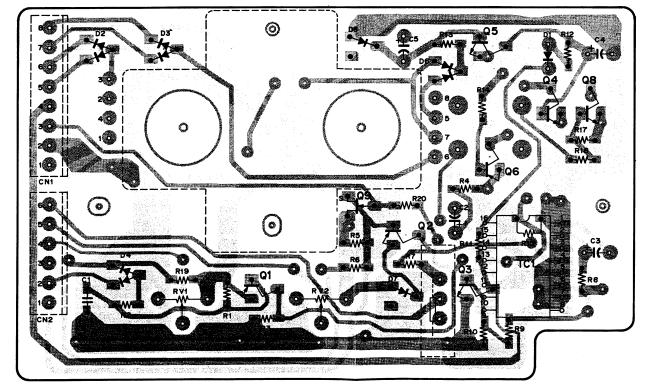


DXC-102 (J) 10021 and higher DXC-102 (UC) 10031 and higher DXC-102P (EK) 10011 and higher



- SOLDERING SIDE-

BI-3 BOARD 1-617-209-12



6-57(b)

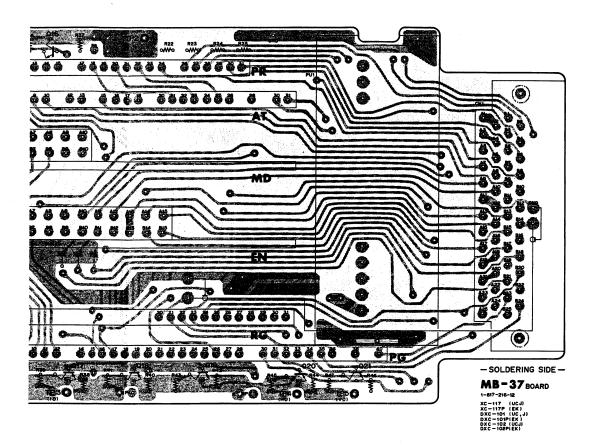
1-617-223-12 DXC-102 (UC,J) DXC-102P (EK)

6-56(b)

DXC-101/102/101P/102P (J, UC, EK)

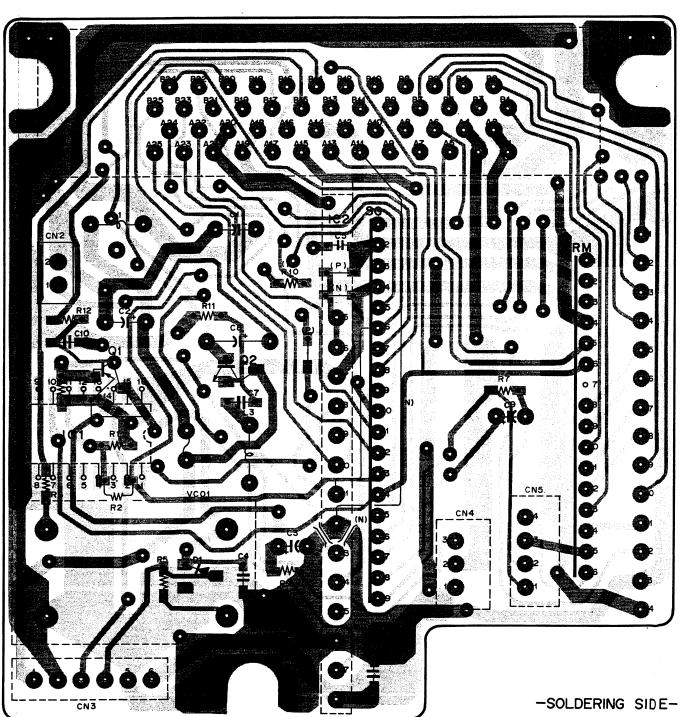
MB-38 BOARD

1-617-213-12 CBK-117 (UCJ) CBK-117P (EK) DXC-102 (UC,J) DXC-102P (EK)



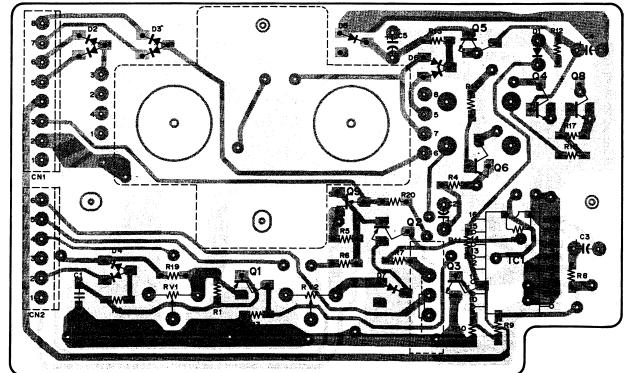
DXC-102 (J) 10191 to 10470 DXC-102 (UC) 10181 to 10660 DXC-102P (EK) 10311 to 11070

SERIAL NO.



SERIAL NO.

DXC-102 (J) 10191 and higher DXC-102 (UC) 10181 and higher DXC-102P (EK) 10311 and higher



-SOLDERING SIDE-

SW-34 BOARD 1-617-223-12 الب) DXC-102 (UC) DXC-102P (EK)

6-57(b)

6-58(b)

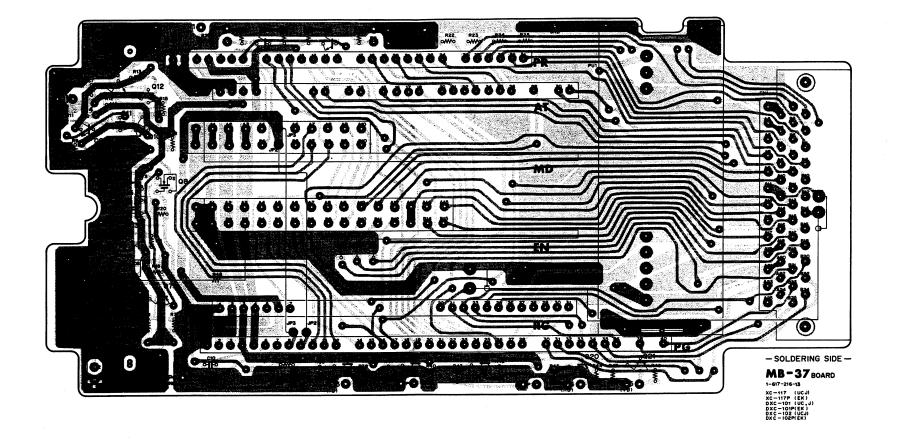
MB-37 BOARD MB-38 BOARD

SERIAL NO.

DXC-102 (J) 10301 and higher

DXC-102 (UC) 10411 and higher

DXC-102P (EK) 10571 and higher



6-56 (c)

MB-37, MB-38

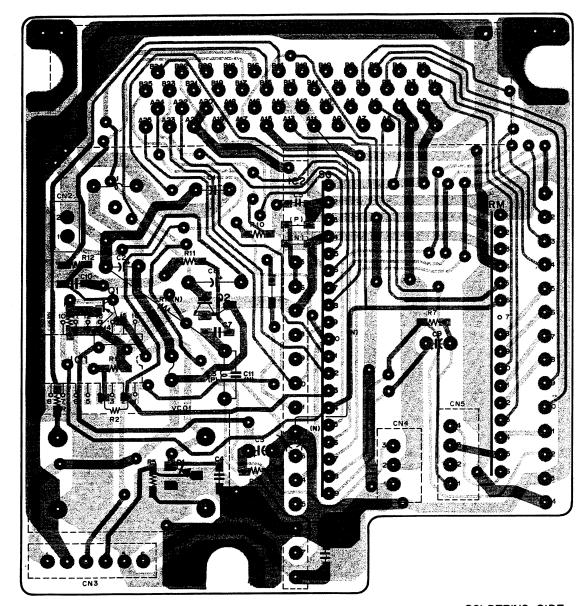
DXC-102/102P

DXC-102/102P

MB-37, MB-38

SERIAL NO.

DXC-102 (J) 10471 and higher DXC-102 (UC) 10661 and higher DXC-102P (EK) 11071 and higher



-SOLDERING SIDE-

MB-38 BOARD

CBK-117 (U

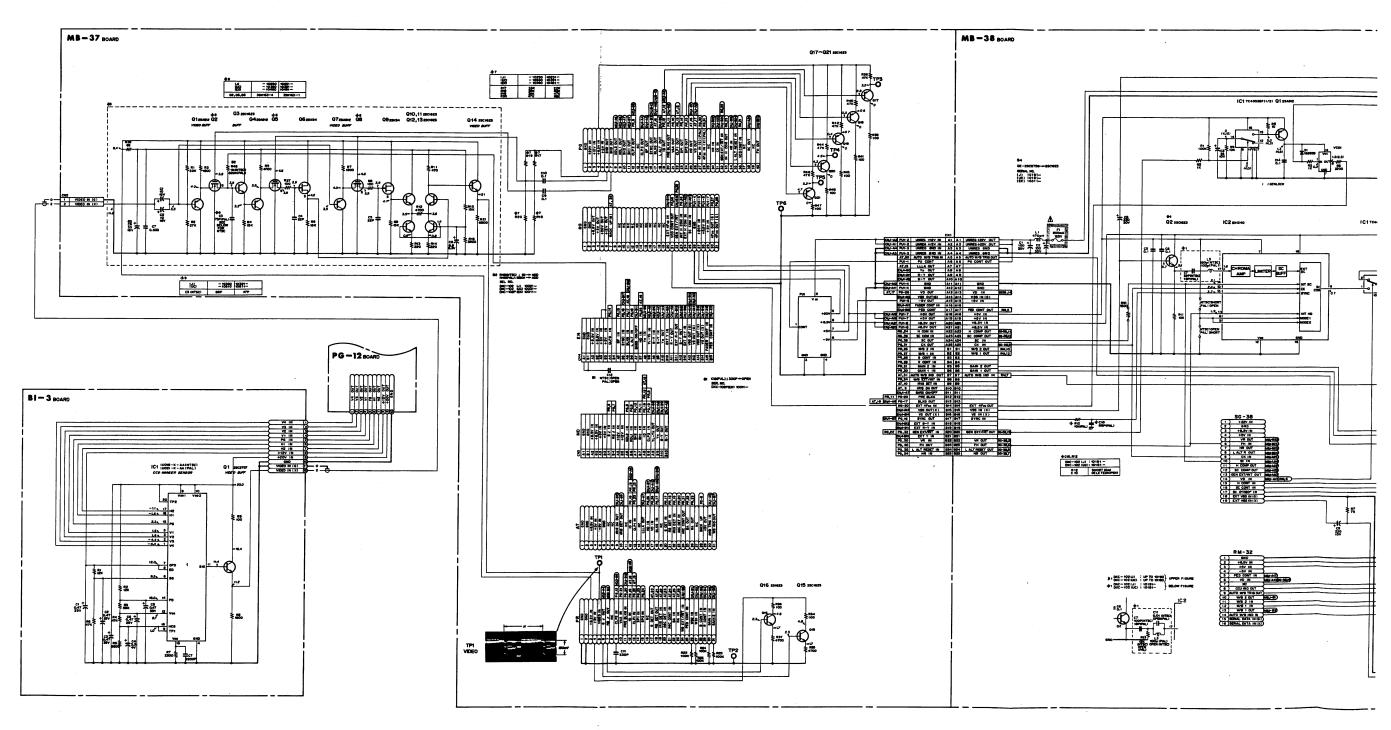
BK-117 (UCJ) BK-117P(EK) XC-102 (UC,J)

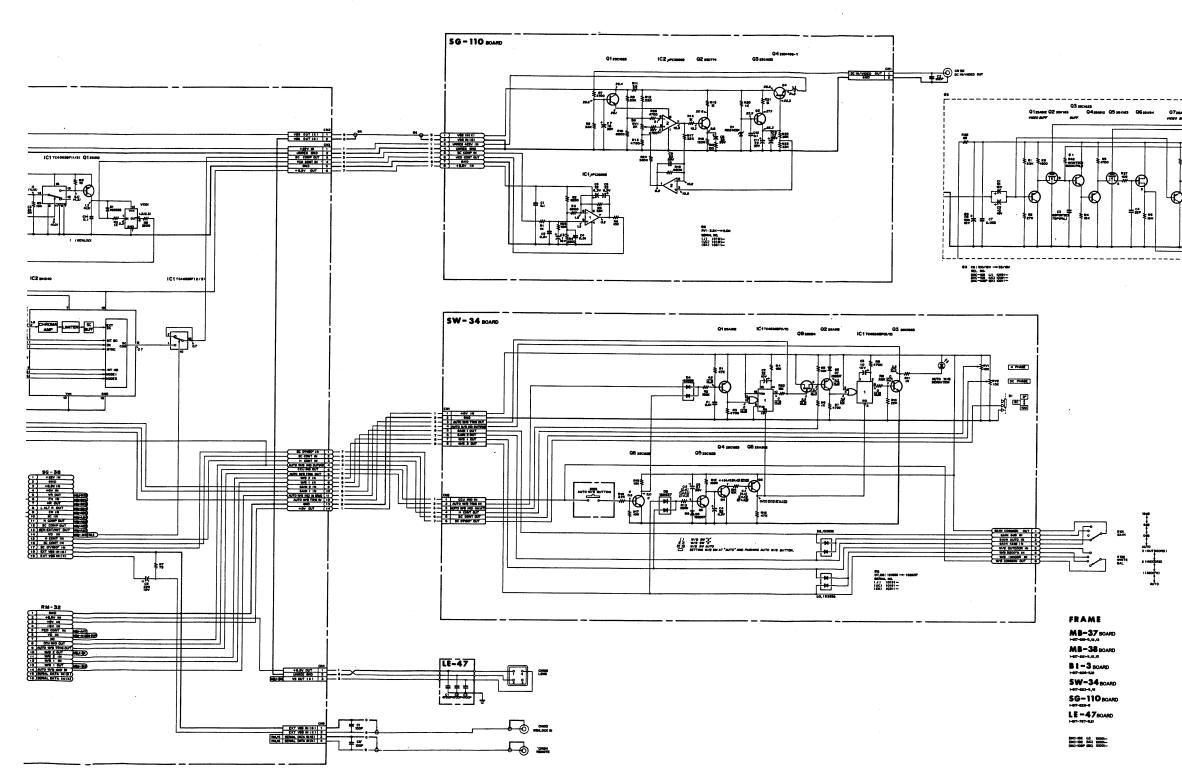


- SOLDERING SIDE -

MB - 37 BOARD
1-617-216-13
XC-117 (EK)
DXC-101 (UC, J)
DXC-101 (UC, J)
DXC-101 (UC, J)
DXC-101 (UC, J)
DXC-102 (UC, J)
DXC-102 (UC, J)

DXC-102/102P FRAME MB-37 BOARD MB-38 BOARD BI-3 BOARD SG-110 BOARD SW-34 BOARD LE-47 BOARD





注意:

- 1. DC電圧はデジタル電圧計による値。
- 2. 波形写真は下記条件で撮影。
 - MB-37基板、TP1にてカラーバーの白部分が150mVp→6こなる様レンズアイリスをセットする。
 (F≒4、波形モニターで100IRE)
 - ●WHITE BALスイッチ←1(3200°K)"位置●GAINスイッチ→ *0dB"位置

NOTE:

- All voltage are dc, measured with a digital voltmeter (in) tresistance 10 MΩ).
- 2. All waveforms are taken in conditions below.
 - Shoot the color bar pattern on the pattern box.

 Adjust lens iris so that a white level at TP1/MB-37 boart is s

 150 mV. [F≒4, White level on the waveform monitor is s

 100 IRE (700 mV for PAL)]
- Set camera WHITE BAL switch to "1 (3200°K)".
- Set camera GAIN switch to "0 dB".
- 3. The shaded and △ marked components are critical
 safety.

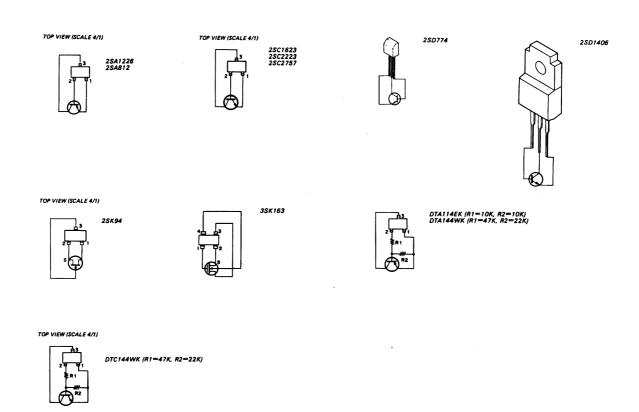
Replace only with same components as specified.

||||||||||||||||||||| 7. SEMICONDUCTOR PIN ASSIGNMENTS

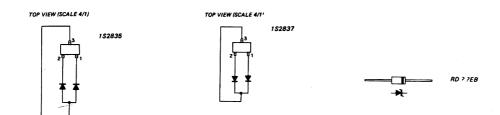
SECTION 7 SEMICONDUCTOR PIN ASSIGNMENTS

NOTE: The circuit diagram of IC is obtained from the IC data book published by the manufacturer.

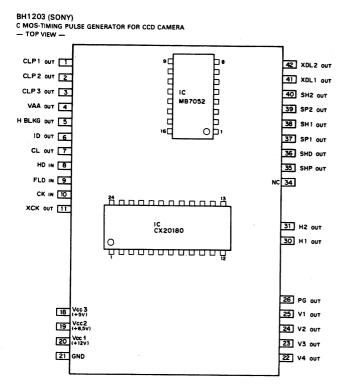
7-1. TRANSISTOR

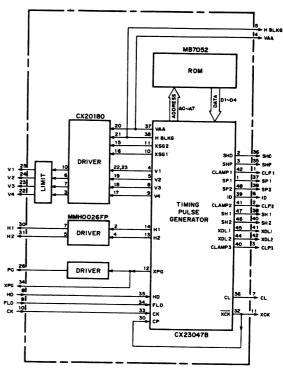


7-2. DIODE

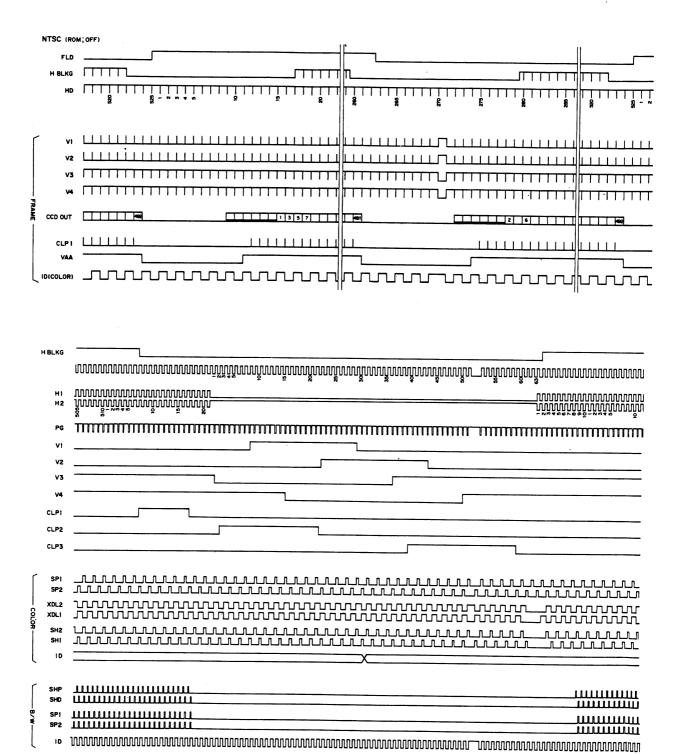


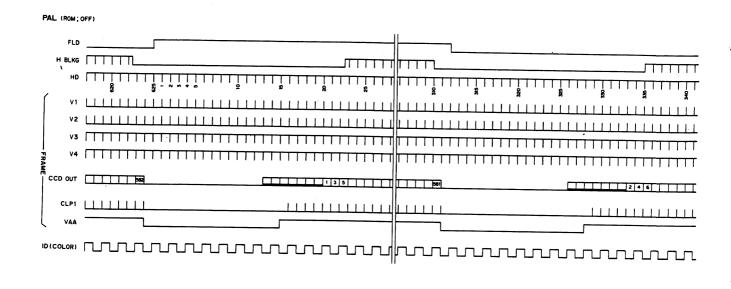
7-3. IC

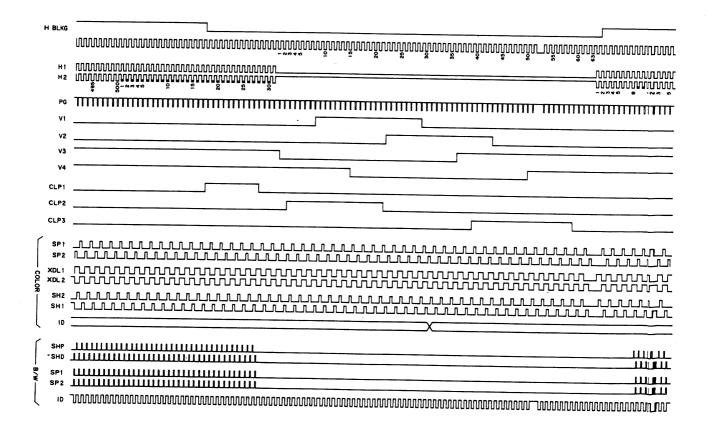




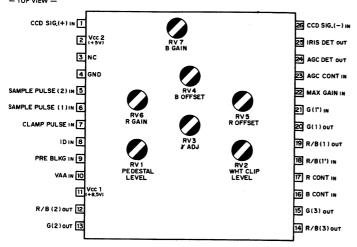
Note; 1.NTSC/PAL MODE IS SELECTED BY ROM DATA. 2.FREQUENCY OF CK, NTSC; 28.6364 MHz PAL ; 28.3750 MHz

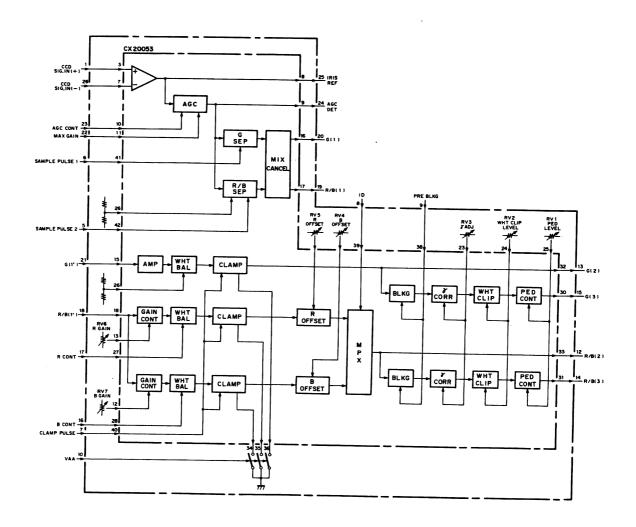


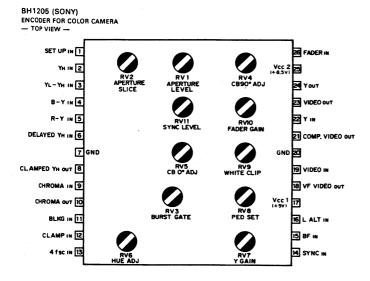


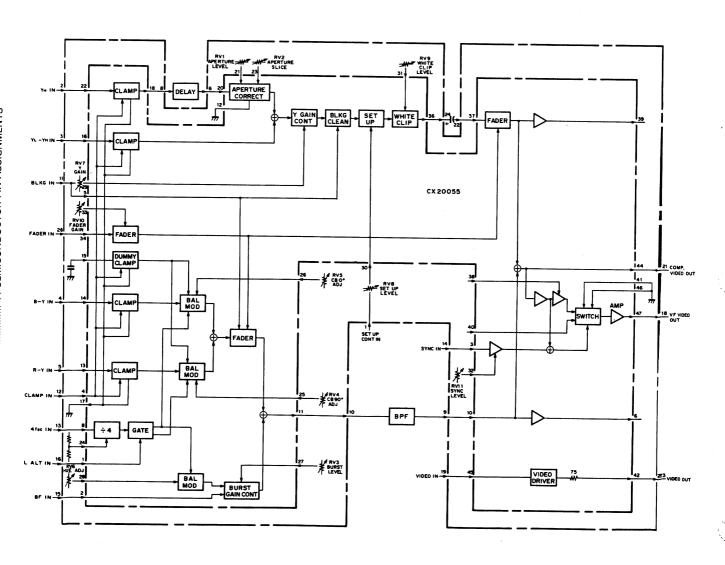




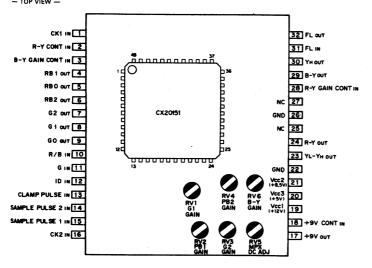


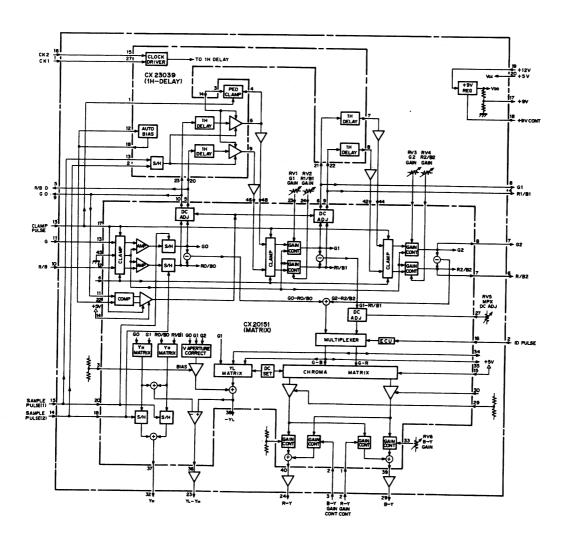




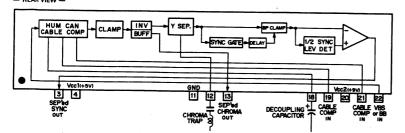




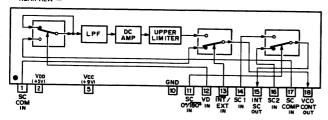




BX1337 (SONY) SYNC SEPARATOR — REAR VIEW —



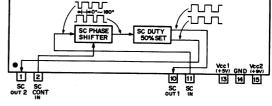
BX1338 (SONY) APC AMPLIFIER AND SC 0°/180° SELECTOR — REAR VIEW —



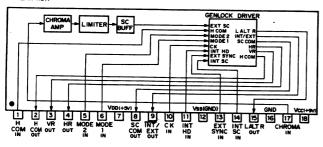
BX1339 (SONY)
BX1339A (SONY)
SC PHASE SHIFTER
— REAR VIEW —

SC PHASE SHIFTER

SC DUTY
SON SET

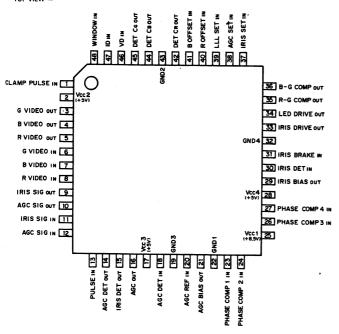


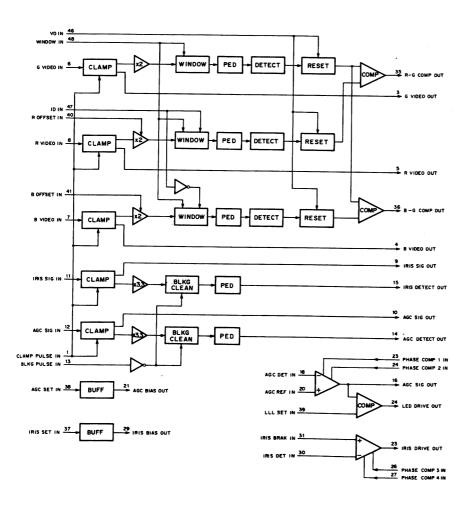
BX1340 (SONY) SC LIMITER AND GENLOCK DRIVER — REAR VIEW —



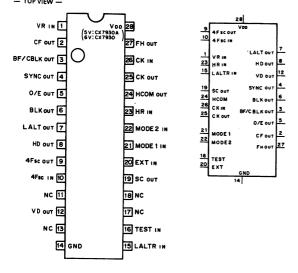








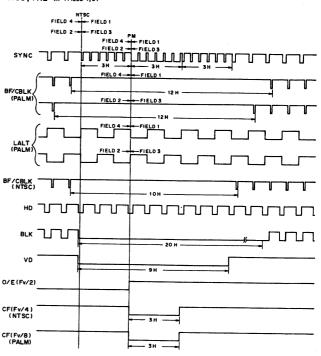


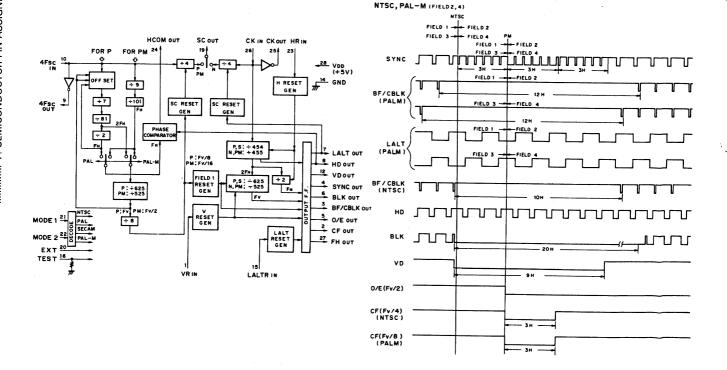


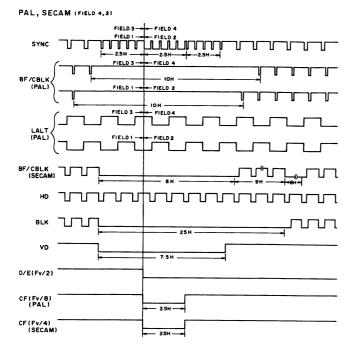
O/E :ODD/EVEN FIELD CF :COLOR FRAME PULSE HCOM:H COMPARATOR

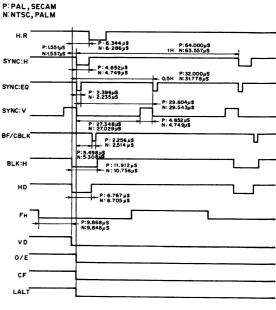
	SYSTEM	4Fsc	CLOCK		INPUTS			NPUTS		l	
	NTSC	910 FH	910FH	MODE 1	MODE 2	SYSTEM	EX	TEST	FUNCTION		
	PAL	1135 FH+2Fv	908 FH	0	0	NTSC		0	INTERNAL	١	
	PALM	909 FH	910FH	0	1	SECAM	T 0	1	INVALID	1	
	SECAM		908 FH	1	0	PALM	1	0	EXT	١	
				1	1	PAL		1	TEST	ı	
	O; LOW LEVEL (GND) 1; HIGH LEVEL (VDD)							TEST 'O": OPEN (INTERNALLY)			

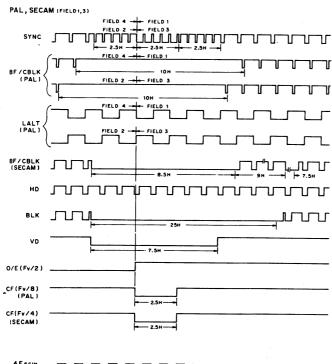
NTSC , PAL- M (FIELD 1,3)

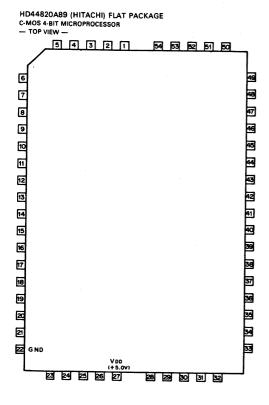


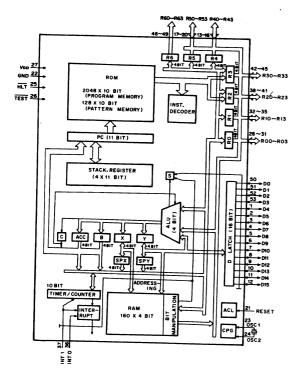


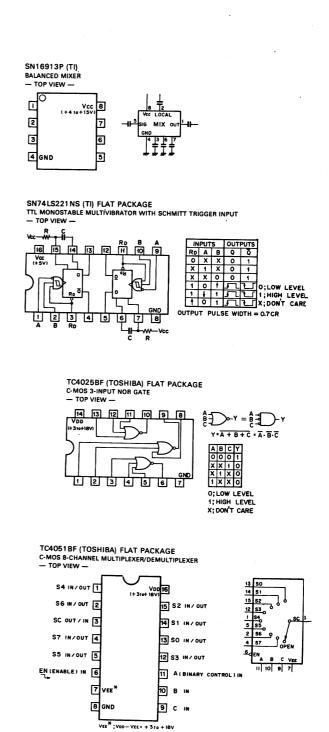


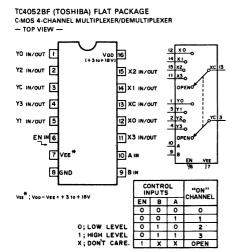


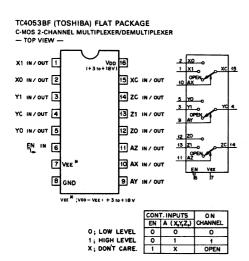


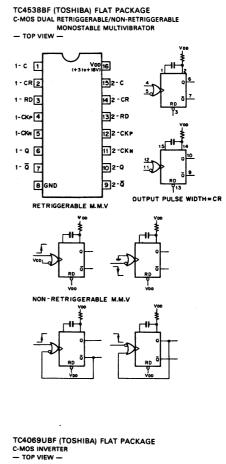


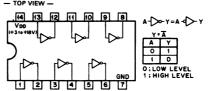


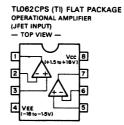












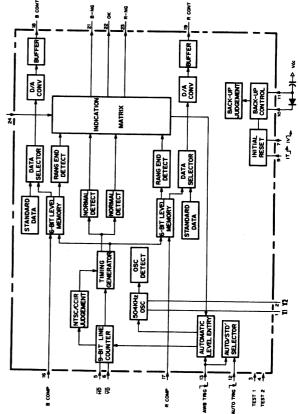
TL431CLP (TI) TL431CLPB (TI) ADJUSTABLE PRECISION SHUNT REGULATOR



uPC358G2 (NEC) FLAT PACKAGE DUAL OPERATIONAL AMPLIFIERS — TOP VIEW —



uPD6107G (NEC)
C-MOS AUTOMATIC WHITE BALANCE CONTROLLER FOR COLOR CAMERA
— TOP VIEW — XI IN I X2 OUT 2 23 TEST 1 IN 22 4 TEST 2 IN 5 20 HD IN 6 IV7_IN 7 18 8 17 ITJ*IN 9 16 B COMP IN TEST1 BUD IN 15 BUC IN П NC 4 X1 X2 AUTO CONT LIN 13 AWB TRIG L IN IV ; IT ; BUD ; BUC ; INITIAL RESET VOLTAGE
INITIAL RESET TIME CONSTANT
BACK-UP DIODE
BACK-UP CAPACITOR š



SECTION 8 SPARE PARTS

8-1. PARTS INFORMATION

1. Safety Related Component Warning

Components identified by shading marked with \triangle on the schematic diagrams, exploded views and electrical spare parts list are critical to safe operation. Replace these components with Sony parts whose parts numbers appear as shown in this manual or in service bulletins and service manual supplements published by Sony.

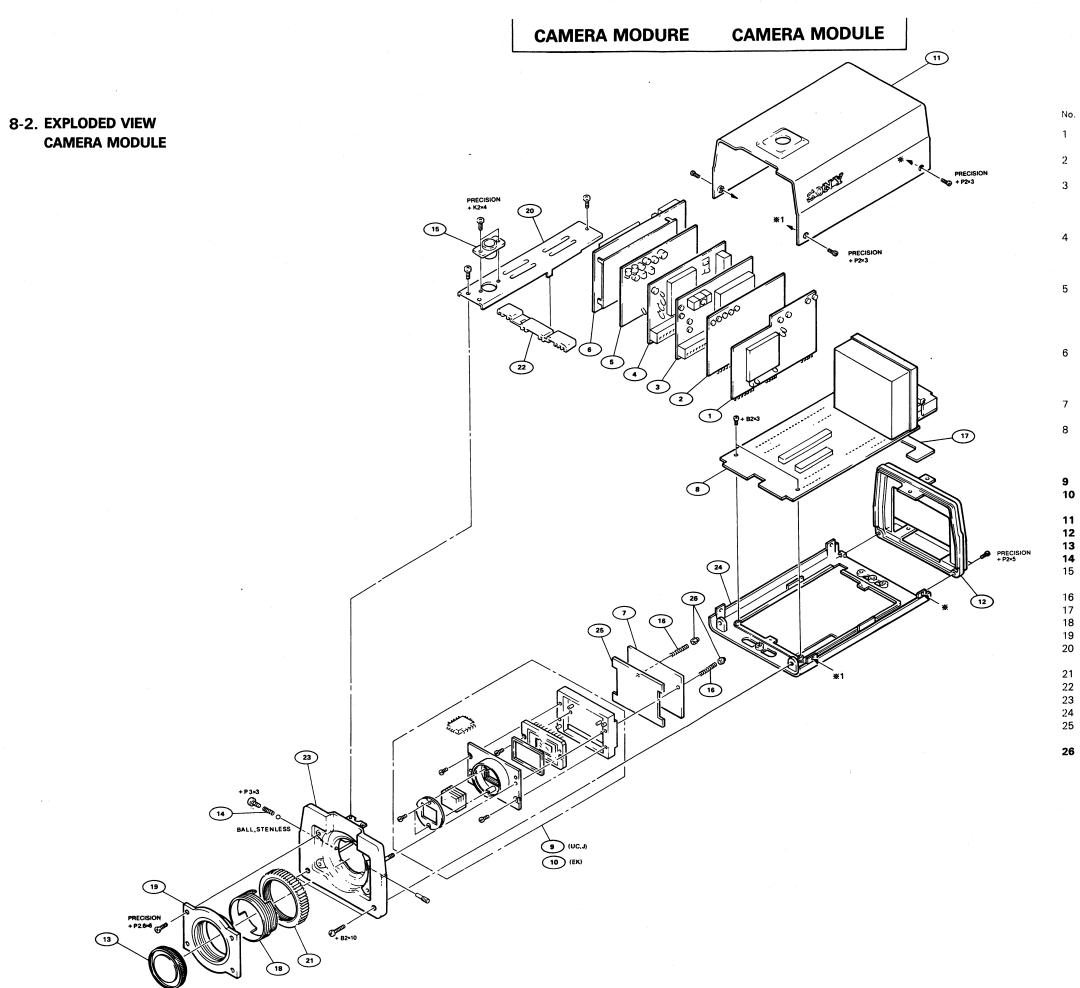
- Replacement Parts supplied from Sony Parts Center will sometimes have different shape and outside view from the parts which actually in
 use. This is due to "accommodating the improved parts and/or engineering changes" or "standardization of genuine parts."
 - This manual's exploded views and electrical spare parts lists are indicating the parts numbers of "the standardized genuine parts at present".
 - Regarding engineering parts changes in our engineering department, refer Sony service bulletins and service manual supplements.
- 3. **Printed Components in Bold-Face type** on the exploded views and electrical spare parts list are normally stocked for replacement purposes. The remaining parts are not normally required for routine service work. Orders for parts not shown in Bold-Face type will be processed, but allow for additional delivery time.
- 4. Item with no part number and/or no description are not stocked because they are seldom required for routine service.

5. Abbreviation

REF. NO.	DESCRIPTION	REF. NO.	DESCRIPTION	REF. NO.	DESCRIPTION
С	CAPACITOR	F	FUSE	Q	TRANSISTOR
CN	CONNECTOR	FL	FILTER	R	RESISTOR
D	DIODE	IC	IC	RV	VARIABLE RESISTOR
DL	DELAY LINE	L	INDUCTOR	S	SWITCH
			· · · · · · · · · · · · · · · · · · ·	X	OSCILI ATOR

All capacitors are in micro farads unless otherwise specified. All inductors are in micro henries unless otherwise specified.

All resistors are in ohms.



8-3

Parts No.

Description

A-7513-323-A MOUNTED CIRCUIT BORAD

A-7513-324-A MOUNTED CIRCUIT BORAD

A-7513-325-A MOUNTED CIRCUIT BORAD

A-7513-326-A MOUNTED CIRCUIT BORAD

A-7513-327-A MOUNTED CIRCUIT BORAD

A-7513-328-A MOUNTED CIRCUIT BORAD

A-7513-329-A MOUNTED CIRCUIT BORAD

A-7513-330-A MOUNTED CIRCUIT BORAD

A-7513-331-A MOUNTED CIRCUIT BORAD

A-7513-332-A MOUNTED CIRCUIT BORAD

A-7520-231-A MOUNTED CIRCUIT BORAD

A-7520-233-A MOUNTED CIRCUIT BORAD

A-7520-234-A MOUNTED CIRCUIT BORAD

A-7560-026-A CCD BLOCK ASSY (UC, J)

A-7560-027-A CCD BLOCK ASSY (EK)

X-3698-801-1 COVER ASSY X-3698-802-1 PANEL ASSY, REAR

2-042-385-00 CAP, C MOUNT 3-563-463-00 SPRING, COMPRESSION

3-670-518-01 SCREW, TRIPOD

3-698-810-01 RING, SLIDE 3-698-811-01 MOUNT, LENS

3-698-813-02 SPAN

3-698-802-01 SPRING, COMPRESSION

3-698-814-01 RING, ADJUSTMENT

3-698-819-01 HOLDER, PC BOARD

3-698-806-02 SHEET, INSULATING, CCD HOLDER

3-698-840-01 PANEL, FRONT

3-698-842-01 CHASSIS

3-698-829-01 NUT

3-698-805-02 SHEET, INSULATING, MB

"AT-40"

"MD-30" (UC, J)

"MD-30" (EK)

"EN-40" (UC, J)

"RG-13" (UC, J)

"PG-12" (UC, J)

"MB-37" (UC, J)

"MB-37" (EK)

"PG-12" (EK)

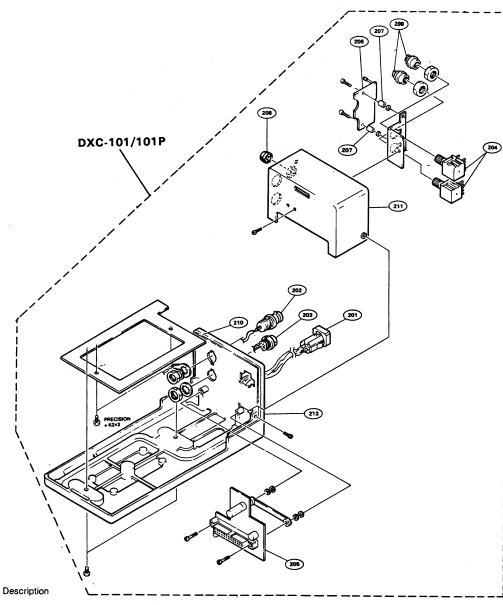
"BI-3"

"EN-40" (EK)

"RG-13" (EK)

DXC-101/102/101P/102P (UC, EK)

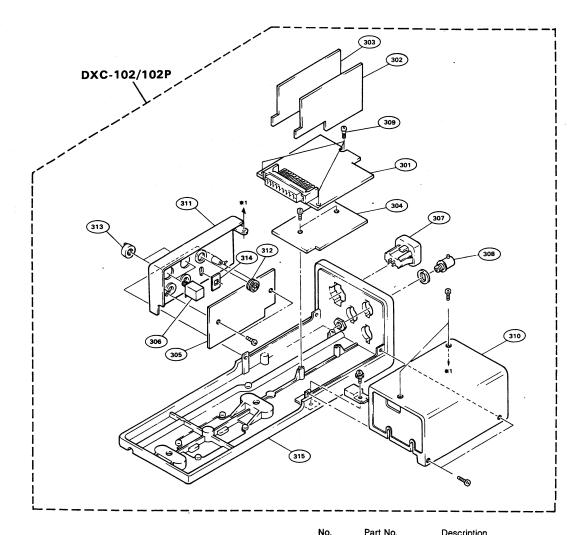
ADAPTOR ASSY



No.	Parts No.	Description	_
201	1-563-113-11	RECEPTACLE,	LENS
202	1-561-781-21	RECEPTACLE,	BNC
203	1-562-381-00	RECEPTACLE,	12P
204	1-570-505-11	ROTARY, SWI	TCH
500000000000000000000000000000000000000		ec.	,

∆ 205	1-617-217-11 PI	RINTED CIRCUIT BOARD
		"CN-39

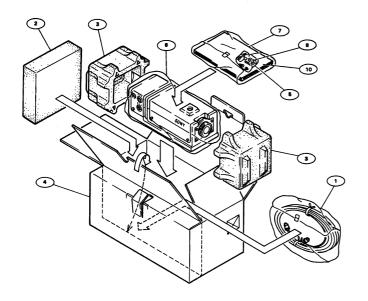
206	1-617-218-11	PRINTED CIRCUIT BOARD ''SW-33'
207 208 209	3-676-244-01 3-698-809-01	GUAIDE, BOTTON COVER, SWITCH KNOB
210 211 212	3-698-834-01 3-698-837-01 3-698-843-02	PLATE, CHASSIS COVER(A), ADAPTOR ADAPTOR (A)'



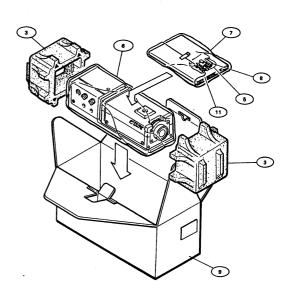
NO.	Fait No.	Description	
301	A-7513-329-A	MOUNTED CIRCUIT BORAD	
	A-7513-350-A	MOUNTED CIRCUIT BOARD	"MB-38" (EK)
302	A-7513-351-A	MOUNTED CIRCUIT BORAD	''RM-32''
303	A-7513-352-A	MOUNTED CIRCUIT BORAD	"SG-38" (UC)
	A-7513-353-A	MOUNTED CIRCUIT BOARD	"SG-38" (EK)
304	A-7513-354-A	MOUNTED CIRCUIT BORAD	"SG-110"
305	A-7513-355-A	MOUNTED CIRCUIT BORAD	''SW-34''
306	1-570-505-11	ROTARY, SWITCH	
307	1-563-113-11	CONNECTOR, LENS	
308	1-561-781-11	BNC, CONNECTOR	
309	3-312-161-00	SCREW, STEP, PRECISION	
310	3-698-863-01	COVER,ADAPTOR(R)	
311	3-698-864-02	COVER,ADAPTOR(L)	
312	3-676-244-01	COVER, SW	
313	3-689-809-01	KNOB	
314	3-680-604-11	PLATE, BLIND	
315	3-698-865-01	ADAPTOR (B)	

8-3. PACKING MATERIAL AND ACCESSORIES

DXC-101/101P



DXC-102/102P



No.	Parts No.	Description
1		CABLE, DC 4P RECEPTACLE 4P RECEPTACLE 12P
2		SPACER (DXC-101/P)
3	3-698-850-01	,
4	3-698-851-01	CARTON INDIVIDUAL (UC)
		CARTON INDIVIDUAL (EK)
5	3-701-613-00	
		SCREW)
6	3-701-626-00	BAG, POLYETHYLENE (DXC-101/P)
	3-701-631-01	BAG, POLYETHYLENE (DXC-102/P)
7	3-701-626-00	BAG, POLYETHYLENE (PRINTED
		MATTER)
8	3-698-830-01	STOPER
	7-621-772-00	SCREW + B2 x 3
9	3-698-854-01	CARTON INDIVIDUAL (UC)
	3-698-854-11	CARTON INDIVIDUAL (EK)
10	3-760-863-11	MANUAL, INSTRUCTION (DXC-101/P)
	3-760-863-31	MANUAL, INSTRUCTION
		(DXC-101/P)
	3-760-863-41	MANUAL, INSTRUCTION (EK)
		(DXC-101/P)
11	3-760-924-11	MANUAL, INSTRUCTION
		(DXC-102/P)
	3-760-924-31	MANUAL, INSTRUCTION
		(DXC-102/P)
	3-760-924-41	MANUAL, INSTRUCTION
		(DXC-102/P)

8-4. ELECTRICAL PARTS LIST

RESISTOR

Parts that are \underline{not} listed in the "reference numbers order list" are shown in following table. Reference numbers are omitted.

CHIP RESISTOR



 \pm 5% 1/10W 0Ω through 3.3MΩ

- Parts No. 1-216-□□□-00 -

Value	Parts No.	
0Ω	295	
1Ω		
1.1		
1.2		
1.3		
1.5		
1.6		
1.8		
2		
2.2	298	
2.4	301	
2.7	302	
3	303	
3.3	304	
3.6	305	
3.9	306	
4.3	307	
4.7	308	
5.1	297	
5. 6	309	
6.2	310	
6.8	311	
7.5	312	
8.2	313	
9.1	314	
10Ω	001	_
11	002	\vdash
12	003	
13	004	
15	005	
16	006	
18	007	
20	800	
22	009	-
24	010	
27	011	1
		Ь

Value	Parts No.		
30	012		
33 Ω	013		
36	014		
39	015		
43	016		
47	017		
51	018		
56	019		
62	020		
68	021		
75	022		
82	023		
91	024		
100Ω	025		
110	026		
120	027		
130	028		
150	029		
160	030		
180	031		
200	032		
220	033		
240	034		
270	035		
300	036		
330	037		
360	038		
390	039		
430	040		
470	041		
510	042		
560	043		
620	044		
680	045		
750	046		
820	047		

	T
Value	Parts No.
	- 000 -
910	048
1kΩ.	049
1.1	050
1.2	051
1.3	052
1.5	053
1.6	054
1.8	055
2	056
2.2	057
2.4	058
2.7	059
3	060
3.3	061
3.6	062
3.9	063
4.3	064
4.7	065
5.1	066
5.6	067
6.2	068
6.8	069
7.5	070
8.2	071
9.1	072
10kΩ	073
11	074
12	075
13	076
15	077
16	078
18	079
20	080
22	081
24	082
27	083

	Parts No.		
Value	- 000 -		
30	084		
33kΩ	085		
36	086		
39	087		
43	088		
47	089		
51	090		
56	091		
62	092		
68	093		
75	094		
82	095		
91	096		
100kΩ	097		
110	098		
120	099		
130	100		
150	101		
160	102		
180	103		
200	104		
220	105		
240kΩ	106		
270	107		
300	108		
330 360	109		
	110		
390 430	111 112		
430	113		
510	114		
560	115		
620	116		
680	117		
750	118		
820	119		

Value	Parts No. — — — —
910	120
1ΜΩ	121
1.1	122
1.2	123
1.3	124
1.5	125
1.6	126
1.8	127
2	128
2.2	129
2.4	13 O
2.7	131
3	132
3.3	133

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
AT-40	BOARD		Q1	8-729-901-04	DTA114EK
			02	8-729-100-66	2SC1623
	Δ-7513-324-Λ	MOUNTED CIRCUIT BOARD	Ω6	8-729-100-76	-
	A 7010 024-A	"AT-40"	0.7	8-729-100-76	
		A1-40	Ω8	8-729-100-66	
			40	0-729-100-00	230 1023
			Q9	8-729-100-76	2SA812
C1	1-135-091-00	TANTALUM CHIP 1 10% 16V	Q10	8-729-100-76	2SA812
C2	1-135-096-21	TANTALUM CHIP 4.7 10% 10V	Q11	8-729-100-76	2SA812
C4	1-135-095-21	TANTALUM CHIP 1.5 10% 10V	Q12	8-729-100-66	2SC1623
C5	1-135-097-00	TANTALUM CHIP 15 10% 10V	Q13	8-729-100-66	2SC1623
C6	1-135-072-21	TANTALUM CHIP 0.22 10% 35V			
			Q15	8-729-900-00	DTA144WK
C7	1-135-096-21	TANTALUM CHIP 4.7 10% 10V	Q16	8-729-901-03	DTC144WK
C8	1-163-038-00	CERAMIC CHIP 0.1 25V			
C9	1-135-096-21	TANTALUM CHIP 4.7 10% 10V			
C10	1-163-038-00	CERAMIC CHIP 0.1 25V			
C11	1-163-141-00	CERAMIC CHIP 0.001 5% 50V	R58	1-249-437-11	CARBON 47K 5% 1/6W
					01 S/N Up to 10220 \
C12	1-163-038-00	CERAMIC CHIP 0.1 25V			22 S/N Up to 10180
C13		CERAMIC CHIP 0.1 25V			11P S/N Up to 10260
C14		CERAMIC CHIP 0.1 25V			22P S/N Up to 10310
C15		CERAMIC CHIP 0.1 25V			CHIP 47K 5% 1/10W
C16		CERAMIC CHIP 0.1 25V			01 S/N 10221 AND HIGHER \
0.0		OZINAMIO OI III O. I ZOV			2 S/N 10181 AND HIGHER
C17	1-135-096-21	TANTALUM CHIP 4.7 10% 10V		1	OTP S/N 10261 AND HIGHER
C18		TANTALUM CHIP 10 20% 16V			2P S/N 10311 AND HIGHER
C19		CERAMIC CHIP 0.001 5% 50V		(21 ON TOSTT AND THEIR
C20		CERAMIC CHIP 0.001 5% 50V			
C21		CERAMIC CHIP 0.001 5% 50V			
			RV1	1-230-871-21	METAL 22V
C22	1-163-038-00	CERAMIC CHIP 0.1 25V	RV2	•	
C23		CERAMIC CHIP 100PF 5% 50V	RV2 RV3	1-230-870-21	
C24		CERAMIC CHIP 0.1 25V		1-230-870-21	
C27		CERAMIC CHIP 0.1 25V	RV4	1-230-868-21	
C27		TANTALUM CHIP 0.1 20% 35V	RV5	1-230-870-21	METAL 10K
020	1-139-070-00	TANTALOM CHIP U. 1 20% 35V			
D3	8-719-100-03	1\$2835			
D4	8-719-100-05	1\$2837			
IC1	8-759-908-12	CX20056: SONY			
IC2		μPD6107G: NEC			

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
BI-3 B	OARD		EN-40	BOARD	
	A-7520-231-A	MOUNTED CIRCUIT BOARD "BI-3"		A-7513-327-A	MOUNTED CIRCUIT BOARD
04				A-7513-328-A	"EN-40" (UC,J) MOUNTED CIRCUIT BOARD "EN-40" (EK)
C1 C2		TANTALUM CHIP 0.47 10% 25V			LIV 40 (ER)
C3		TANTALUM CHIP 0.47 10% 25V TANTALUM CHIP 0.47 10% 35V			
C4		TANTALUM CHIP 3.3 10% 4V	04		
C5		TANTALUM CHIP 0.47 10% 35V	C1	1-131-380-00	TANTALUM 33 10% 10V
			C2	1-131-374-00	TANTALUM 33 10% 16V
C6	1-135-083-00	TANTALUM CHIP 0.47 10% 25V	C3 C4		ELECT 100 20% 6.3V
C7		CERAMIC CHIP 0.0022 10% 50V	C5	1-163-038-00	CERAMIC CHIP 0.1 25V
			CS	1-163-097-00	CERAMIC CHIP 15PF 5% 50V
			C6	1-131-373-00	TANTALUM 22 10% 16V
			C7	1-131-380-00	TANTALUM 33 10% 10V
Q1	8-729-175-73	2SC2757	C8	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
			C9		CERAMIC CHIP 0.1 25V
			C10		TANTALUM 10 10% 10V
•			C11	1-163-038-00	CERAMIC CHIP 0.1 25V
			C12	1-163-038-00	CERAMIC CHIP 0.1 25V
			C13	1-163-119-00	CERAMIC CHIP 120PF 5% 50V
			C14	1-163-119-00	CERAMIC CHIP 120PF 5% 50V
			C15	1-163-119-00	CERAMIC CHIP 120PF 5% 50V
			C16	1-163-038-00	CERAMIC CHIP 0.1 25V
			C17	1-163-129-00	CERAMIC CHIP 330PF 5% 50V (EK) (DXC-101P S/N 10061 AND HIGHER) (DXC-102P S/N 10011 AND HIGHER)
			CN1 CN2	1-561-770-00 1-564-012-00	RECEPTACLE, 30P MALE RECEPTACLE, 2P MALE
			D1 D2 D3	8-719-100-05 8-719-104-24 8-719-100-05	1S2837 1S2835
			DL1	1-415-463-11	150nS

			PU1	1-464-580-11	CONVERTER, DC-DC UNIT
C1 C2 C3	1-163-035-00	CERAMIC CHIP 0.047 50V CERAMIC CHIP 0.047 50V CERAMIC CHIP 0.001 5% 50V	CN6 CN7 CN8		RECEPTACLE, 2P MALE RECEPTACLE, 2P FEMALE RECEPTACLE, 2P FEMALE
	1-617-767-21	PRINTED CIRCUIT BOARD "LE-47B" (DXC-102/102P)	CN4 CN5	1-564-867-11 1-564-858-11	
	1-617-767-11	PRINTED CIRCUIT BOARD ''LE-47A'' (DXC-101/101P)	CN3	1-564-026-00	PLUG CONTACT RECEPTACLE, 20P MALE
LE-47	BOARD	PRINTED CIRCUIT DOADS	CN1 CN2	1-564-001-11	RECEPTACLE, 50P MALE RECEPTACLE, 2P MALE PLUG HOUSING 2P
			0.2		CENAMIC SSUPP 10% SUV (EK)
			C10 C11 C12	1-102-112-00	CERAMIC CHIP 0.1 25V CERAMIC 330PF 10% 50V CERAMIC 330PF 10% 50V (EK)
			C9		TANTALUM CHIP 6.8 10% 6.3V CERAMIC CHIP 0.1 25V
RV1	1-230-868-11	METAL 2.2 K	C7 C8	1-163-034-00	CERAMIC CHIP 0.033 50V
			C5 C6	1-163-101-00	CERAMIC CHIP 22PF 5% 50V ELECT 33 10% 16V
Q8	8-729-100-66	2SC1623	C4	1-163-101-00	CERAMIC CHIP 22PF 5% 50V
Q6 Q7	8-729-109-44 8-729-100-76	2SA812		1-163-249-11	(DXC-102 S/N 10711 AND HIGHER) CERAMIC CHIP 75PF 5% 50V (EK)
Q5	8-729-100-76			1-163-109-00	CERAMIC CHIP 47PF 5% 50V (UC) / DXC-101 S/N 11181 AND HIGHER
Q4	8-729-100-66 8-729-100-66	2SC1623			DXC-101 S/N Up to 11180 DXC-102 S/N Up to 10710
Q2 Q3	8-729-100-66		C3	1-163-101-00	CERAMIC CHIP 22PF 5% 50V (UC)
Q1	8-729-100-66		C1 C2		TANTALUM CHIP 10 10% 16V TANTALUM CHIP 10 10% 16V
IC2		BH1205: SONY			''MB-37'' (EK)
IC1	8-759-969-13	SN16913P: TI		A-7520-234-A	"MB-37" (UC,J) MOUNTED CIRCUIT BOARD
	. 100 400 11	DANS FACO THOMAS (EIX)		A-7520-233-A	MOUNTED CIRCUIT BOARD
FL1 FL1		BAND PASS 3.58MHz (UC,J) BAND PASS 4.43MHz (EK)	MB-37	BOARD	
Ref. No.	Part No.	Description	Ref. No.	Part No.	Description

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
Q1 Q2	8-729-100-76 8-769-401-84		MD-30	BOARD	
		01 S/N Up to 10220 \ 02 S/N Up to 10030		A-7513-325-A	MOUNTED CIRCUIT BOARD
	EK: DXC-1	01P S/N Up to 10060 02P S/N Up to 10010		A-7513-326-A	"MD-30" (UC,J) MOUNTED CIRCUIT BOARD
	8-769-401-67	′ 3SK163-1			''MD-30'' (EK)
		01 S/N 10221 AND HIGHER \			
		02 S/N 10031 AND HIGHER			
		01P S/N 10061 AND HIGHER / 02P S/N 10011 AND HIGHER /	C1	1-131-375-00	TANTALUM 4.7 10% 10V
O3	8-729-100-66		C2	1-131-374-00	TANTALUM 33 10% 16V
Q4	8-729-100-76		C3 C4		CERAMIC CHIP 0.1 25V
Q5	8-769-401-84		C5	1-163-101-00	CERAMIC CHIP 22PF 5% 50V CERAMIC CHIP 22PF 5% 50V
	/UC: DXC-1	01 S/N Up to 10220 \	03	1-103-101-00	CENAMIC CHIP 22PF 5% 50V
		02 S/N Up to 10030	C6	1-163-101-00	CERAMIC CHIP 22PF 5% 50V
		01P S/N Up to 10060	C7	1-163-101-00	CERAMIC CHIP 22PF 5% 50V
	8-769-401-67	02P S/N Up to 10010 /	C8	1-163-101-00	CERAMIC CHIP 22PF 5% 50V
		01 S/N 10221 AND HIGHER \	C9	1-131-357-00	TANTALUM 4.7 10% 25V
		02 S/N 10031 AND HIGHER	C10	1-163-101-00	CERAMIC 22PF 5% 50V
		01P S/N 10061 AND HIGHER	C11	1-163-038-00	CERAMIC CHIP 0.1 25V
		02P S/N 10011 AND HIGHER/			
Q6	8-729-109-44	26804			
Q7	8-729-100-76		CN1	1-563-114-11	RECEPTACLE, 20P MALE
Q8	8-769-401-84				
	/UC: DXC-10	01 S/N Up to 10220 \			
		02 S/N Up to 10030	FL1	1-235-394-11	LOW PASS 4.773MHz (UC,J)
		01P S/N Up to 10060	FL1	1-235-442-11	LOW PASS 0-25MHZ (EK)
		02P S/N Up to 10010/			Total Control of Dominia (ERC)
	8-769-401-67	35K163-1 D1 S/N 10221 AND HIGHER \			
		D2 S/N 10031 AND HIGHER			
		O1P S/N 10061 AND HIGHER	IC1		TL431CLP: TI
	DXC-10	D2P S/N 10011 AND HIGHER	IC2	1-807-385-11	BH1206: SONY
Q9	8-729-109-44				
Q10	8-729-100-66	2SC1623			
Q11	8-729-100-66	2501622	L1	1-408-399-00	MICRO 1.5
012	8-729-100-66		L2	1-408-409-00	MICRO 10
Q13	8-729-100-66				
Q14	8-729-100-66				
Q15	8-729-100-66	2SC1623	Q1	8-729-100-66	2SC1623
				8-729-100-76	
Q16	8-729-100-66		O3	8-729-100-66	2SC1623
Q17 Q18	8-729-100-76 8-729-100-76			8-729-100-66	
Q19	8-729-100-76		Q5	8-729-102-76	2SA812
020	8-729-100-76		06	0 700 400 00	
021	8-729-100-76			8-729-100-66 8-729-100-66	
				8-729-100-66 8-729-100-66	
				B-729-100-66	
				8-729-100-66	
R48	1-215-493-00	CARBON 1M 5% 1/4W (UC)			
	(DXC-101 S/N 10221 AND HIGHER			
	`	DXC-102 S/N 10031 AND HIGHER	D) / 4		
				1-230-870-21	
				1-230-870-21	
R48	1-215-491-00	CARBON 820K 5% 1/4W (EK)		1-230-870-21 1-230-870-21	
	1	DXC-101P S/N 10061 AND HIGHER		I-230-870-21	
	(DXC-102P S/N 10011 AND HIGHER	-		THE TOIL

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
PR-72	BOARD		C24	1-163-125-00	CERAMIC CHIP 220PF 5% 50V
	A-7513-323-A	MOUNTED CIRCUIT BOARD "PR-72"			UC: DXC-101 S/N 10831 AND HIGHER DXC-102 S/N 10611 AND HIGHER
					EK: DXC-101P S/N 11081 AND HIGHER
C1	1-131-371-00	TANTALUM 10 10% 16V			DXC-102P S/N 10921 AND
C2		CERAMIC CHIP 0.1 25V			\ HIGHER /
C3		CERAMIC CHIP 0.1 25V	C25	1-163-129-00	CERAMIC CHIP 330PF 5% 50V
C4		TANTALUM 33 10% 10V			/UC: DXC-101 S/N 10831 AND
C5	1-163-085-00	CERAMIC CHIP 2PF ±0.25PF 50V			HIGHER DXC-102 S/N 10611 AND
C6	1-163-218-11	CERAMIC CHIP 1.5PF ±0.25PF 50V			HIGHER
C7		CERAMIC CHIP 7PF ±0.25PF 50V			EK: DXC-101P S/N 11081 AND
C8		CERAMIC CHIP 0.1 25V			HIGHER /
C9		TANTALUM 1 10% 35V			DXC-102P S/N 10921 AND
C10	1-163-038-00	CERAMIC CHIP 0.1 25V			\ HIGHER /
C11		CERAMIC CHIP 0.1 25V	D1	8-719-100-05	162027
C12		TANTALUM CHIP 22 10% 6.3V	ы	6-719-100-05	192637
C13 C14		TANTALUM 10 10% 16V			
C14		TANTALUM 10 10% 16V TANTALUM CHIP 22 10% 6.3V	IC1	8-759-201-00	TC4052BF: TOSHIBA
0.0	1 100-101-21	TAILTALON OTH 22 10/0 0.34	IC2		TC4052BF: TOSHIBA
C16	1-135-101-21	TANTALUM CHIP 22 10% 6.3V	IC3		μPC358G2: NEC
		/UC: DXC-101 S/N Up to 10120 \	IC4	1-807-383-13	BH1204: SONY
		DXC-102 S/N Up to 10180			
		EK: DXC-101P S/N Up to 10260	Q1	8-729-100-66	2501623
C17	1-163-255-00	DXC-102P S/N Up to 10310 / CERAMIC CHIP 150PF 5% 50V	02	8-729-100-66	
C18		CERAMIC CHIP 24PF 5% 50V	QЗ	8-729-100-66	
C19		CERAMIC CHIP 2PF ±0.25PF 50V	Q4	8-729-109-44	2SK94
C20		TANTALUM CHIP 2.2 10% 6.3V	Q5	8-729-109-44	2SK94
		/UC: DXC-101 S/N Up to 10830 \	Q6	8-729-100-66	2SC1623
		DXC-102 S/N Up to 10610	Q7	8-729-100-66	· · · · ·
		EK: DXC-101P S/N Up to 11080	Q8	8-729-100-66	2SC1623
	1-135-101-21	DXC-102P S/N Up to 10920/ TANTALUM CHIP 22 10% 6.3V	Q9	8-729-100-66	
		/UC: DXC-101 S/N 10831 AND	Q10	8-729-100-66	2SC1623
		/ HIGHER \	Q11	8-729-100-66	2SC1623
		DXC-102 S/N 10611 AND	Q12	8-729-109-44	
		HIGHER	Q13	8-729-100-66	
		EK: DXC-101P S/N 11081 AND	Q14	8-729-100-66	2SC1623
		HIGHER DXC-102P S/N 10921 AND		DXC-10	1 S/N 10221 AND HIGHER \ 2 S/N 10181 AND HIGHER
		HIGHER		EK: DXC-10	1P S/N 10261 AND HIGHER
		,		DXC-10	2P S/N 10311 AND HIGHER
C21	1-124-444-00	ELECT 220 20% 6.3V			·
		UC: DXC-101 S/N Up to 10830 DXC-102 S/N Up to 10610	R12	1-214-590-00	METAL 24K 1% 1/8W
		EK: DXC-101P S/N Up to 11080	R13	1-214-589-00	METAL 22K 1% 1/8W
		DXC-102P S/N Up to 10920	R14	1-214-584-00	METAL 13K 1% 1/8W
C22	1-135-076-21	TANTALUM CHIP 1 10% 35V	R15	1-214-585-00	METAL 15K 1% 1/8W
		/UC: DXC-101 S/N 10831 AND	R18	1-214-584-00	METAL 13K 1% 1/8W
		HIGHER	R19	1-214-585-00	METAL 15K 1% 1/8W
		DXC-102 S/N 10611 AND HIGHER	R20	1-214-584-00	METAL 13K 1% 1/8W
		EK: DXC-101P S/N 11081 AND	R21	1-214-586-00	METAL 16K 1% 1/8W
		HIGHER			
		DXC-102P S/N 10921 AND	RV1	1-230-870-21	METAL 10K
		\ HIGHER /	RV2	1-230-870-21	
			RV3	1-230-870-21	
			RV4	1-230-870-21	METAL 10K
			RV5	1-230-870-21	METAL 10K
D			RV6	1-230-871-21	
DXC-101	I/102/101P/102I	P (UC. EK)	8-13		

F	Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
F	PG-12	BOARD		D1	8-719-100-05	162027
				D2	8-719-100-05	
		A-7513-331-A	MOUNTED CIRCUIT BOARD	D3	8-719-100-05	
			"PG-12" (UC,J)	D4	8-719-100-03	
		A-7513-332-A	MOUNTED CIRCUIT BOARD			
			''PG-12'' (EK)			
			•	IC1		CX7930-1: SONY
C	:1	1-163-093-00	CERAMIC CHIP 10PF 5% 50V (UC,J)	IC2	1-807-382-11	BH1203: SONY
-	:1	1-163-241-11	CERAMIC CHIP 10PF 5% 50V (UC,J) CERAMIC CHIP 39PF 5% 50V (EK)			
	2	1-163-097-00	CERAMIC CHIP 15PF 5% 50V (EK)			
C	2	1-163-099-00	CERAMIC CHIP 18PF 5% 50V (EK)	L1	1-408-399-00	MICPO 1 5
C	3	1-163-093-00	CERAMIC CHIP 10PF 5% 50V	L2	1-408-399-00	
			•	L3	1-408-728-21	
_	4	1-163-093-00	CERAMIC CHIP 10PF 5% 50V			
	5	1-163-093-00	CERAMIC CHIP 10PF 5% 50V			
	6		CERAMIC CHIP 10PF 5% 50V			
	:7 :8	1-163-109-00	CERAMIC CHIP 47PF 5% 50V	Q1	8-729-100-66	2SC1623
C	•	1-163-093-00	CERAMIC CHIP 10PF 5% 50V	Q2	8-729-100-76	
c	9	1-162-119 00	CEDARNO CUID 12005 1007 5017	Q3	8-729-122-63	
•		1-103-119-00	CERAMIC CHIP 120PF 10% 50V	Q4	8-729-102-06	2SC2223
С	9	1-163-247-00	(UC,J) CERAMIC CHIP 68PF 5% 50V (EK)			
	10	1-163-109-00	CERAMIC CHIP 47PF 5% 50V (UC,J)			
С	10	1-163-111-00	CERAMIC CHIP 56PF 5% 50V (EK)	R35	1-249-405-11	CARBON 100 1/4W (EK)
C	11	1-163-141-00	CERAMIC CHIP 0.001 5% 50V			CAMBON 100 1/4W (ER)
С	12	1-163-251-00	CERAMIC CHIP 100PF 5% 50V			
	13	1-163-038-00	CERAMIC CHIP 0.1 25V			
	14	1-163-109-00	CERAMIC CHIP 47PF 5% 50V	VCO1	1-567-549-11	28.63636MHz (UC,J)
		1-163-141-00	CERAMIC CHIP 0.001 5% 50V	VCO1	1-567-550-11	28.375MHz (EK)
C	16	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
C	17	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
		1-163-105-00	CERAMIC CHIP 33PF 5% 50V (UC,J)			
	19	1-163-109-00	CERAMIC CHIP 47PF 5% 50V (EK)			
C	20	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
C	21	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
_						
	22 23	1-163-038-00	CERAMIC CHIP 0.1 25V			
	23 24	1-103-141-00	CERAMIC CHIP 0.001 5% 50V TANTALUM CHIP 1 10% 16V			
	25	1-135-051-00	TANTALUM CHIP 1 10% 16V TANTALUM 22 10% 10V			
	26	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
-	-					
C	27	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
	28	1-163-109-00	CERAMIC CHIP 47PF 5% 50V			
C2	29	1-163-087-00	CERAMIC CHIP 4PF 0.25PF 50V (EK)			
			DXC-101P S/N Up to 12080	,		
			DXC-102P S/N Up to 11070			
		1-163-101-00	CERAMIC CHIP 22PF 5% 50V (EK)			
			DXC-101P S/N 12081 AND HIGHER			
СЗ	10	1-163-109-00	DXC-102P S/N 11071 AND HIGHER CERAMIC CHIP 47PF 5% 50V (EK)			
C3	1	1-163-105-00	CERAMIC CHIP 33PF 5% 50V (EK)			
			Of iii OOI I 0/0 00 V			
СЗ	2	1-163-105-00	CERAMIC CHIP 33PF 5% 50V			
СЗ	3	1-163-101-00	CERAMIC CHIP 22PF 5% 50V (UC.J)			
C3	4	1-163-034-00	CERAMIC CHIP 0.033 50V			
C3	5	1-135-093-21	TANTALUM CHIP 10 10% 16V			
C3	6	1-131-345-00	TANTALUM CHIP 0.47 1% 35V			
СЗ	8 '	1.163-262-00	CERAMIC CHIP 330PF 5% 50V			
C3	9 '	1-163-038-00	CERAMIC CHIP 330PF 5% 50V CERAMIC CHIP 0.1 25V			
C4	O 1	1-161-021-11	CERAMIC 0.047 10% 25V (EK)			
-			(ER)			

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
RG-13	BOARD		L1 L2	1-408-409-00	
	A-7513-329-A	MOUNTED CIRCUIT BOARD	L3	1-408-417-21 1-408-417-21	MICRO 47
	A-7513-330-A	"RG-13" (UC,J) MOUNTED CIRCUIT BOARD	L4	1-408-416-00	MICRO 39 (EK)
		''RG-13'' (EK)			
			Q1	8-729-100-76	2SA812
C1	1 162 029 00	CERAMIC CHIP 0.1 25V	02	8-729-100-66	
C2		ELECT 10 20% 35V	Ω3 Ω4	8-729-109-44 8-729-100-66	- ·
C3		CERAMIC CHIP 0.1 25V	Q5	8-729-175-73	
C4	1-124-236-00	ELECT 47 20% 16V			
		UC: DXC-101 S/N Up to 10220 \ DXC-102 S/N Up to 10180			
		EK: DXC-101P S/N Up to 10260	RV1	1-228-395-11	METAL 10K (UC,J)
	•	DXC-102P S/N Up to 10310	RV1		METAL 10K (EK)
	1-124-584-00	ELECT 100 20% 10V	RV2	1-228-395-11	METAL 10K (UC,J)
		UC: DXC-101 S/N 10221 AND HIGHER	RV2	1-228-395-00	METAL 10K (EK)
		DXC-102 S/N 10181 AND			
		HIGHER			
		EK: DXC-101P S/N 10261 AND HIGHER	VC01	1-527-585-00	17.734475MHz (EK)
		DXC-102P S/N 10311 AND			
OF.	4 462 000 00	\ HIGHER /			
C5	1-163-038-00	CERAMIC CHIP 0.1 25V	FRAME	•	
C6		ELECT 100 20% 10V			
C7		CERAMIC CHIP 0.01 10% 50V			CCD ASSY (UC,J)
C8 C9		ELECT 10 20% 35V CERAMIC CHIP 0.01 10% 50V		A-7560-027-A	CCD ASSY (EK)
C10		ELECT 47 20% 16V			
		/UC: DXC-101 S/N Up to 10220 \			
		DXC-102 S/N Up to 10180	FIXTU	RE	
		EK: DXC-101P S/N Up to 10260		1 6020 4E0 A	EVERTICAL DO LES MENTES
	1-124-584-00	DXC-102P S/N Up to 10310 / ELECT 100 20% 10V		J-6028-450-A	EXTENTION BOARD "EX-97"
	1 124 304 00	/UC: DXC-101 S/N 10221 AND \			
		HIGHER			
		DXC-102 S/N 10181 AND			
		HIGHER EK: DXC-101P S/N 10261 AND			
		HIGHER			
		DXC-102P S/N 10311 AND			
		\ HIGHER /			
C11		CERAMIC CHIP 0.01 10% 50V			
C12		ELECT 100 20% 10V			
C13 C14		TANTALUM 10 10% 16V			
C14	1-135-093-21	CERAMIC CHIP 0.001 5% 50V (EK) TANTALUM CHIP 10 10% 16V (EK)			
0.0					
C16	1-135-097-21	TANTALUM CHIP 15 10% 10V (EK)			
C17 C18	1-163-021-00	CERAMIC CHIP 0.01 10% 50V CERAMIC CHIP 0.01 10% 50V (EK)			
C19	1-125-373-11	DOUBLE LAYERS 0.022 5.5V			
C20		CERAMIC CHIP 0.1 25V			
C21	1.163.113.00	CERAMIC CHIP 68PF 5% 50V (EK)			
U E1	1-103-113-00	CENAMIC CHIP BOPF 5% 5UV (EK)			
IC1	8-759-200-81	TC4053BF: TOSHIBA			
IC2		μPC358G2: NEC			

Ref. No.	Part No.	Description		Ref. No.	Párt No.	Description
2.50	BOARD	2000 piloti		DC-28	BOARD	
	1-617-217-11	PRINTED CIRCUIT BOARD ,	'CN-39''		1-617-768-12	PRINTED CIRCUIT BOARD "DC-28"
C1 C2 C3 C4 C5	1-131-379-00 1-131-377-00 1-124-139-00	ELECT 100 20% 16V TANTALUM 22 10% 10V TANTALUM 10 10% 10V ELECT 100 20% 10V CERAMIC CHIP 0.01 10% 50V		C1	1-163-141-00	CERAMIC CHIP 0.001 5% 50V
C6		ELECT 1000 20% 10V		SW-33	BOARD	
C7 C8	1-161-013-11	TANTALUM 10 10% 6.3V CERAMIC 0.01 10% 25V (UC: DXC-101 S/N Up to 10 EK: DXC-101P S/N Up to 10	0060/		1-617-218-11	PRINTED CIRCUIT BOARD "SW-33"
C8 `	1-163-021-00	CERAMIC CHIP 0.01 10% 50V (UC: DXC-101 S/N 10221 A HIGHER EK: DXC-101P S/N 10061 A HIGHER	ND \	CN1	1-564-018-11	RECEPTACLE, 8P MALE
		`	,	D1 D2 D3	8-719-800-33 8-719-100-03 8-719-100-03	1\$2835
CN1	1-562-715-11	RECEPTACLE, 50P FEMALE			- 7.10 .00 00	102000
D1 D2	8-719-100-03 8-719-100-05			Q1	8-729-100-76	2SA812
				S1	1-553-856-00	KEY BOARD
₫ F1	1-532-721-11	GLASS, TUBE 0.8A 125V				
				FRAME		
IC1	8-759-200-90	TC4538BF: TOSHIBA		C1	1-102-106-00	CERAMIC 100PF 10% 50V
Q1 Q2 Q3 Q4 Q5 Q6	8-729-100-76 8-729-100-76 8-729-109-44 8-729-100-76 8-729-100-66	2SA812 2SK94 2SA812 2SA812		CN102 CN103 CN104 CN200	1-564-026-00 1-563-113-11 1-561-781-21 1-562-381-00 1-562-147-11 1-562-148-11 1-564-026-00 1-562-147-11	PLUG HOUSING 8P PLUG CONTACT RECEPTACLE, 4P MALE RECEPTACLE, BNC RECEPTACLE, 12P MALE PLUG HOUSING 2P PLUG HOUSING 3P PLUG CONTACT PLUG CONTACT PLUG CONTACT
					1-570-505-11 1-570-505-11	

MB-38	Part No.	Description	Ref. No.	Part No.	Description
	BOARD		RM-32	BOARD	
Δ	∆A-7513-349-A	MOUNTED CIRCUIT BOARD ''MB-38'' (UC,J)		A-7513-351-A	TIVI 02
Δ	∆A-7513-350-A	MOUNTED CIRCUIT BOARD ''MB-38'' (EK)	C1 C2 C3	1-163-021-00	CERAMIC CHIP 0.001 5% 50V CERAMIC CHIP 0.01 10% 50V TANTALUM 2.2 20V
C1 C2 C3 C4 C5	1-124-121-00 1-131-380-00 1-163-038-00	ELECT 100 20% 35V ELECT 100 20% 35V TANTALUM 33 10% 10V CERAMIC CHIP 0.1 25V CERAMIC CHIP 0.1 25V		1-135-095-00	UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310 TANTALUM CHIP 1.5 10% 10V /UC: DXC-102 S/N 10181 AND HIGHER EK: DXC-102P S/N 10311 AND
C6 C7 C7 C8	1-163-117-00 1-163-099-00	CERAMIC CHIP 0.1 25V CERAMIC CHIP 100PF 5% 50V (UC,J CERAMIC CHIP 18PF 5% 50V (EK) ELECT 330 20% 50V	CE	1-135-076-21 1-135-070-00	HIGHER TANTALUM CHIP 1 10% 35V TANTALUM CHIP 0.1 10% 35V (UC: DXC-102 S/N Up to 10180)
C9 C10	1-124-140-00 1-163-113-00	ELECT 220 20% 10V CERAMIC CHIP 68PF 5% 50V (EK) (EK: DXC-102P S/N 10311 AND) HIGHER		1-135-076-21	EK: DXC-102P S/N Up to 10310 TANTALUM CHIP 1 10% 35V / UC: DXC-102 S/N 10181 AND HIGHER EK: DXC-102P S/N 10311 AND
C11	1-161-051-00	CERAMIC 0.01 10% 25V (UC,J)	C6	1-135-093-21	\ HIGHER / TANTALUM CHIP 10 10% 16V
CN1 CN2	1-564-001-00	RECEPTACLE, 50P MALE RECEPTACLE, 2P MALE PLUG HOUSING 2P	C7 C8 C9	1-135-093-21 1-135-093-21	TANTALUM CHIP 10 10% 16V TANTALUM CHIP 10 10% 16V CERAMIC CHIP 0.01 10% 50V
CN3	1-564-026-00 1-564-005-00 1-562-151-11	PLUG CONTACT RECEPTACLE, 6P MALE PLUG HOUSING 6P PUG CONTACT	C10 C11	1-135-076-21	TANTALUM CHIP 1 10% 35V TANTALUM CHIP 1 35V (UC: DXC-102 S/N Up to 10180 (EK: DXC-102P S/N Up to 10310
CN4 CN5		RECEPTACLE, 3P MALE RECEPTACLE, 4P MALE	D1	8-719-100-05	1\$2837
D1	8-719-100-03	1\$2835	D2 D3	8-719-100-05	
F1	1-532-721-11	GLASS TUBE 0.8A 125V		8-719-100-03	
***************************************		*	IC1 IC2	8-759-200-75 8-759-200-82	TC4025BF: TOSHIBA TC4069UBF: TOSHIBA
IC1		TC4053BF: TOSHIBA	IC3	8-759-300-40	HD44820A89: HITACHI
IC2	8-741-134-00	BX1340: SONY	IC4 IC5		TL062CPS: TI TC4051BF: TOSHIBA
L1	1-421-843-11		Q1	8-729-100-66	2501622
L3 L3		MICRO 150 (UC,J) MICRO 100 (EK)	02	8-729-100-76	2SA812
			O3	8-729-100-66	2SC1623 (UC: DXC-102 S/N Up to 10180 \ EK: DXC-102P S/N Up to 10310/
	8-729-100-76		Q4	8-729-100-66	2SC1623
	8-729-178-55				
	8-729-178-55	/ UC: DXC-102 S/N Up to 10180 \	Q5 Q6	8-729-100-66	2SC1623
02	8-729-178-55 8-729-271-22	UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310	Q5 Q6 Q7	8-729-100-66 8-729-100-66 8-729-100-76	2SC1623 2SC1623 2SA812
Q2		(UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310) 2SC1623 /UC: DXC-102 S/N 10181 AND	Q5 Q6 Q7 Q8	8-729-100-66 8-729-100-66 8-729-100-76 8-729-100-66	2SC1623 2SC1623 2SA812 2SC1623
02		(UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310) 2SC1623	Q5 Q6 Q7 Q8 Q9 Q10	8-729-100-66 8-729-100-66 8-729-100-76	2SC1623 2SC1623 2SA812 2SC1623 2SA812 2SA812
R11	8-729-271-22 1-247-855-11	UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310) 2SC1623 UC: DXC-102 S/N 10181 AND HIGHER EK: DXC-102P S/N 10310 AND	Q5 Q6 Q7 Q8 Q9 Q10 Q11	8-729-100-66 8-729-100-66 8-729-100-76 8-729-100-66 8-729-100-76 8-729-100-66 1-215-829-11	2SC1623 2SC1623 2SA812 2SC1623 2SA812 2SA812

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description .
SG-38	BOARD		SG-11	0 BOARD	
	A-7513-352-A	MOUNTED CIRCUIT BOARD		A-7513-354-A	MOUNTED CIRCUIT BOARD "SG-110"
	Δ-7513-353-Δ	"SG-38" (UC,J) MOUNTED CIRCUIT BOARD			
	7, 7010 000-7	"SG-38" (EK)	C1	1 162 020 00	
		3G-36 (EK)	C1 C2	1-163-038-00	CERAMIC CHIP 0.1 25V
			C3	1-103-021-00	CERAMIC CHIP 0.01 10% 50V TANTALUM CHIP 1 10% 16V
C1	1-163-021-00	CERAMIC CHIP 0.01 10% 50V	C4	1-163-021-00	CERAMIC CHIP 0.01 10% 50V
C2	1-163-021-00	CERAMIC CHIP 0.01 10% 50V	C5	1-135-101-21	TANTALUM CHIP 22 10% 6.3V
C3	1-163-021-00	CERAMIC CHIP 0.01 10% 50V			22 10/0 0.34
C4 C5	1-163-021-00	CERAMIC CHIP 0.01 10% 50V	C6	1-135-101-21	TANTALUM CHIP 22 10% 6.3V
CS	1-103-101-00	CERAMIC CHIP 22PF 5% 50V (UC,J)	C7	1-131-353-00	TANTALUM 10 10% 35V
C5	1-163-099-00	CERAMIC CHIP 18PF 5% 50V (EK)	C8	1-131-367-00	TANTALUM 22 10% 20V
C6	1-163-021-00	CERAMIC CHIP 18PF 5% 50V (EK) CERAMIC CHIP 0.01 10% 50V	C9	1-124-282-00	ELECT 22 20% 25V
C7	1-163-111-00	CERAMIC CHIP 56PF 5% 50V (UC,J)	C10	1-163-038-00	CERAMIC CHIP 0.1 25V
C7	1-163-107-00	CERAMIC CHIP 39PF 5% 50V (EK)	C11	1 124 240 00	FI FOT OR ONLY
C8	1-163-021-00	CERAMIC CHIP 0.01 10% 50V	C12	1-124-248-00	ELECT 22 20% 35V ELECT 22 20% 35V
			CIZ	1-124-246-00	ELECT 22 20% 35V
C9	1-163-021-00	CERAMIC CHIP 0.01 10% 50V			
C10	1-163-255-00	CERAMIC CHIP 150PF 5% 50V (UC,J)	CN1	1-564-012-00	RECEPTACLE, 2P MALE
C10	1-163-141-00	CERAMIC CHIP 0.001 5% 50V (EK)			MOLE, ZI WALL
C11	1-163-021-00	CERAMIC CHIP 0.01 10% 50V			
C12	1-131-380-00	TANTALUM 33 10% 10V	D1	8-719-100-89	RD24EB1
C13	1-131-380-00	TANTALUM 33 10% 10V			
C14	1-131-380-00	TANTALUM 33 10% 10V	104		
C15	1-131-380-00	TANTALUM 33 10% 10V	IC1 IC2	8-759-100-94	μPC358G2: NEC
C16	1-131-380-00	TANTALUM 33 10% 10V	IC2	8-759-100-94	μPC358G2: NEC
C17	1-124-139-00	ELECT 100 20% 10V			
			Q1	8-729-100-66	2SC1623
C18	1-131-380-00	TANTALUM 33 10% 10V	Q2	8-729-177-43	
		TANTALUM 33 10% 10V	G3	8-729-100-66	2SC1623
C20 C21		ELECT 10 20% 16V TANTALUM 33 10% 10V	Q4	8-729-201-78	2SD1406
021	1-131-360-00	TANTALOW 33 10% 10V			
			R11	1 244 912 00	CARBON 3.3 5% 1/2W
			R16	1-247-013-00	CARBON 1.2K 5% 1/4W
		BX1340: SONY		+, , , + 00	OANDON 1.2K 5% 1/4VV
		BX1337: SONY			
		BX1338: SONY	RV1	1-228-457-00	METAL 2K
		BX1339A: SONY			
IC5	8-759-907-81	SN74LS221NS: TI			
			L1	1-408-074-11	MICRO 56
	1-408-124-00				
	1-408-124-00				
	1-408-124-00		•		
L4	1-408-423-00	MICRO 150 (UC,J)			
L4	1-408-123-00	MICRO 100 (EK)			
L5	1-408-124-00	MICRO 39 (UC,J)			
L5	1-408-123-00	MICRO 33 (EK)			
	1-408-124-00				
L7	1-408-124-00	MICRO 39			
L8	1-408-124-00	MICRO 39			
R1	1-214-583-00	METAL 12K 1% 1/8W (UC,J)			
	1-214-581-00	METAL 12K 1% 1/8W (UC,J) METAL 10K 1% 1/8W (EK)			

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description
SW-34	BOARD	•	R20	1-247-861-11	CARBON 18K 5% 1/6W
	A-7513-355-A	MOUNTED CIRCUIT BOARD "SW-34"			(UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310)
C1 C2 C3	1-131-379-00	CERAMIC CHIP 0.01 10% 50V TANTALUM 22 10% 10V TANTALUM 10 10% 10V	RV1 RV2	1-224-940-00 1-224-940-00	
C4 C5	1-131-385-00	TAMTALUM 22 10% 6.3V TAMTALUM 0.1 10% 35V			
			S1 S2	1-554-165-00 1-553-856-00	· -
CN1 CN2	1-564-007-00 1-564-005-00	RECEPTACLE, 8P RECEPTACLE, 6P			
		THESE TRIBLE, OF	FRAM	E	
D1	8-719-800-33	TI G102A	CN101	1-561-781-11	HEEL MICE BIVE BEINTVIDEO OUT
D2	8-719-100-03		CN102 CN103	1-563-113-11 1-561-781-11	LEINO
D3	8-719-100-03	1S2835	CN104	1-561-781-11	RECEPTACLE ''GENLOCK'' RECEPTACLE ''REMOTE''
D4	8-719-100-03				THE TEMOTE
D5	8-719-100-03				
DC	0.740.400.05	(UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310)	S101 S102	1-570-505-11 1-570-505-11	ROTARY "GAIN" ROTARY "WHITE BAL"
D6 D7	8-719-100-05 8-719-815-55	1\$1555			
	8-719-100-05	/UC: DXC-102 S/N 10181 AND	C1 C2 C3	1-102-106-21	CERAMIC 100PF 10% 50V CERAMIC 100PF 10% 50V CERAMIC 100PF 10% 50V
		HIGHER EK: DXC-102P S/N 10311 AND HIGHER			
D8	8-719-815-55	1\$1555	FIXTU	RE	
		(UC: DXC-102 S/N Up to 10180 EK: DXC-102P S/N Up to 10310)		J-6080-058-A	LB-140 FILTER
	8-719-100-05	1S2837 /UC: DXC-102 S/N 10181 AND \		J-6029-590-A	
		HIGHER EK: DXC-102P S/N 10311 AND HIGHER			
IC1	8-759-200-90	TC4538BF: TOSHIBA			
Q1	8-729-100-76	2SA812			
Q2	8-729-100-76				
Q3 Q4	8-729-100-66 8-729-100-66				
Q5	8-729-100-66				
Q6	8-729-100-76	2SA812			
Q7	8-729-100-76	2SA812 / UC: DXC-102 S/N Up to 10180 \			
Q 9	8-729-100-66 8-729-109-44				

AUTO IRIS LENS

VCL-08Y/16Y





VCL-08Y

VCL-16Y

SPECIFICATIONS

Mount

C-mount

Focal length

VCL-08Y: 8 mm (1/3 inches)

VCL-16Y: 16 mm (5/8 inches)

Maximum aperture ratio

1:1.4

Iris range

F1.4 to F360 (effective value)

Auto iris range

30 to 100,000 lux

Minimum focus distance

VCL-08Y: 0.2 m (75% inches)

VCL-16Y: 0.5 m (193/4 inches)

Image size

11 mm dia. (7/16 inches) 43 mm dia., 0.75 mm-pitch

Front thread 43 mm d Power requirements 12 V DC

Operating temperature

0°C +

0°C to 40°C (32°F to 104°F)

Dimensions

VCL-08Y:

Approx. 46.5 mm dia. × 51.1 mm long

(17/8 inches dia. × 21/8 inches)

VCL-16Y:

Approx. 46.5 mm dia. \times 46.7 mm long (17/8 inches dia. \times 17/8 inches)

VCL-08Y: Approx. 170 g (6 oz)

Weight

VCL-16Y: Approx. 140 g (5 oz)

Accessories supplied

Lens cap (1)

Dust cap (1)



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	Focusing						
	Sensitity Adjustment						
	ALC Adjustment						

2. SPARE PARTS

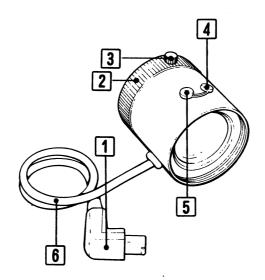
2-1.	Exproded View	 2-	1

SECTION 1 GENERAL DESCRIPTION

1-1. PARTS IDENTIFICATION

(See illustration A.)

Refer to "PARTS IDENTIFICATION".
Se reporter à "IDENTIFICATION DES ORGANES".
Siehe "BEZEICHNUNG DER TEILE".



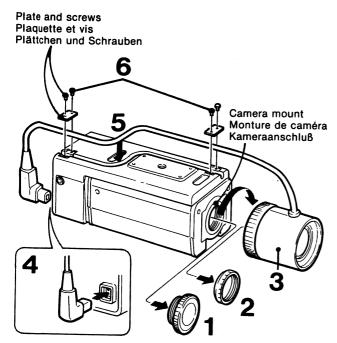
- [1] Lens connector (4-pin) Connect to the LENS connector on the camera. The video camera sends a signal for automatic iris adjustment to the lens.
- 2 Focus ring (See "FOCUSING".)
- 3 Focus ring fixing screw
 Fixes the focus ring after focusing. (See "FOCUSING".)
- 4 LEVEL adjustment control
 Adjusts the lens sensitivity. (See "SENSITIVITY ADJUST-MENT".)
- 5 ALC (Automatic Light Control) adjustment control
 Determines the video signal level measuring system of the
 lens. (See "ALC ADJUSTMENT".)
- 6 Lens cord

1-2. ATTACHING THE LENS TO THE

CAMERA (See illustration B.)

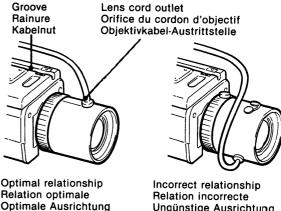
- '1 Remove the lens mount cap of the camera.
- Remove the lens dust cap.
- Align the lens with the camera's lens mount and secure it by turning it clockwise.
- Connect the lens cord to the LENS connector of the camera. (If the lens mounting position is not appropriate for connecting, see "Adjustment of the lens mounting position" below.)
- Thread the lens cord through the groove of the camera.
- Fasten the lens cord with the plates and screws (supplied with the camera) (at two points on the DXC-101 series camera, and at three points on the DXC-102 series camera).





Adjustment of the lens mounting position (See illustration [C].) After the lens is attached to the camera (in step 3 above), if the relationship between the lens cord outlet and camera groove is not appropriate, make the following adjustment.





- Relation optimale Optimale Ausrichtung
- Ungünstige Ausrichtung
- Unplug the lens cord from the camera, and loosen the lens by turning it counterclockwise one full rotation.
- Turn the lens clockwise or counterclockwise to the desired position by pushing it toward the camera firmly to release the clutch inside the lens.
- Tighten the lens by turning it clockwise without pushing it in.

If the lens is not fixed at the desired position, repeat the above steps 1 to 3. When it is fixed at the desired position, proceed to step 4 in "ATTACHING THE LENS TO THE CAMERA".

To remove the lens

Reverse the procedure described in "ATTACHING THE LENS TO THE CAMERA".

1-3. FOCUSING

- 1 Remove the lens cap and loosen the focus ring fixing screw.
- 2 Watch the monitor screen, and focus by adjusting the focus ring.
- 3 Tighten the focus ring fixing screw to fix the focus ring. The focus ring setting will remain stable, even if the camera is subjected to vibration.

1-4. SENSITIVITY ADJUSTMENT

(See illustration D.)

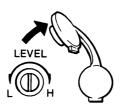
Since the lens sensitivity has been adjusted at the factory, it is not necessary for you to readjust it. If the picture is too dark, however, or if the picture's highlights are extremely overexposed, remove the cap and adjust the LEVEL adjustment control with a screwdriver to improve the picture quality.

If the control is turned

toward L: The picture becomes darker.

toward H: The picture becomes brighter.





1-5. ALC ADJUSTMENT (See illustration E.)

The ALC adjustment control sets the reference signal level for auto iris control at a level within a range between the average brightness level of the entire image and the level of the brightest part of the image. Since the ALC adjustment has been preset at the factory, usually no further adjustment is required.

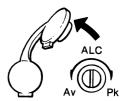
However, when shooting an image which includes a luminous body (such as a fluorescent lamp) that might cause an overexposed picture, remove the cap and adjust the ALC adjustment control as follows:

If the control is turned

toward Av: The picture becomes brighter and the picture's highlights become more overexposed.

toward Pk: The picture becomes darker and the picture's highlights become less overexposed.



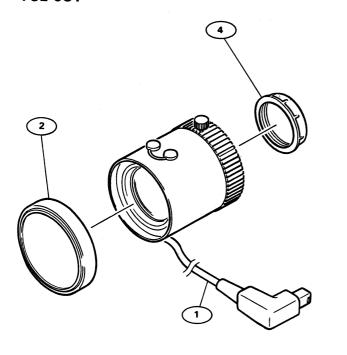


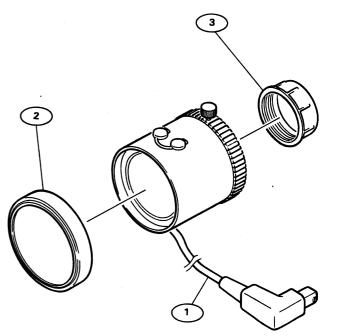
SECTION 2 SPARE PARTS

2-1. EXPLODED VIEW

VCL-08Y

VCL-16Y





No.	Parts No.	Description
1	1-558-489-11	CABLE WITH CONNECTOR
2	3-706-842-01	CAP, LENS
3	3-706-843-01	CAP, DUST (VCL-16Y)
4	3-707-254-01	CAP DUST (VCL-08V)

PACKING MATERIAL

3-760-960-02 MANUAL, INSTRUCTION (UC, EK)